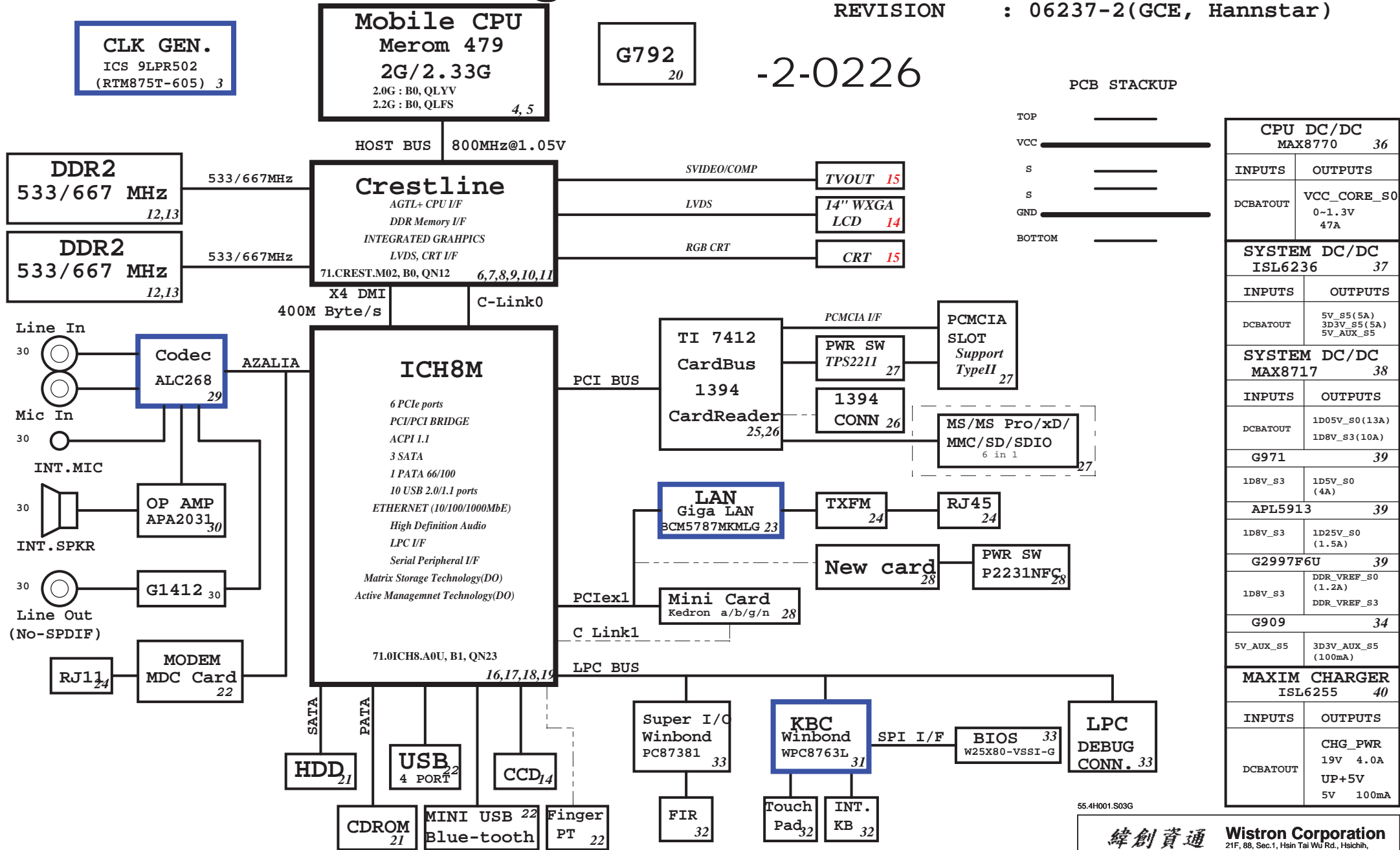


# Biwa Block Diagram

Project code: 91.4H001.001  
 PCB P/N : 55.4H001.XXX  
 REVISION : 06237-2(GCE, Hannstar)



# ICH8M Functional Strap Definitions

ICH8-M EDS 21762 2.0V1 page 16

Signal	Usage/When Sampled	Comment
HDA_SDOUT	XOR Chain Entrance/ PCIE Port Config1 bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low. When TP3 not pulled low at rising edge of PWROK, sets bit1 of RPC.PC(Config Registers: offset 224h)
HDA_SYNC	PCIE config1 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-down. Sets bit0 of RPC.PC(Config Registers:Offset 224h)
GNT2#	PCIE config2 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-up. Sets bit2 of RPC.PC2(Config Registers:Offset 0224h)
GPIO20	Reserved	This signal should not be pulled high.
GNT1#/ GPIO51	ESI Strap (Server Only) Rising Edge of PWROK	ESI compatible mode is for server platforms only. This signal should not be pulled low for desktop and mobile.
GNT3#	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT0#/ SPI_CS1#	Boot BIOS Destination Selection. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT0# is MSB, 01-SPI, 10-PCI, 11-LPC.
INTVRMEN	Integrated VccSus1_05, VccSus1_5 and VccCL1_5 VRM Enable/Disable. Always sampled.	Enables integrated VccSus1_05, VccSus1_5 and VccCL1_5 VRM's when sampled high
LAN100_SLP	Integrated VccLAN1_05 and VccCL1_05 VRM Enable/Disable. Always sampled.	Enables integrated VccLAN1_05 and VccCL1_05 VRM's when sampled high
SATALED#	PCI Express Lane Reversal. Rising Edge of PWROK.	Signal has weak internal pull-up. Sets bit 27 of MPC.LR(Device 28:Function 0:Offset D8)
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH8 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.
GPIO33/ HDA_DOCK _EN#	Flash Descriptor Security Override Strap Rising Edge of PWROK	This signal has a weak internal pull-up. Sampled low:the Flash Descriptor Security will be overridden. If high,the security measures will be in effect.This should only be used in manufacturing environments.

# ICH8M IDE Integrated Series Termination Resistors

DD[15:0], DIOW#, DIOR#, DREQ, DDACK#, IORDY, DA[2:0], DCS1#, DCS3#, IDEIRQ	approximately 33 ohm
--	----------------------

# PCI Routing

page 17

	IDSEL	INT	REQ	GNT
FI7412	AD22	G:CARDBUS B:1394 F:Flash Media G:SD Host	0	0

# PCIE Routing

LANE1	LAN BCM5787M
LANE2	MiniCard WLAN
LANE3	NewCard WLAN

# USB Table

USB	
Pair	Device
0	USB1
1	USB2
2	USB3
3	USB4
4	MINIC1
5	BT
6	CCD
7	Finger
8	NEW
9	NC

# ICH8M Integrated Pull-up and Pull-down Resistors

ICH8-M EDS 21762 2.0V1

SIGNAL	Resistor Type/Value
HDA_BIT_CLK	PULL-DOWN 20K
HDA_RST#	NONE
HDA_SDIN[3:0]	PULL-DOWN 20K
HDA_SDOUT	PULL-DOWN 20K
HDA_SYNC	PULL-DOWN 20K
GNT[3:0]	PULL-UP 20K
GPIO[20]	PULL-DOWN 20K (?)
LDA[3:0]#/FHW[3:0]#	PULL-UP 20K
LAN_RXD[2:0]	PULL-UP 10K
LDRQ[0]	PULL-UP 20K
LDRQ[1]/GPIO23	PULL-UP 20K
PME#	PULL-UP 20K
PWRBTN#	PULL-UP 20K
SATALED#	PULL-UP 15K
SPI_CS1#	PULL-UP 20K
SPI_CLK	PULL-UP 20K
SPI_MOSI	PULL-UP 20K
SPI_MISO	PULL-UP 20K
TACH_[3:0]	PULL-UP 20K (?)
SPKR	PULL-DOWN 20K
TP[3]	PULL-UP 20K
USB[9:0][P,N]	PULL-DOWN 15K
CL_RST#	PULL-UP 13K

# History

- 2007/02/16
1. Page 33: Add SIO 87381 for FIR Issue.
  2. Page 31, change KBC from 8768L to 8763L.
  3. Page 33, del U33(LPC golden Finger).
  4. Page 24/32, change ERC1/ERC2 due to 77.61021.02L is Obsoleted Part !
  5. Page 37, del TC22/TC19.
  6. Page 38, del TC1/TC4.

- 2007/02/09
1. Page 14:Modify "Q14" "BTBTN1" "WLBTN1" symbol.
  2. Page 36, 37, 38: Replace 0ohm with 0ohm pad.

- 2007/02/08a
1. Page 14:Modify R428 to "FRONT\_PWRLED#\_1" and RN58 pin7 to "STBY\_LED#\_2" due to LED brightness issue.
  2. Page 38:Replace "TC26" with "77.C1561.01L".

- 2007/02/08
1. Page 10:Replace "R244" with "0603-PAD".
  2. Page 36:Replace open power gap with close power gap.
  3. Page 38:Add capacitor "TC26" for acoustic noise

# Crestline Strapping Signals and Configuration

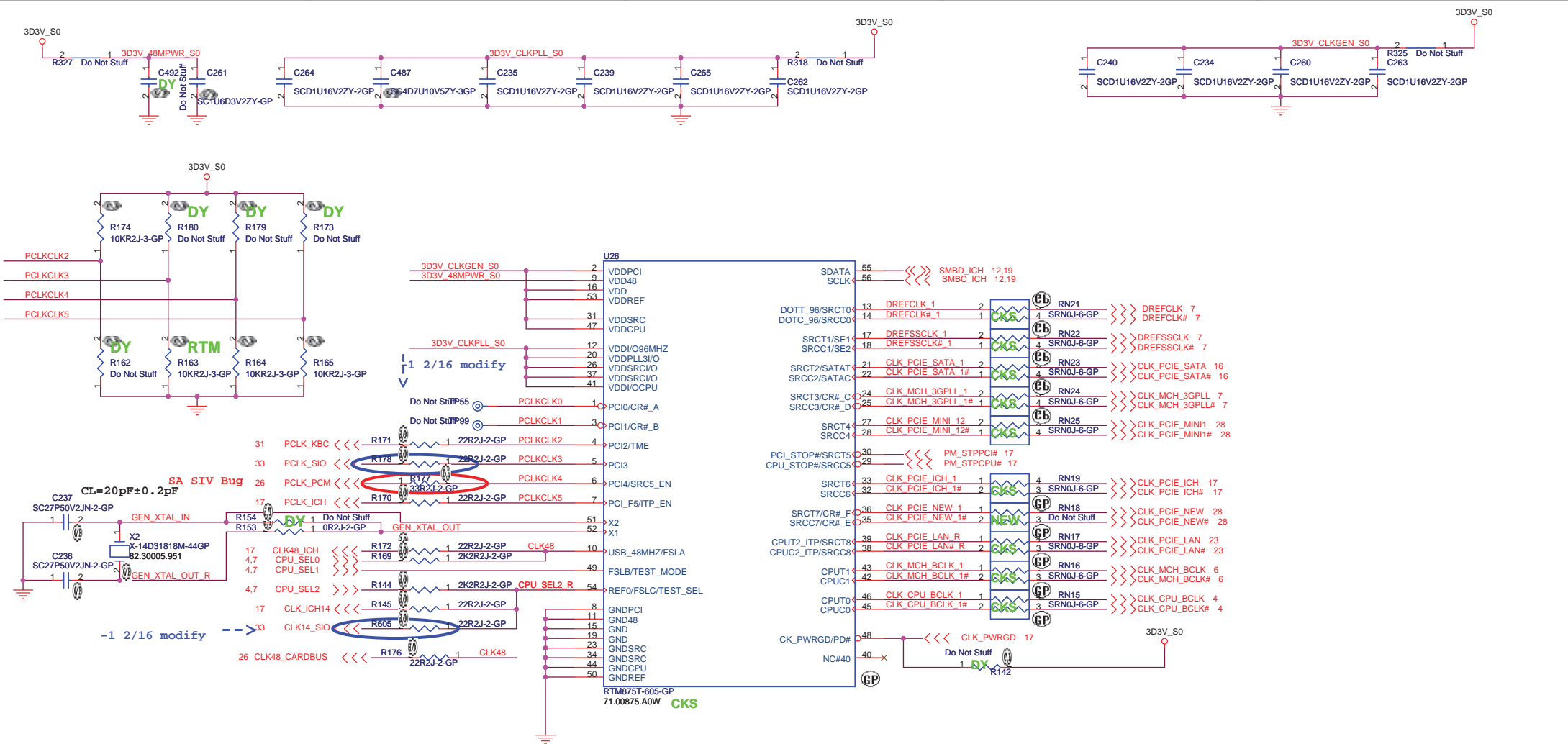
Crestline EDS 20954 1.0 page 7

Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	001 = FSB533 011 = FSB667 010 = FSB800 others = Reserved
CFG[4:3]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (Default)
CFG[8:6]	Reserved	
	Low Power PCI Express	0 = Normal mode 1 = Low Power mode (Default)
CFG9	PCI Express Graphics Lane Reversal	0 = Reverse Lanes,15->0,14->1 ect.. 1 = Normal operation(Default):Lane Numbered in order
CFG[11:10]	Reserved	
CFG[13:12]	XOR/ALL Z test straps	00 = Reserved 01 = XOR mode enabled 10 = All Z mode enabled 11 = Normal Operation (Default)
CFG[15:14]	Reserved	Reserved
CFG16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG[18:17]	Reserved	
CFG19	DMI Lane Reversal	0 = Normal operation (Default):lane Numbered in order 1 =Reverse Lane,4->0,3->1 ect...
CFG20	SDVO/PCIE Concurrent	0 = Only SDVO or PCIE x1 is operational (Default) 1 =SDVO and PCIE X1 are operating simultaneously via the PEG port
SDVOCRTL_DATA	SDVO Present	0 = No SDVO Card present (Default) 1 = SDVO Card present

NOTE: All strap signals are sampled with respect to the leading edge of the Crestline GMCH PWROK in signal.

55.4H001.S03G

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<b>Reference</b>			
Title	Document Number		
Size A3	<b>Biwa</b>		Rev -2
Date: Thursday, March 01, 2007	Sheet 2	of	42



ICS9LPR502HGLFT-GP setting table

PIN NAME	DESCRIPTION
PCI0/CR#_A	Byte 5, bit 7 0 = PCI0 enabled (default) 1 = CR#_A enabled. Byte 5, bit 6 controls whether CR#_A controls SRC0 or SRC2 pair Byte 5, bit 6 0 = CR#_A controls SRC0 pair (default), 1 = CR#_A controls SRC2 pair
PCI1/CR#_B	Byte 5, bit 5 0 = PCI1 enabled (default) 1 = CR#_B enabled. Byte 5, bit 6 controls whether CR#_B controls SRC1 or SRC4 pair Byte 5, bit 4 0 = CR#_B controls SRC1 pair (default) 1 = CR#_B controls SRC4 pair
PCI2/TME	0 = Overclocking of CPU and SRC Allowed 1 = Overclocking of CPU and SRC NOT allowed
PCI4/SRC5_EN	0 = Pin29 as CPU_STOP#, pin 30 as PCI_STOP#. 1 = Pins29,30 as SRC-5 differential pair.
PCI_F5/ITP_EN	0 = SRC8/SRC8# 1 = ITP/ITP#

RTM875T-605 setting table

PIN NAME	DESCRIPTION
PCI0/CR#_A	Byte 5, bit 7 0 = PCI0 enabled (default) 1 = CR#_A enabled. Byte 5, bit 6 controls whether CR#_A controls SRC0 or SRC2 pair Byte 5, bit 6 0 = CR#_A controls SRC0 pair (default), 1 = CR#_A controls SRC2 pair
PCI1/CR#_B	Byte 5, bit 5 0 = PCI1 enabled (default) 1 = CR#_B enabled. Byte 5, bit 6 controls whether CR#_B controls SRC1 or SRC4 pair Byte 5, bit 4 0 = CR#_B controls SRC1 pair (default) 1 = CR#_B controls SRC4 pair
PCI2/TME	0 = Overclocking of CPU and SRC Allowed 1 = Overclocking of CPU and SRC NOT allowed
PCI3/SRC-5_EN	0 = Pin29 as CPU_STOP#, pin 30 as PCI_STOP#. 1 = Pins29,30 as SRC-5 differential pair.
PCI4/27M_SEL	0 = Pin17 as SRC-1, Pin18 as SRC-1#, Pin13 as DOT96, Pin14 as DOT96# 1 = Pin17 as 27MHz, Pin 18 as 27MHz_SS, Pin13 as SRC-0, Pin14 as SRC-0#
PCI_F5/ITP_EN	0 = SRC8/SRC8# 1 = ITP/ITP#

SEL2	SEL1	SEL0	CPU	FSB
FSC	FSB	FSA		
1	0	1	100M	X
0	0	1	133M	X
0	1	1	166M	667M
0	1	0	200M	800M

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Title: **Clock Generator**

Size: Document Number **Biwa** Rev: **-2**

Date: Thursday, March 01, 2007 Sheet 3 of 42

6 H\_A#(35..3) <<<>> H\_A#(35..3)

H\_DINV#(3..0) <<>> H\_DINV#(3..0) 6  
H\_DSTBN#(3..0) <<>> H\_DSTBN#(3..0) 6  
H\_DSTBP#(3..0) <<>> H\_DSTBP#(3..0) 6  
H\_D#(63..0) <<>> H\_D#(63..0) 6

6 H\_ADSTB#0 <<<>> H\_REQ#(4..0)

6 H\_ADSTB#1 <<<>> A6

16 H\_A20M# <<<>> A5

16 H\_FERR# <<<>> C4

16 H\_IGNNE# <<<>> A3

16 H\_STPCLK# <<<>> D5

16 H\_INTR <<<>> C6

16 H\_NMI <<<>> B4

16 H\_SMI# <<<>> A3

Do Not Stuff#25 <<<>> M4

Do Not Stuff#30 <<<>> N5

Do Not Stuff#14 <<<>> T2

Do Not Stuff#19 <<<>> V3

Do Not Stuff#15 <<<>> B2

Do Not Stuff#20 <<<>> C3

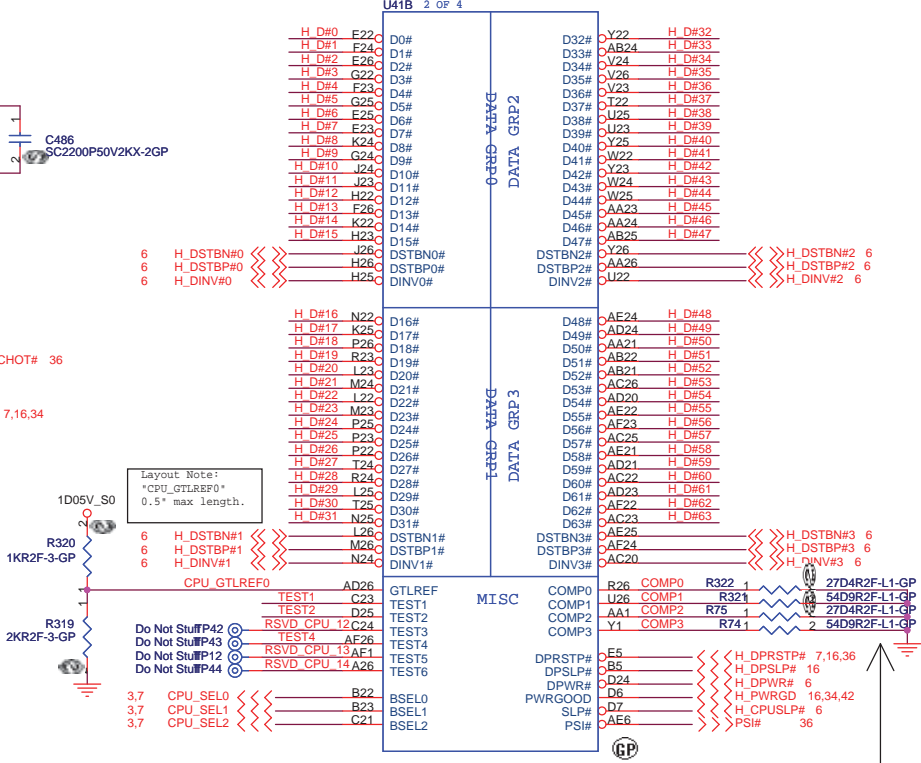
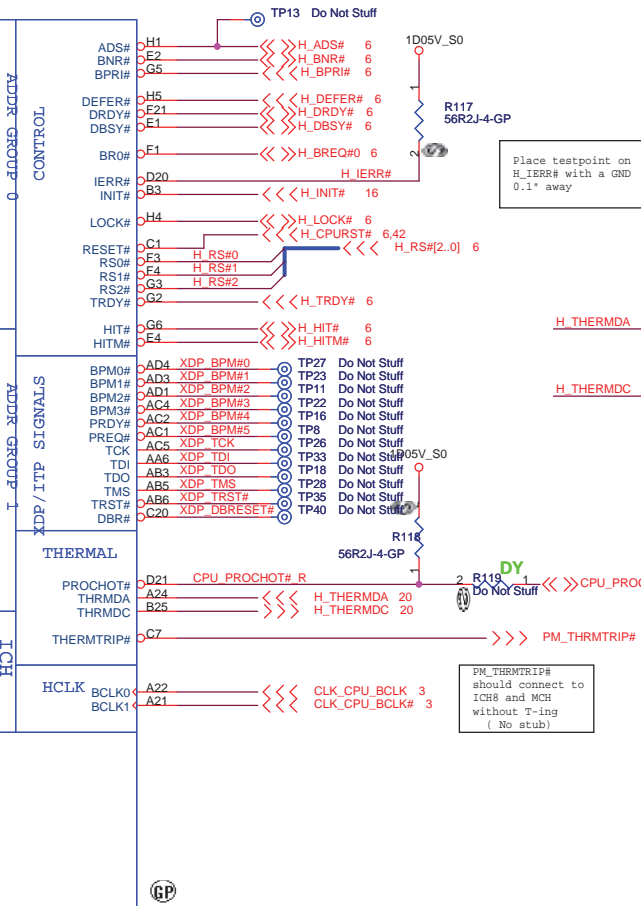
Do Not Stuff#17 <<<>> D2

Do Not Stuff#41 <<<>> D22

Do Not Stuff#22 <<<>> D3

Do Not Stuff#32 <<<>> F6

Do Not Stuff#10 <<<>> B1

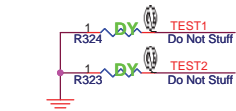
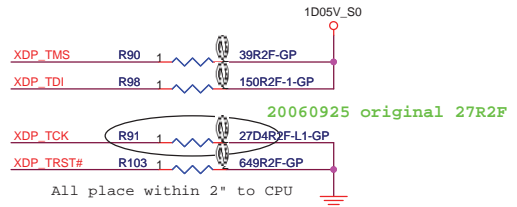


Layout Note:  
"CPU\_GTLREF0"  
0.5" max length.

PM\_THRMTRIP#  
should connect to  
IC98 and MCH  
without T-ing  
( No stub)

Layout Note:  
Comp0, 2 connect with Zo=27.4 ohm, make  
trace length shorter than 0.5"  
Comp1, 3 connect with Zo=55 ohm, make  
trace length shorter than 0.5"

Net "TEST4" as short as possible,  
make sure "TEST4" routing is  
reference to GND and away other  
noisy signals



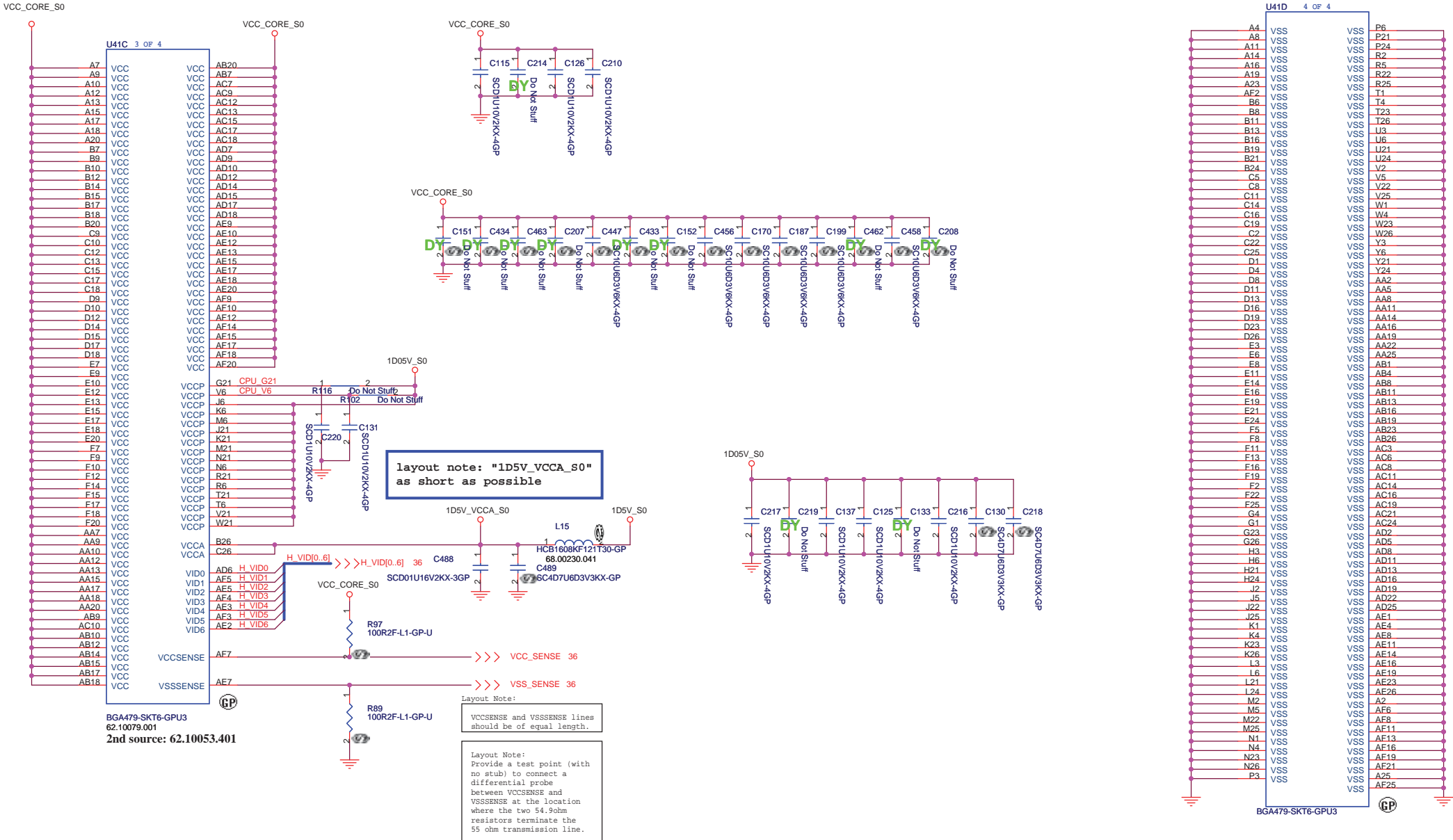
BGA479-SKT6-GPU3  
62.10079.001  
2nd source: 62.10053.401

BGA479-SKT6-GPU3

55.4H001.S03G

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Title		
CPU (1 of 2)		
Size	Document Number	Rev SA
Biwa		
Date: Thursday, March 01, 2007	Sheet 4	of 42



BGA479-SKT6-GPU3  
62.10079.001  
2nd source: 62.10053.401

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Title: **CPU (2 of 2)**

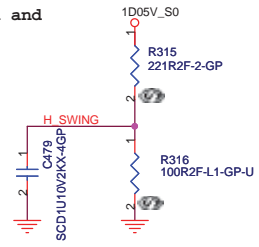
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Date: Thursday, March 01, 2007 Sheet 5 of 42

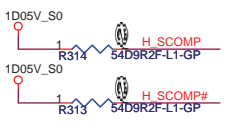


H\_SWING routing Trace width and Spacing use 10 / 20 mil

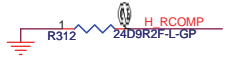
H\_SWING Resistors and Capacitors close MCH 500 mil ( MAX )



H\_SCOMP and H\_SCOMP# Resistors and Capacitors close MCH 500 mil ( MAX )

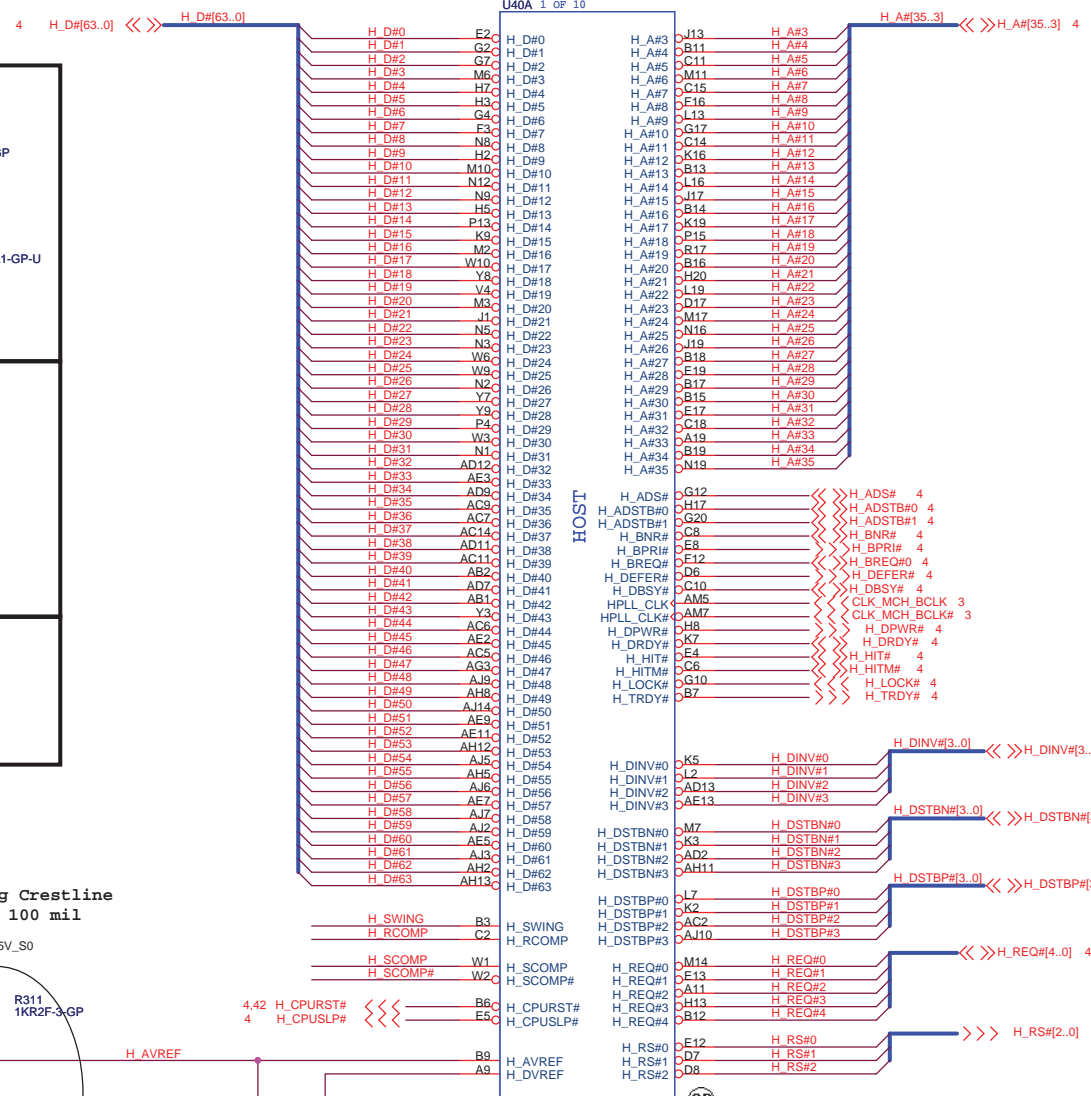
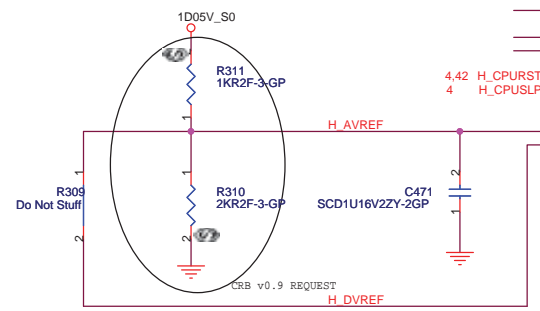


H\_RCOMP routing Trace width and Spacing use 10 / 20 mil



Place them near to the chip ( < 0.5" )

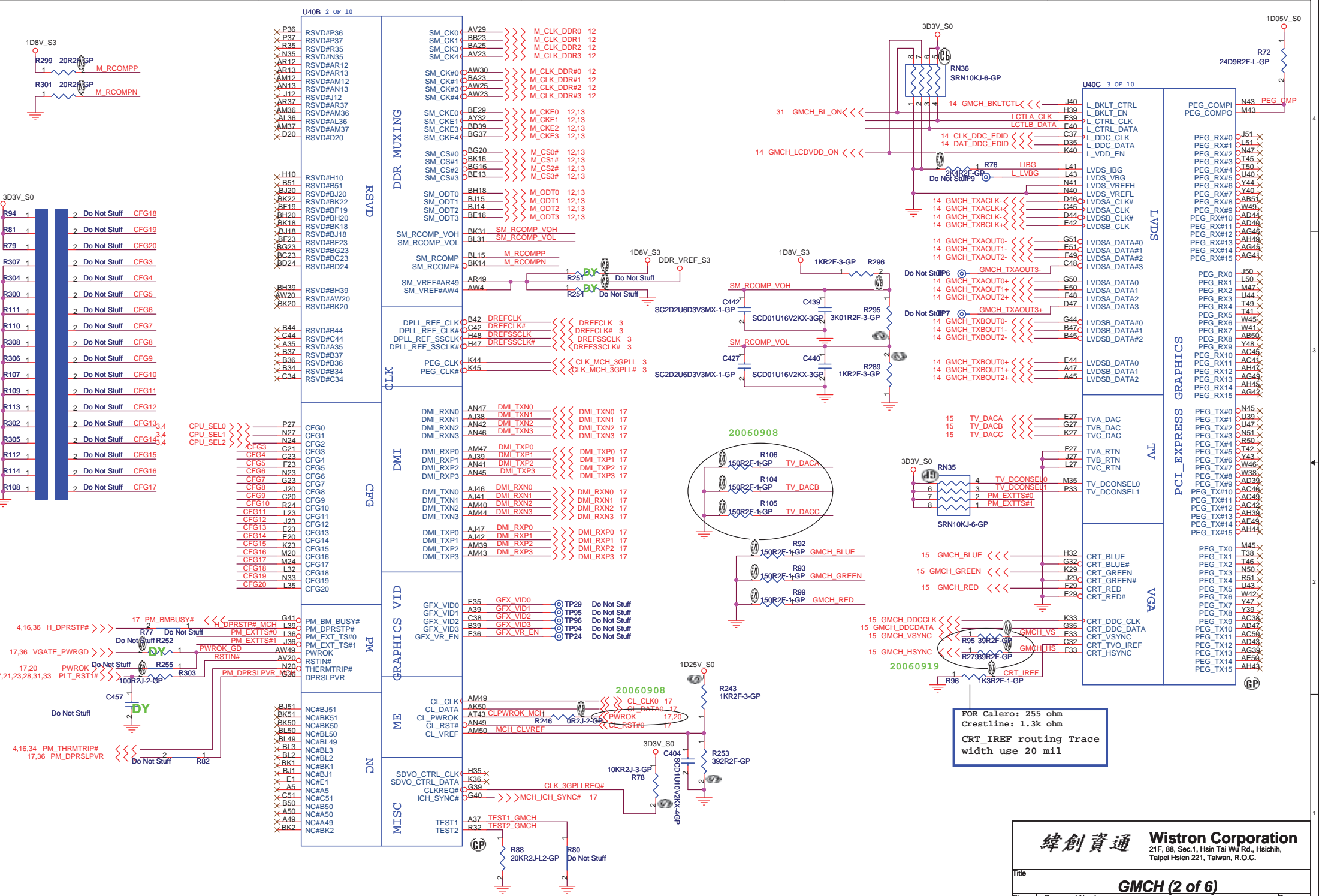
H\_REF Decoupling Crestline close Crestline 100 mil



55.4H001.S03G

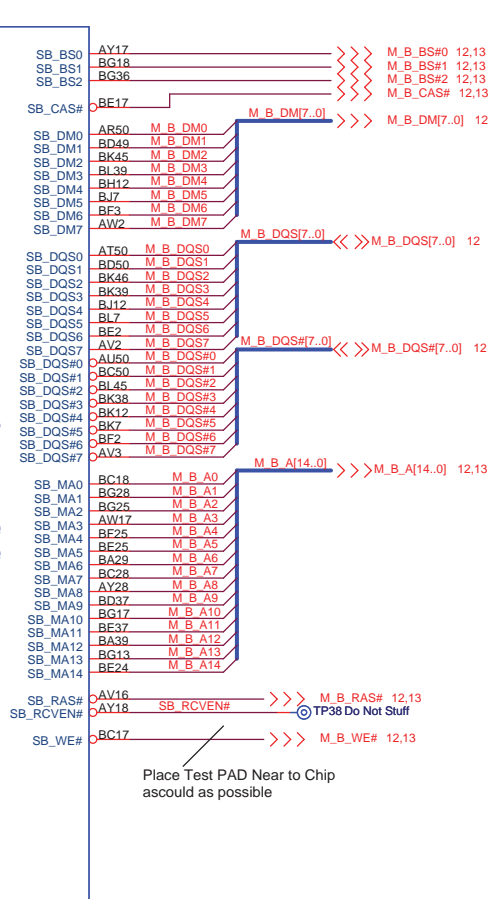
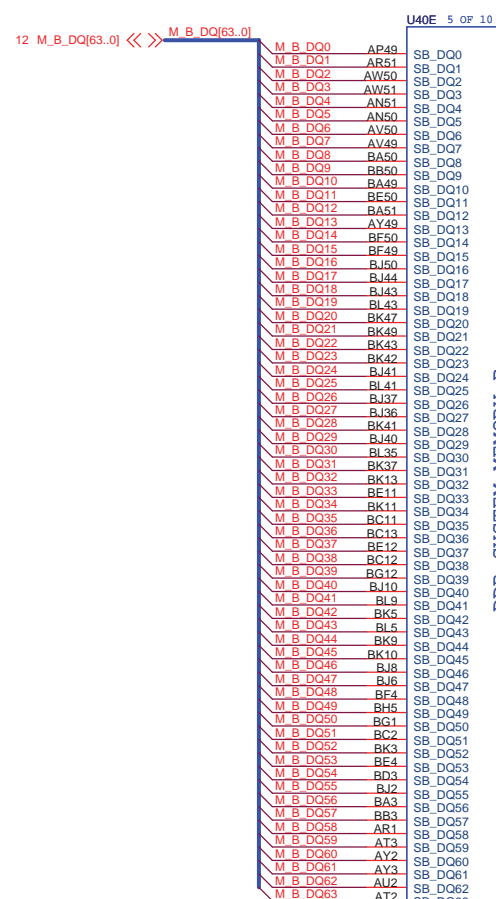
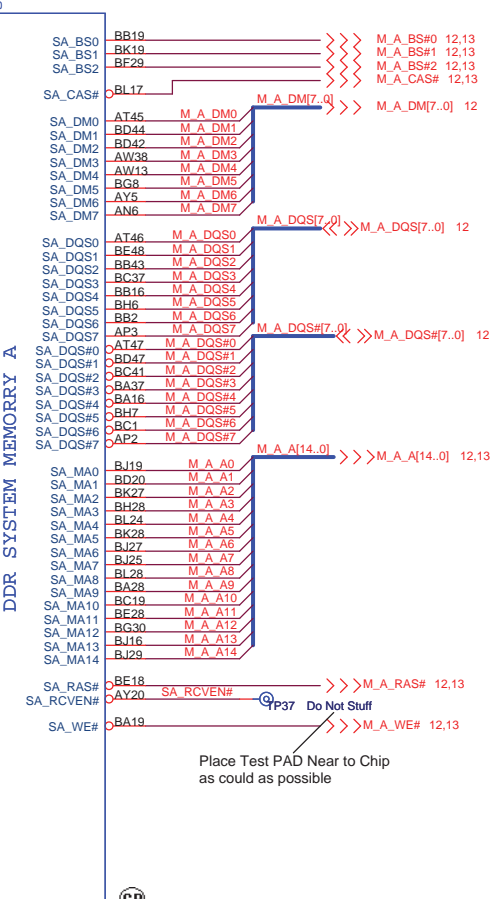
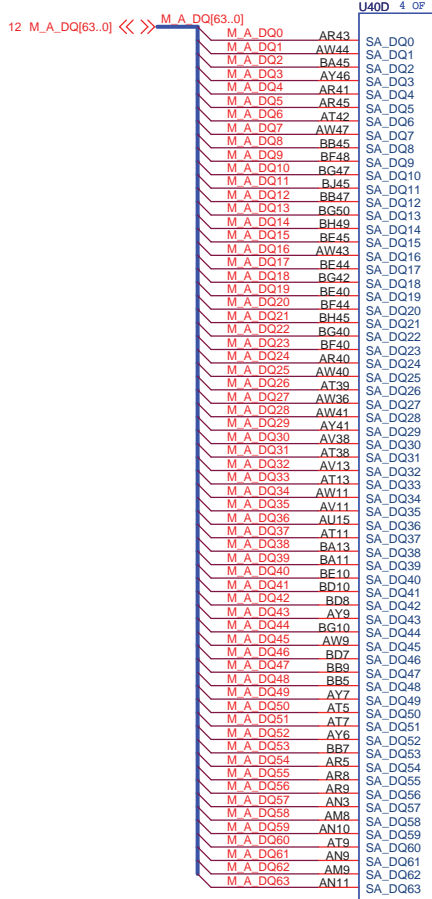
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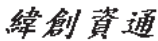
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Size	Document Number	Rev	SA
Date	Thursday, March 01, 2007	Sheet	6 of 42



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<b>GMCH (2 of 6)</b>			
File	Document Number	Rev SA	
<b>Biwa</b>		Sheet 7 of 42	
Date:	Thursday, March 01, 2007		

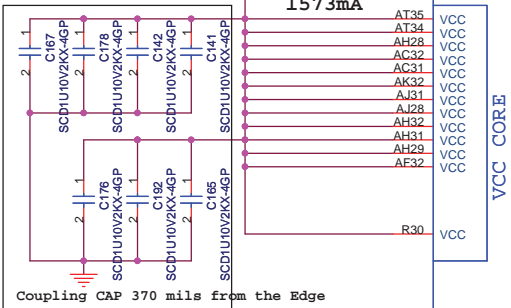


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<b>GMCH (3 of 6)</b>	
Title	SA
Size	Rev
Document Number	Biwa
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VCC\_NCTF + VCC=1573mA

FOR VCC CORE



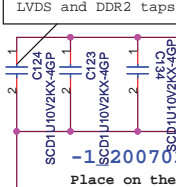
POWER

1D8V\_S3

3138mA

FOR VCC SM

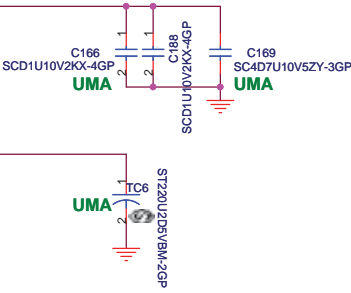
Place CAP where LVDS and DDR2 taps



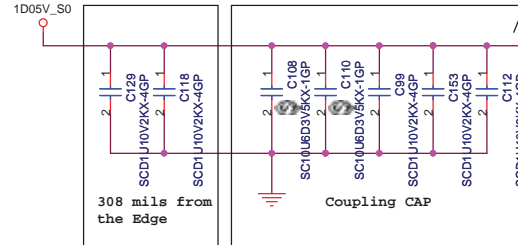
POWER

VCC\_AXG\_NCTF + VCC\_AXG=7700mA

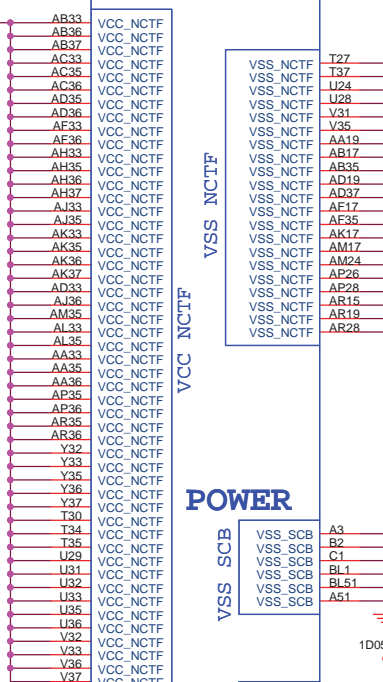
UMA



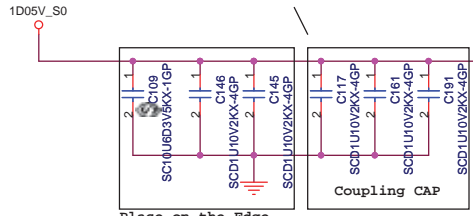
FOR VCC CORE AND VCC NCTF



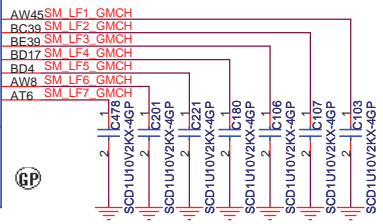
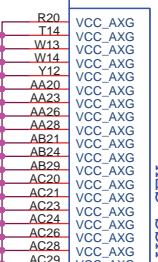
U40G 7 OF 10



FOR VCC AXM NCTF AND VCC AXM

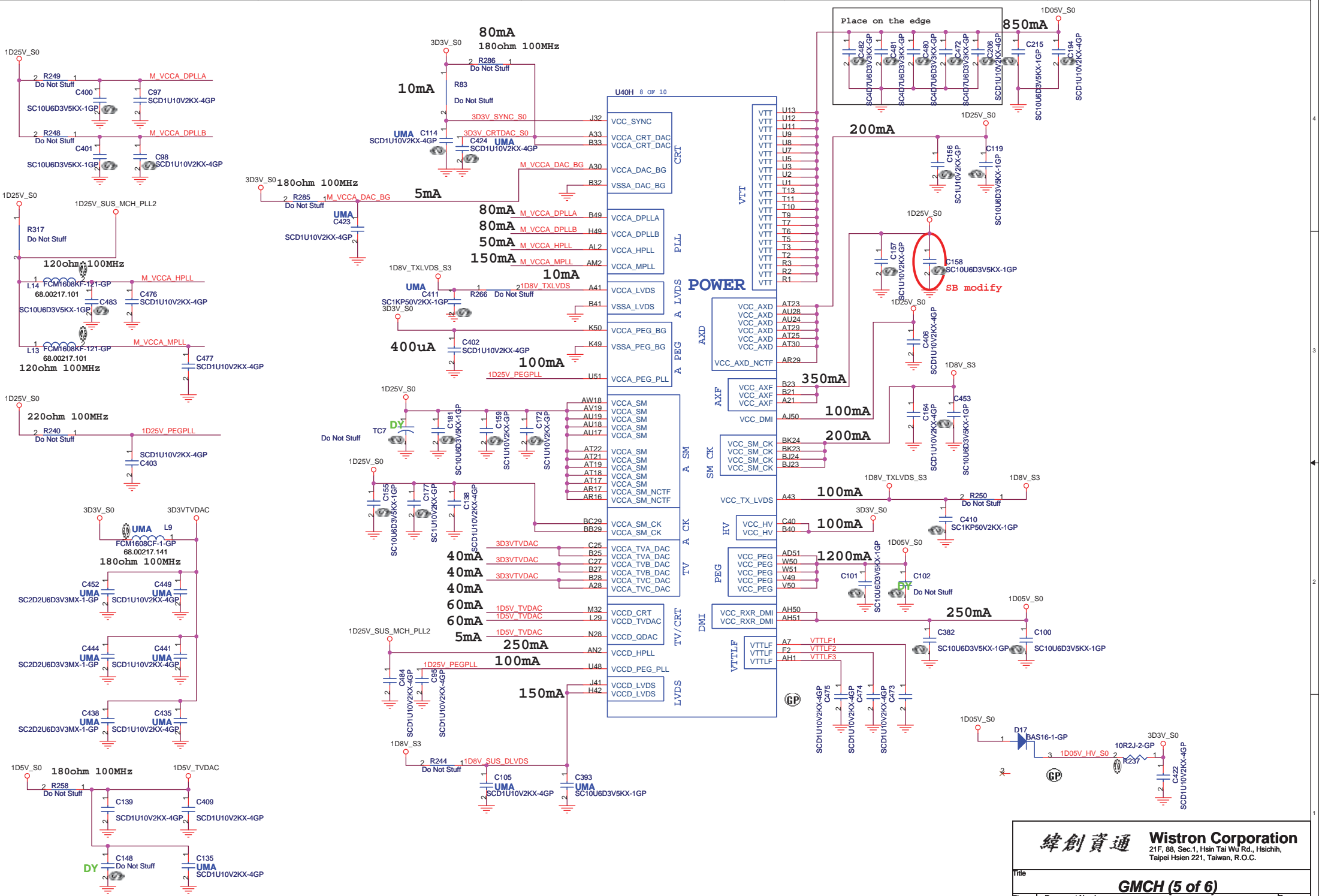


VCC\_AXM\_NCTF + VCC\_AXM=540mA




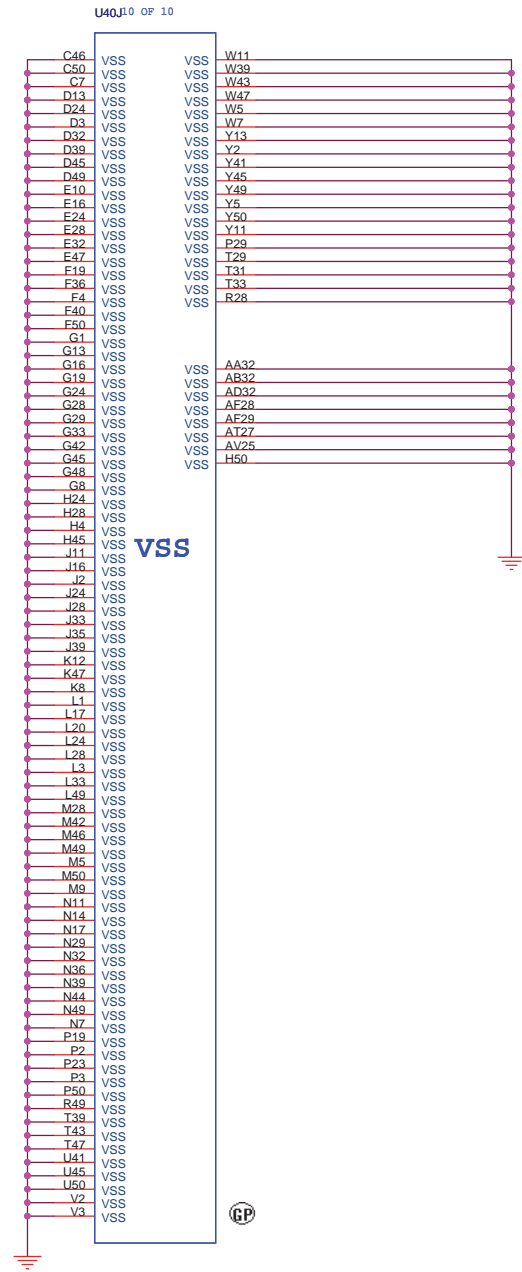
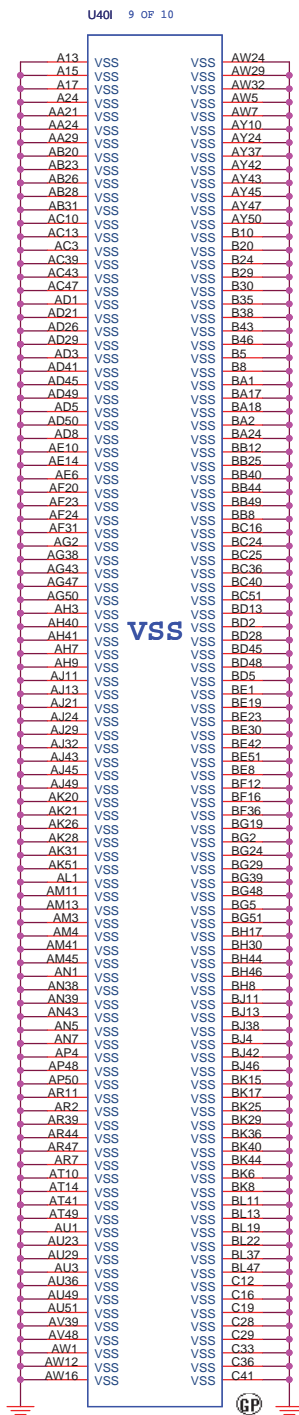
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Table with 3 columns: Title (GMCH (4 of 6)), Size (Document Number), Rev (-1), Date (Thursday, March 01, 2007), Sheet (9 of 42).



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<b>GMCH (5 of 6)</b>	
File	Rev
Size	SB
Document Number	Sheet 10 of 42
Date: Thursday, March 01, 2007	Biwa

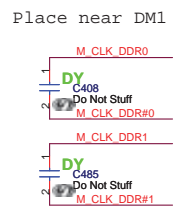
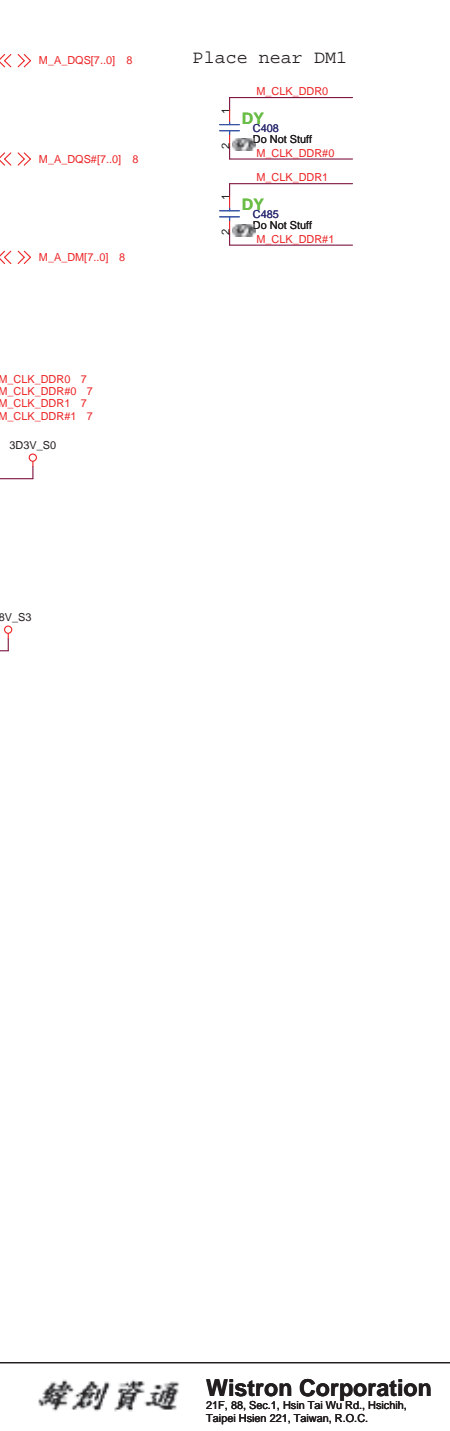
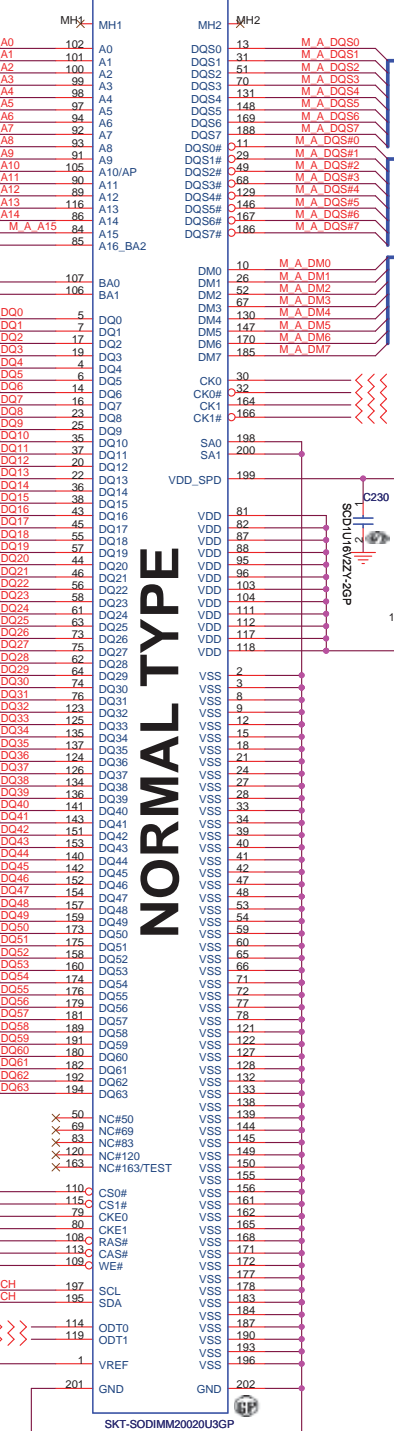
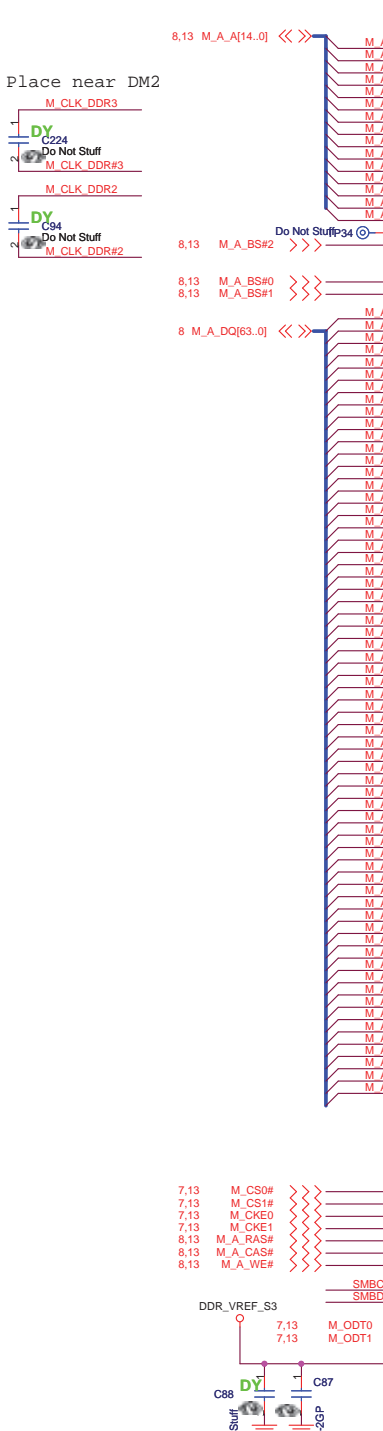
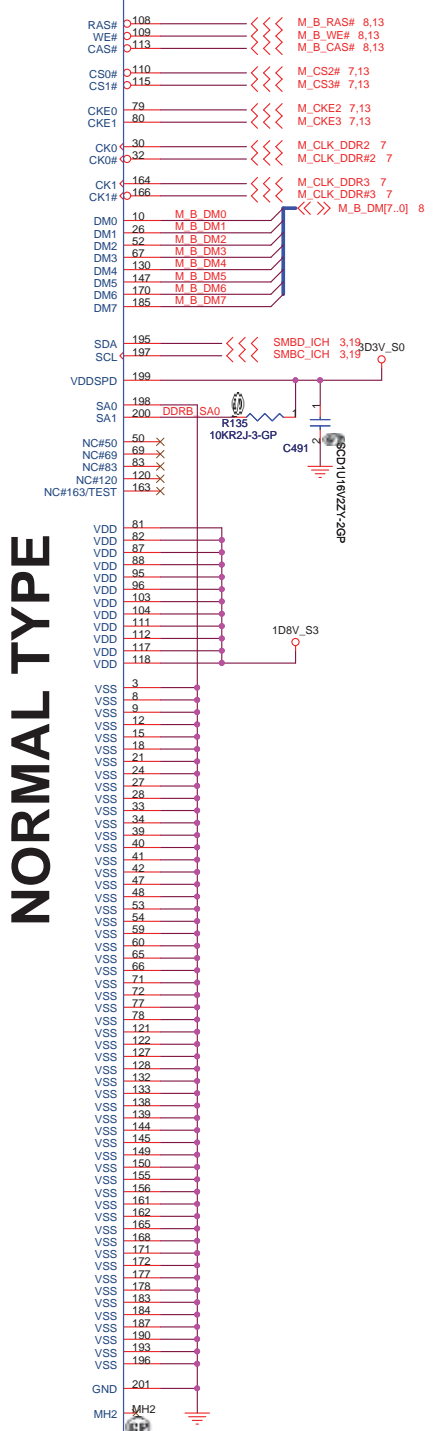
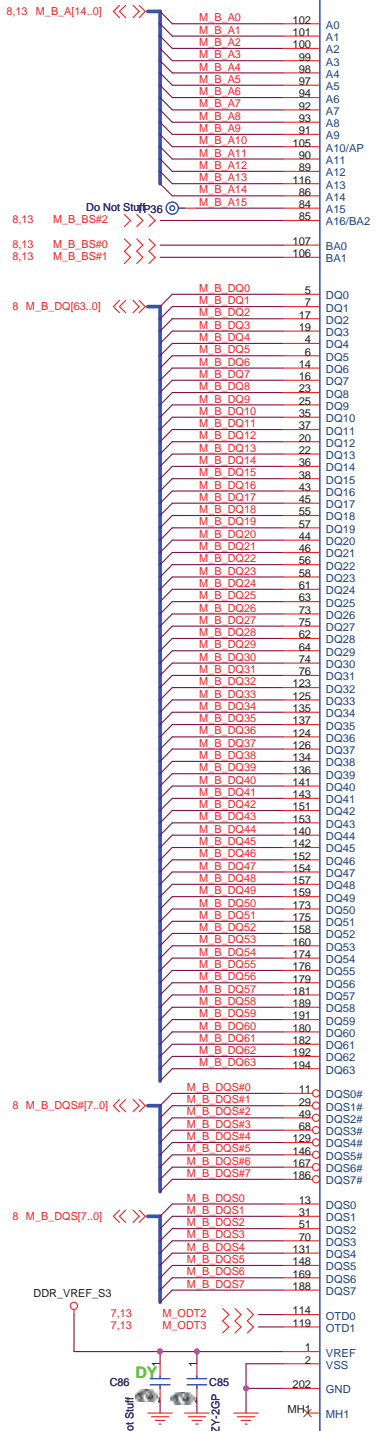


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Title: **GMCH (6 of 6)**

Size	Document Number	Rev
		SA

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DDR2-200P-22-GP-U1  
62.10017.A61 2nd source: 62.10017.A51  
High 9.2mm

SKT-SODIMM2002U3GP  
62.10017.661  
High 5.2mm  
2nd source: 62.10017.A41

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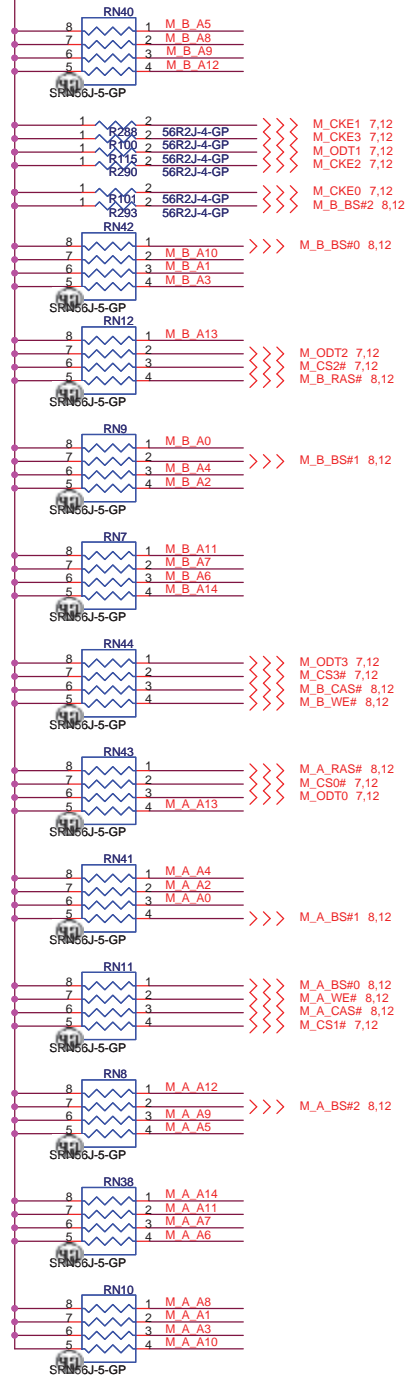
Title: **DDR2 Socket**

Size: Document Number: **Biwa** Rev: SA

Date: Thursday, March 01, 2007 Sheet 12 of 42

# PARALLEL TERMINATION

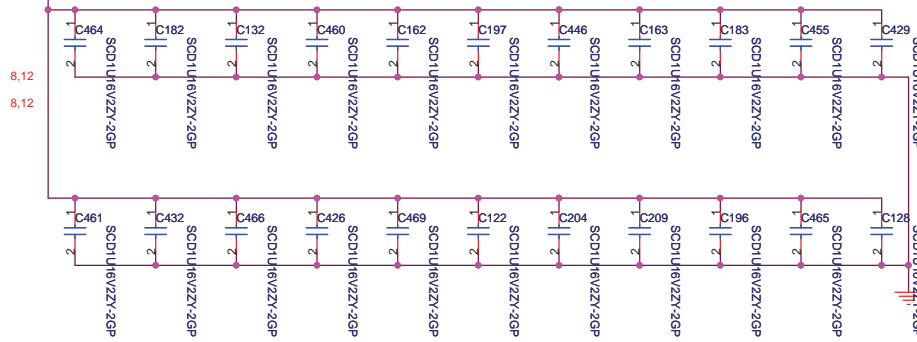
DDR\_VREF\_S0 Put decap near power(0.9V) and pull-up resistor



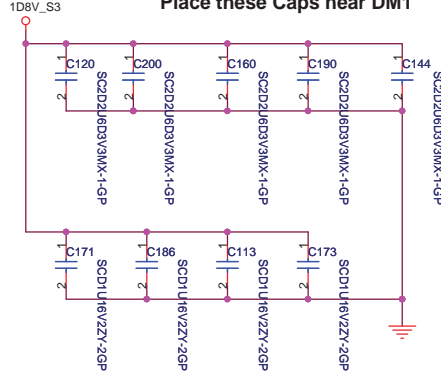
M\_A A[14..0] <<< M\_A\_A[14..0] 8,12  
M\_B A[14..0] <<< M\_B\_A[14..0] 8,12

# Decoupling Capacitor

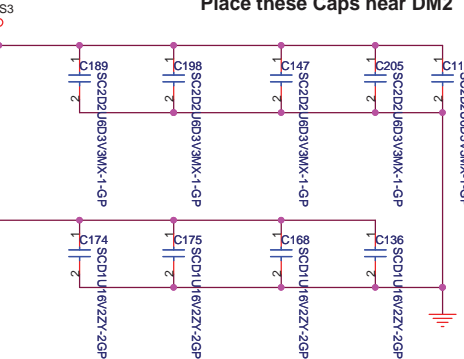
Put decap near power(0.9V) and pull-up resistor



Place these Caps near DM1



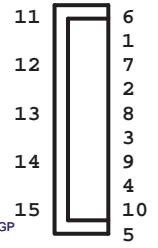
Place these Caps near DM2





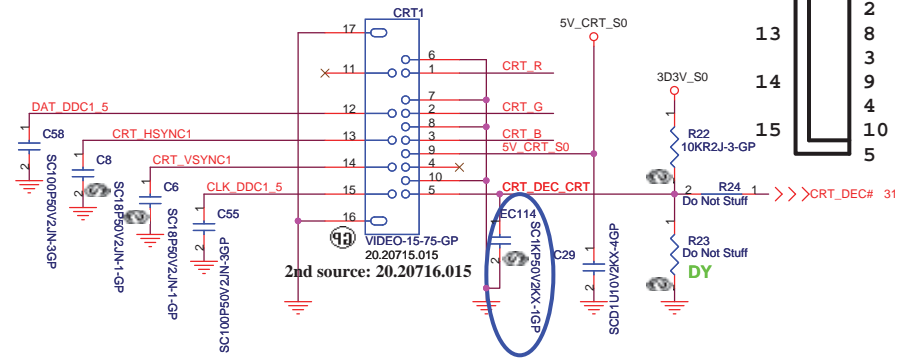
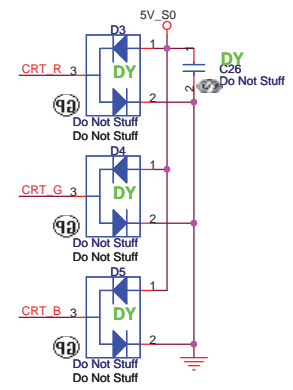
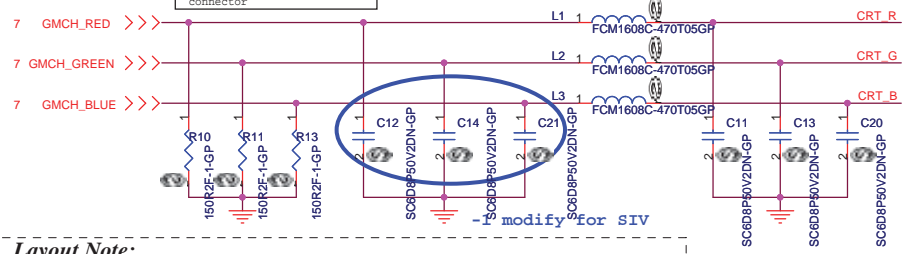


# CRT I/F & CONNECTOR



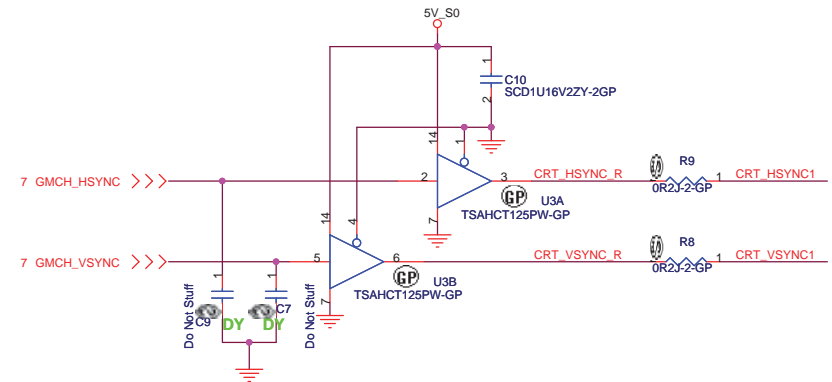
Layout Note:  
Place these resistors close to the CRT-out connector

Ferrite bead impedance: 47 ohm@100MHz

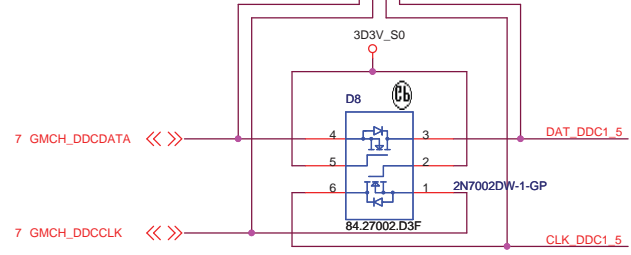


Layout Note:  
\* Must be a ground return path between this ground and the ground on the VGA connector.  
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.

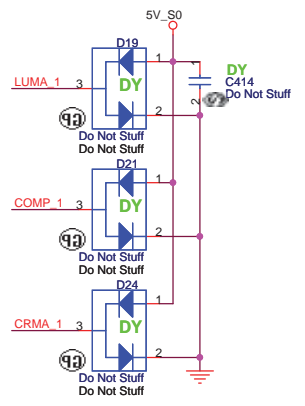
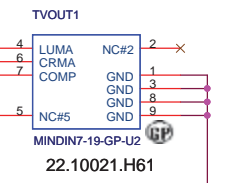
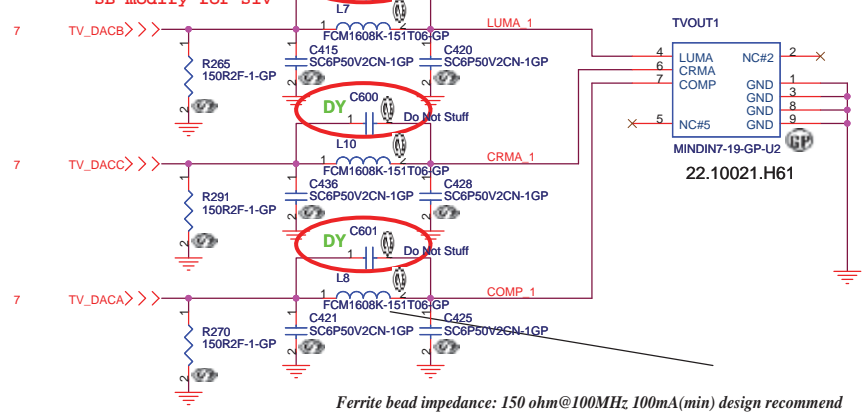
## Hsync & Vsync level shift



## DDC\_CLK & DATA level shift



## TV CONN

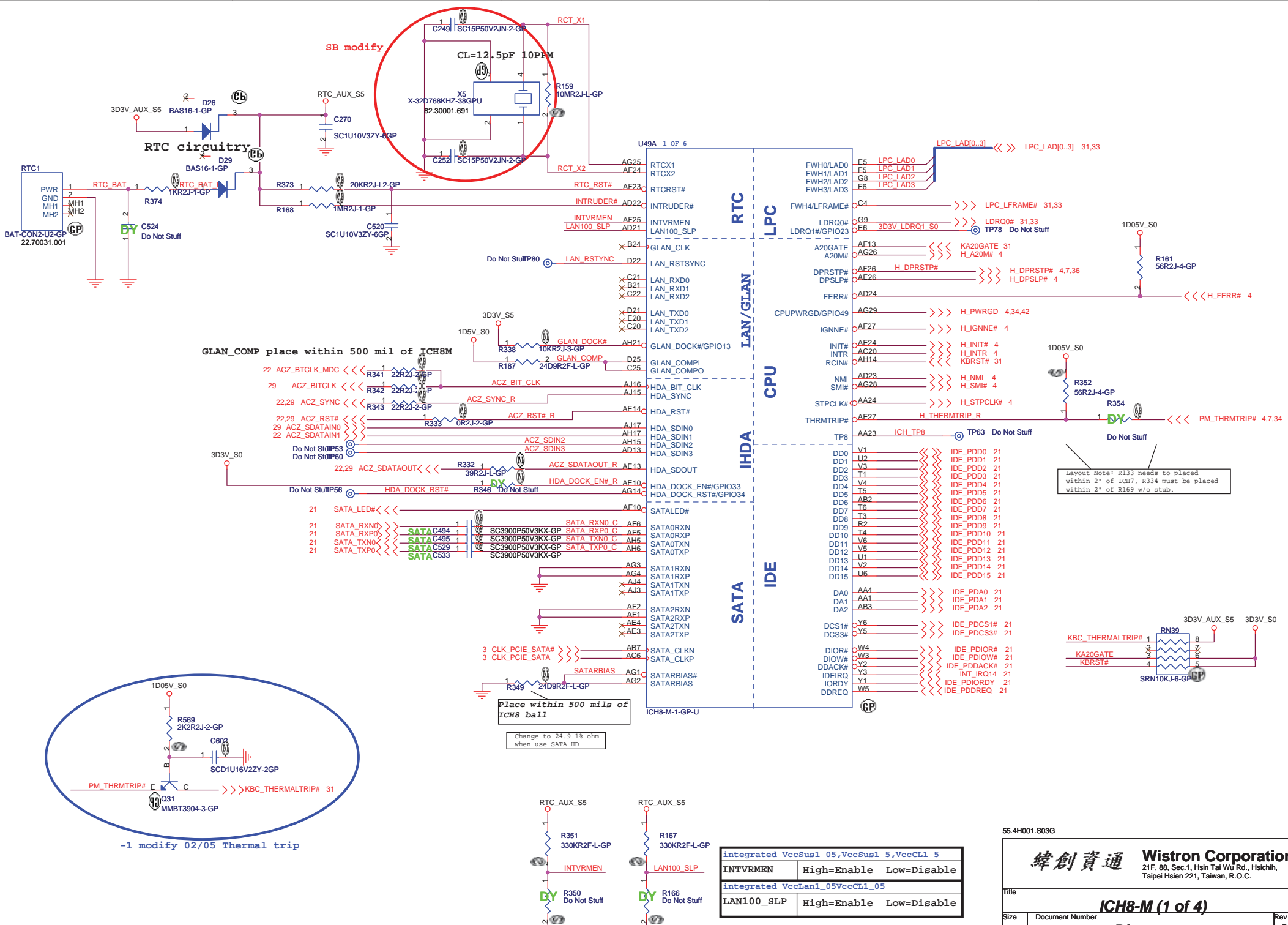


Ferrite bead impedance: 150 ohm@100MHz; 100mA(min) design recommend

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Title		<b>CRT/TV Connector</b>	
Size	Document Number	Rev	<b>-1</b>
Date: Thursday, March 01, 2007	Sheet	15	of 42



integrated VccSus1_05,VccSus1_5,VccCLL1_5		
INTVRMEN	High=Enable	Low=Disable
integrated VccLan1_05VccCLL1_05		
LAN100_SLP	High=Enable	Low=Disable

55.4H001.S03G

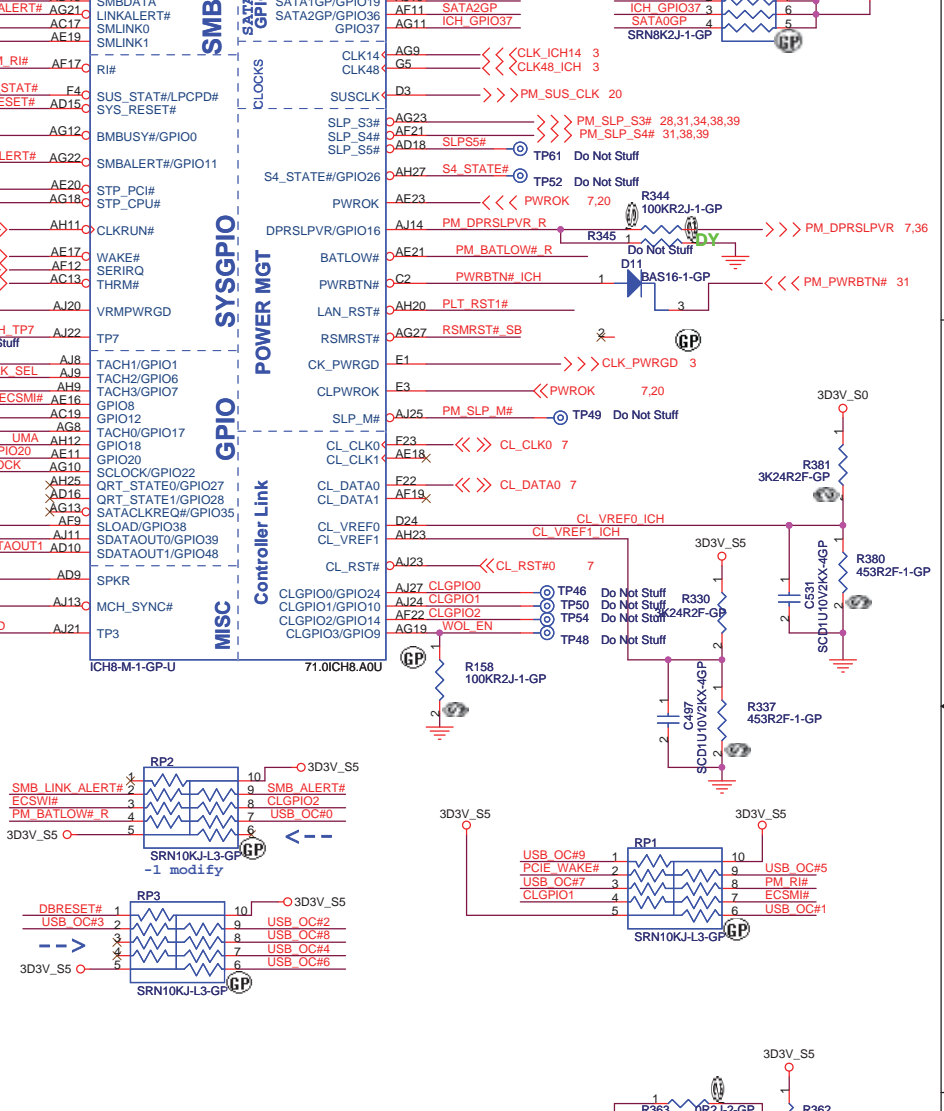
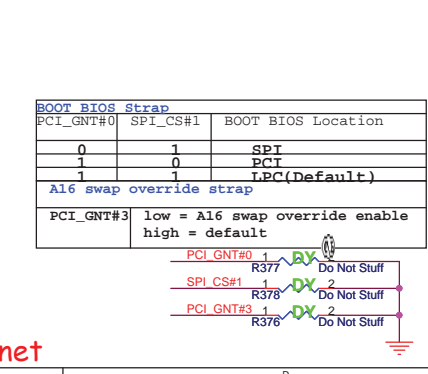
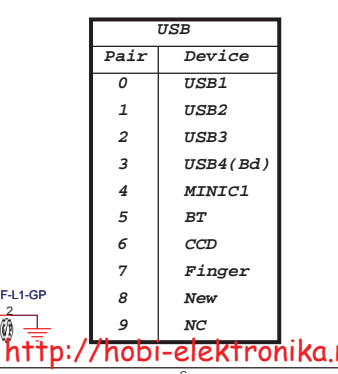
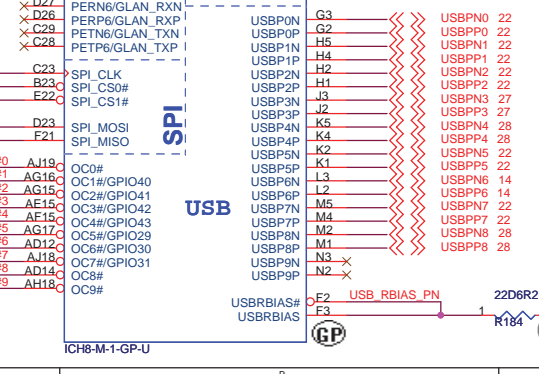
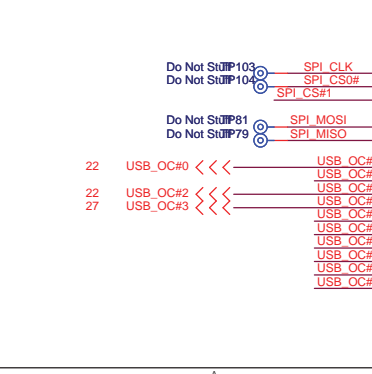
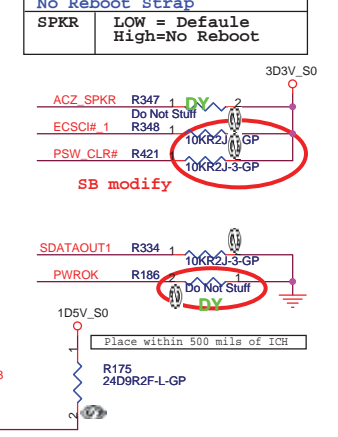
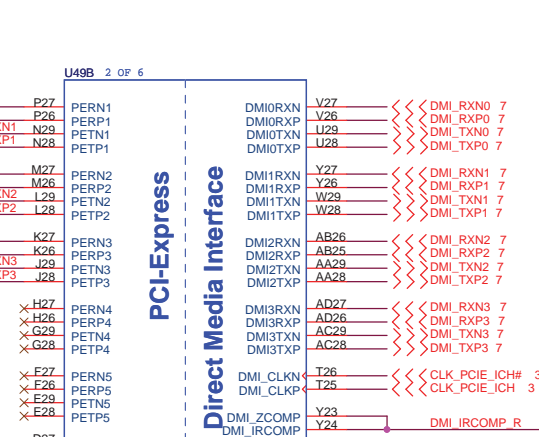
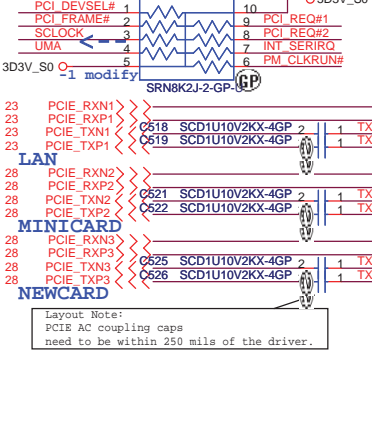
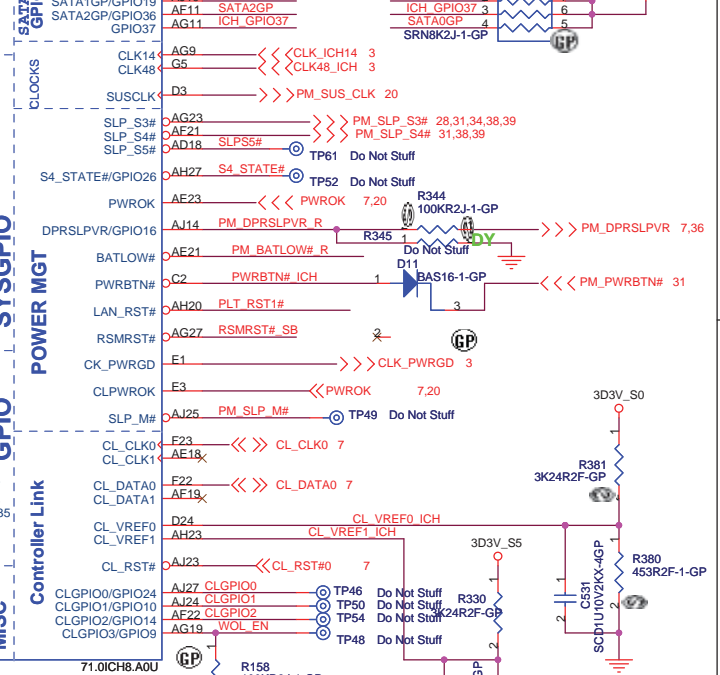
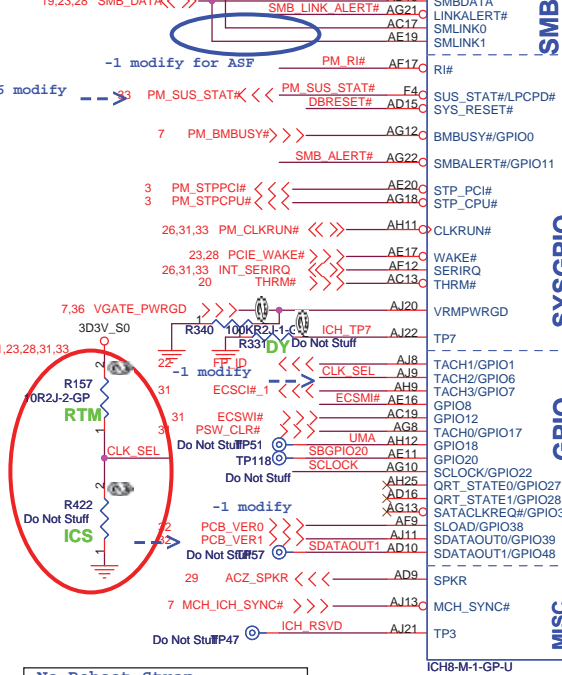
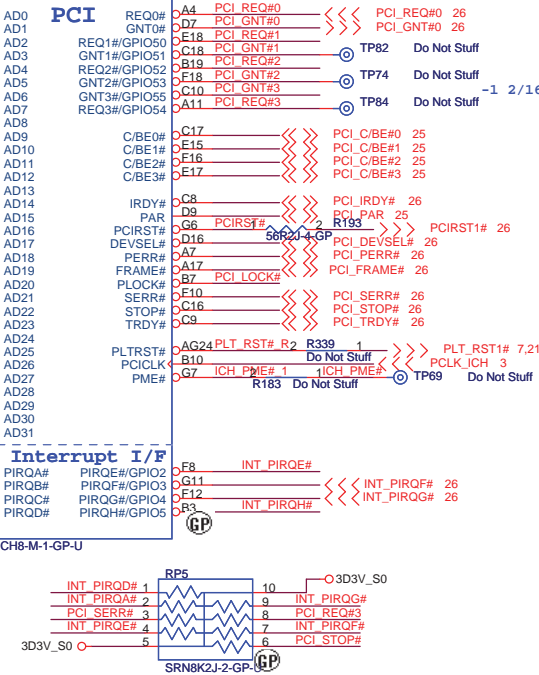
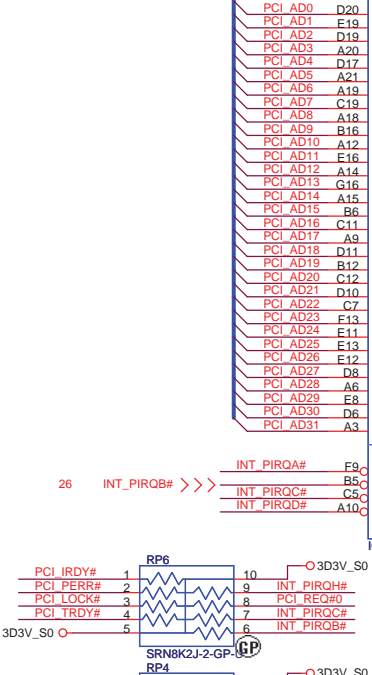
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Title: **ICH8-M (1 of 4)**

Size: Document Number: **Biwa** Rev: **SB**

Date: Thursday, March 01, 2007 Sheet 16 of 42

25,26 PCI\_AD[31..0] <<>



USB	
Pair	Device
0	USB1
1	USB2
2	USB3
3	USB4 (Bd)
4	MINIC1
5	BT
6	CCD
7	Finger
8	New
9	NC

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**ICH8-M (2 of 4)**

**Biwa**

Date: Thursday, March 01, 2007

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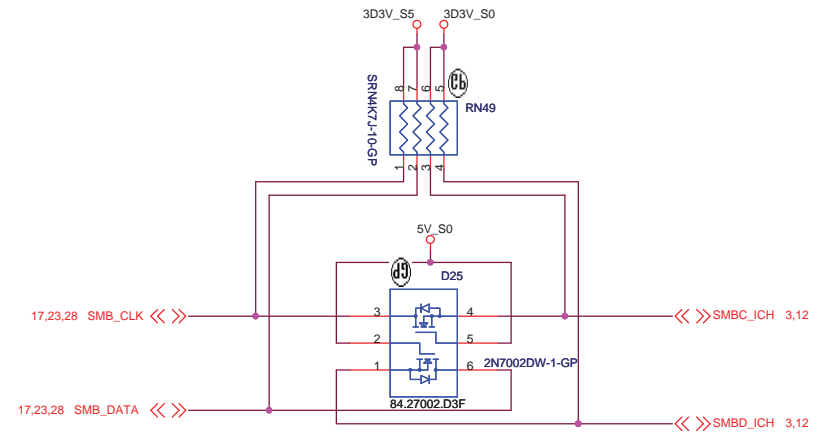
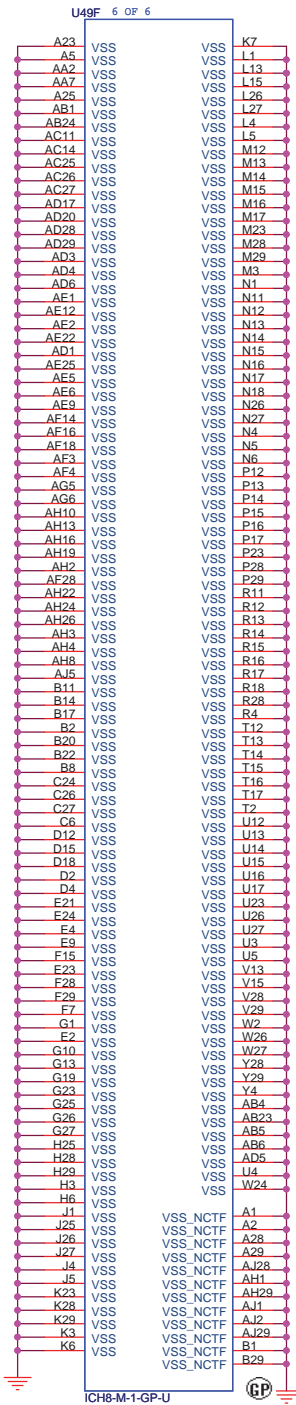
File:   
 Size:   
 Document Number:   
 Rev: -1

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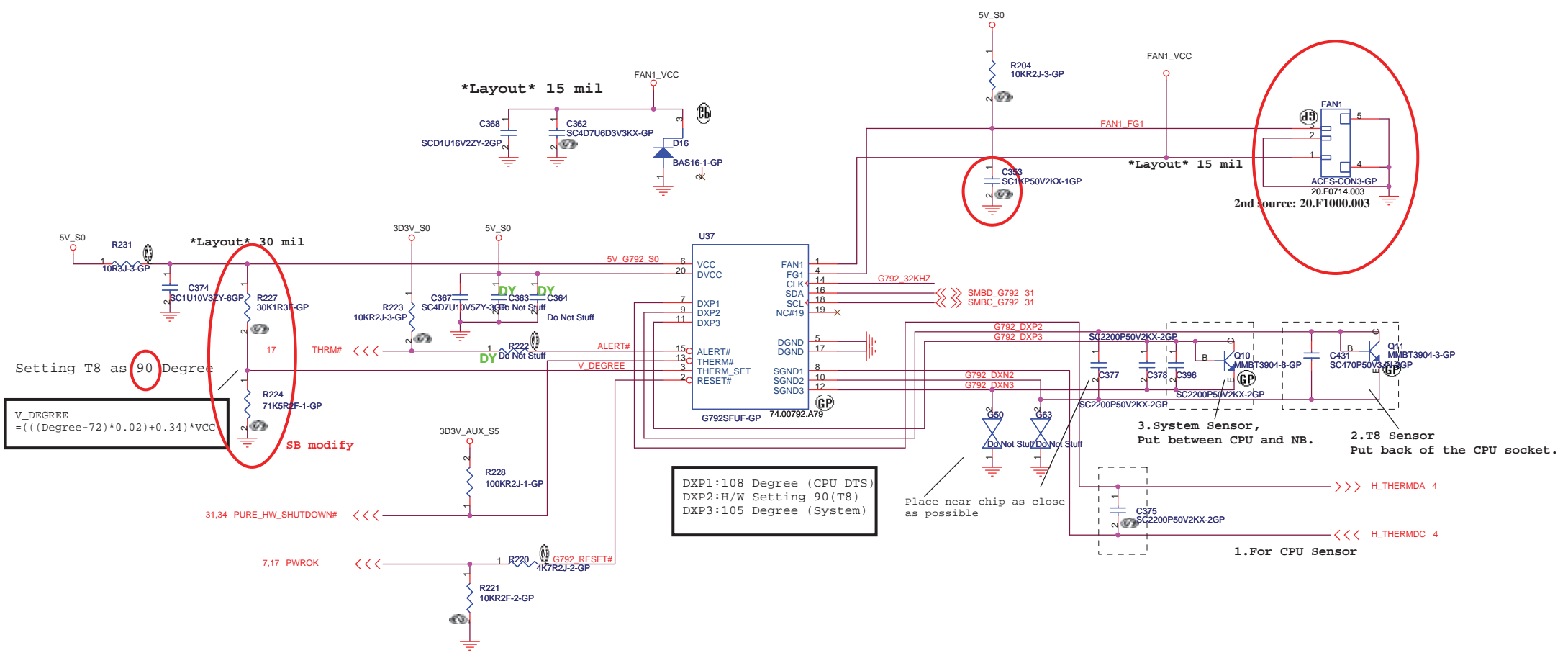




D55 connect SMLINK and SMBUS in S) for SMBus 2.0 compliance

### SMBUS

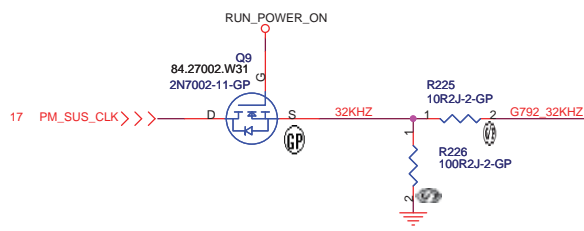
<b>Wistron Corporation</b> 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
<b>ICH8-M (4 of 4)</b>	
Size	Document Number
Date: Thursday, March 01, 2007	Rev SA
<b>Biwa</b>	
Sheet 19	of 42



Setting T8 as 90 Degree

$$V\_DEGREE = (((Degree-72)*0.02)+0.34)*VCC$$

DXP1:108 Degree (CPU DTS)  
DXP2:H/W Setting 90(T8)  
DXP3:105 Degree (System)



- 3. System Sensor, Put between CPU and NB.
- 2. T8 sensor Put back of the CPU socket.
- 1. For CPU Sensor

TEMP.	Digital Output Data Bits			
	Sign	MSB	LSB	EXT
+127.875	0	111	1111	111
+126.375	0	111	1110	011
+25.5	0	001	1001	100
+1.75	0	000	0001	110
+0.5	0	000	0000	100
+0.125	0	000	0000	001
-0.125	1	111	1111	111
-1.125	1	111	1110	111
-25.5	1	110	0110	100
-55.25	1	100	1000	110
-65.000	1	011	1111	000

Biwa Thermal Table 1106

Sensor	Temp	T6	T7
Sensor 0	CPU DTS	100	102
Sensor 1	CPU G792 Analog	110	113
Sensor 2	System G792	85	87
Sensor 3	T8		
Sensor 4	ADIA status		

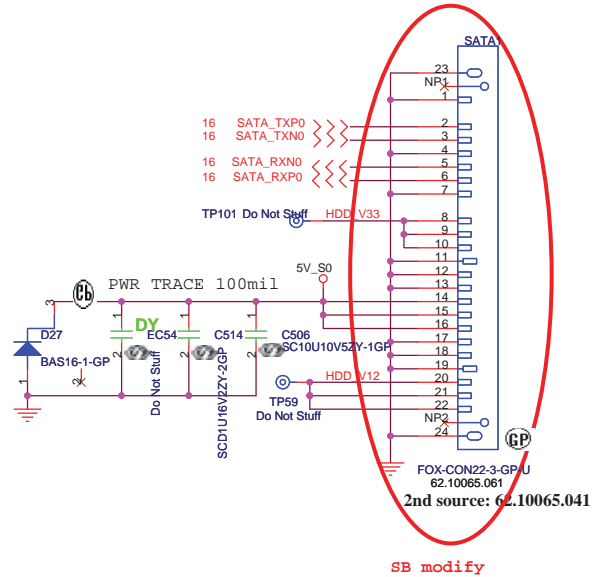
**緯創資通 Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **Thermal/Fan Controller**

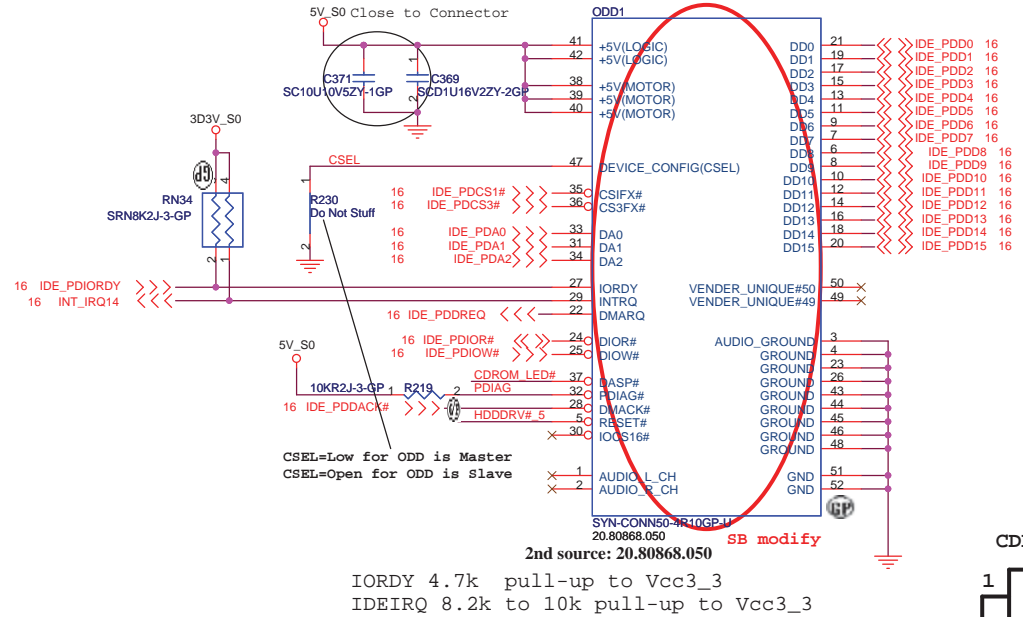
Size: Document Number: **Biwa** Rev: **SB**

Date: Thursday, March 01, 2007 Sheet 20 of 42

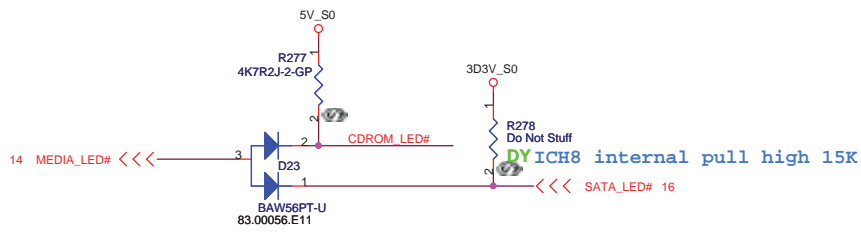
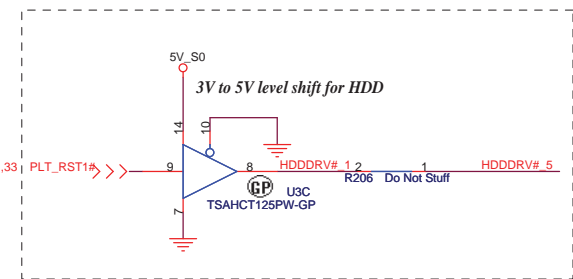
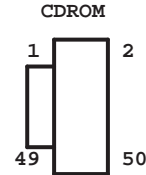
# SATA Connector



# ODD Connector



IORDY 4.7k pull-up to Vcc3\_3  
 IDEIRQ 8.2k to 10k pull-up to Vcc3\_3



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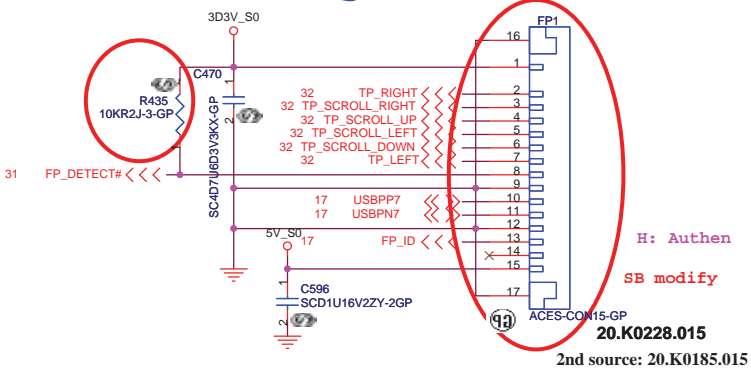
**緯創資通** Wistron Corporation  
 21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title  
**HDD and CDROM**

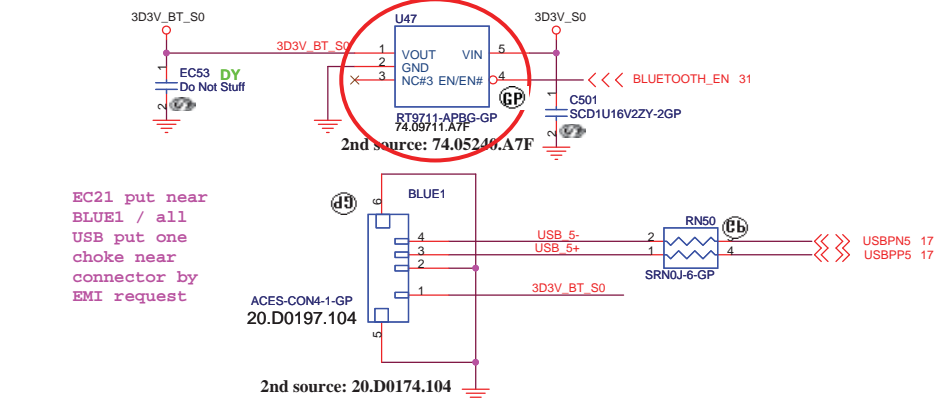
Size Document Number  
**Biwa**

Date: Thursday, March 01, 2007 Sheet 21 of 42  
 Rev **SB**

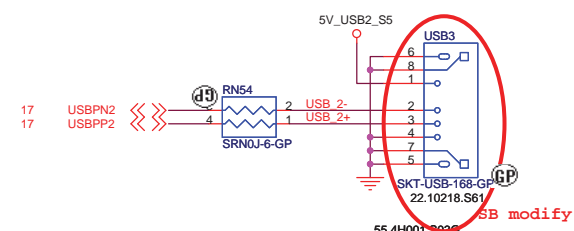
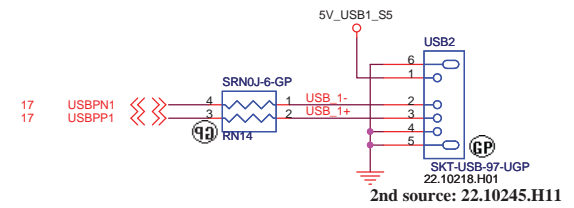
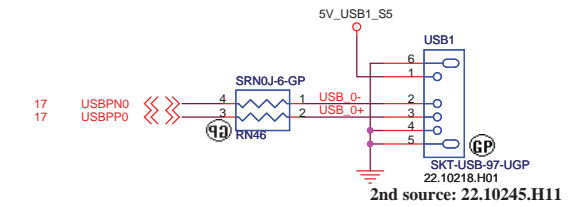
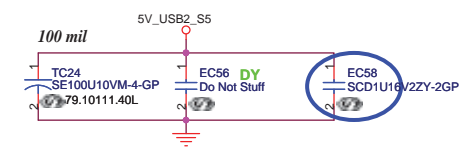
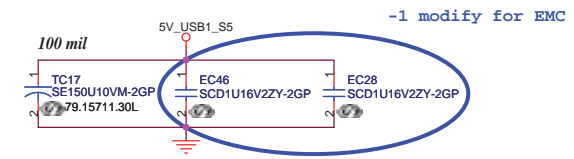
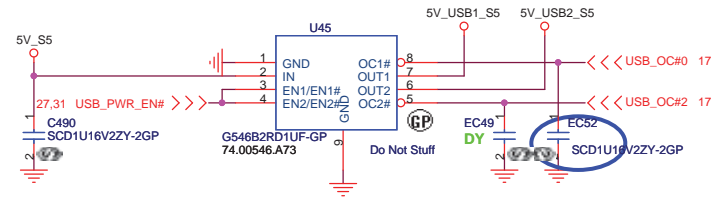
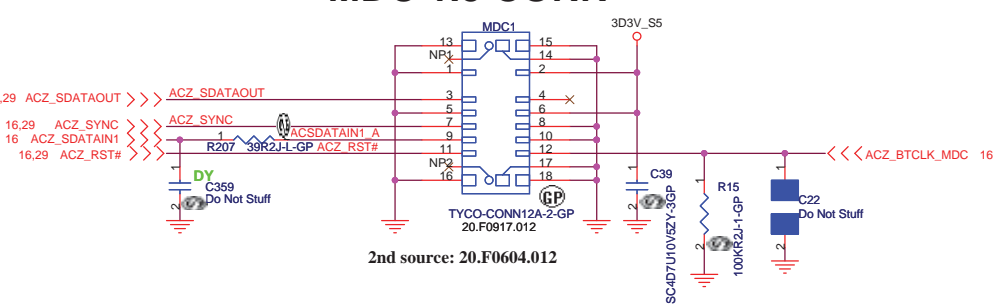
# Finger Print



# BLUETOOTH MODULE



# MDC 1.5 CONN

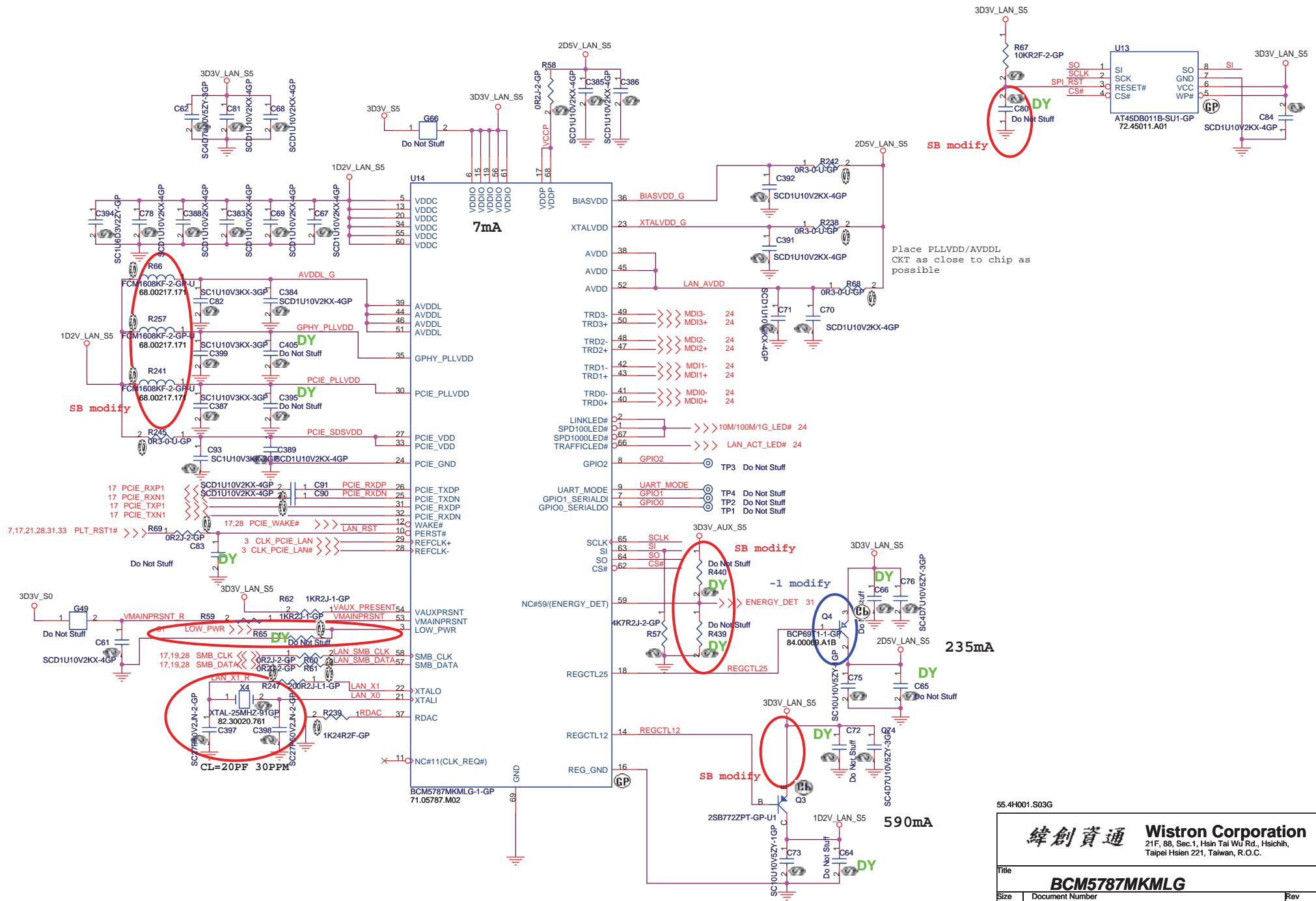


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Title: **USB / MDC / BLUETOOTH / FP**

Size: Document Number **Biwa** Rev **-1**

Date: Thursday, March 01, 2007 Sheet 22 of 42



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55.4H001.S03G

<b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
<b>BCM5787MKMLG</b>	
Title	
Size A3	Document Number
<b>Biwa</b>	
Date: Thursday, March 01, 2007	Rev <b>-1</b>



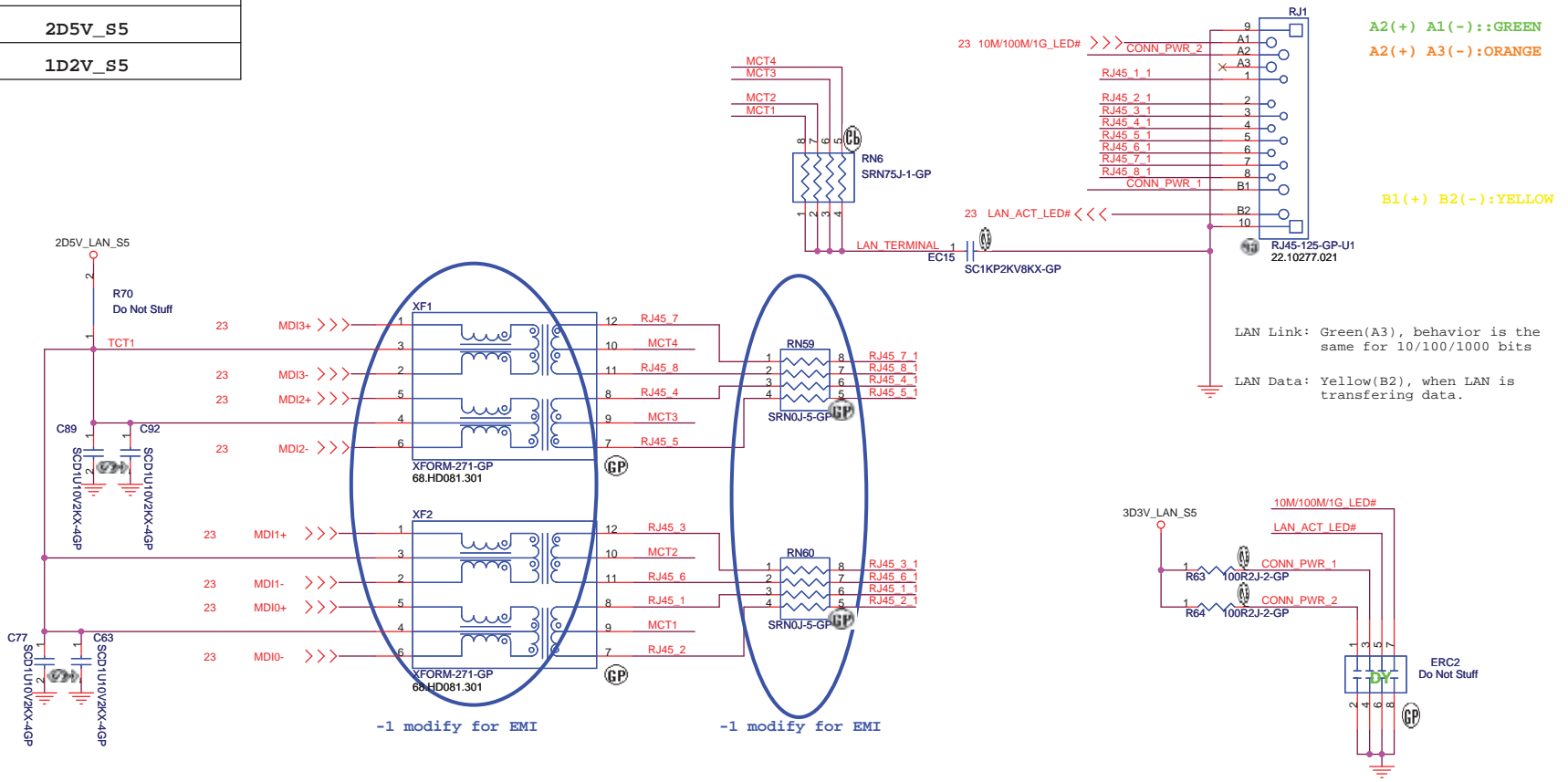
Voltage Rail	4401E	5789	5787
VDDIO_PCI	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDC	1D8V_LAN_S5	1D2V_LAN_S5	
VDDIO	3D3V_LAN_S5	3D3V_LAN_S5	
VESD	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDP	Don't Care	2D5V_S5	
3D3V_2D5V_S5	3D3V_S5	2D5V_S5	
1D8V_1D2V_S5	1D8V_LAN_S5	1D2V_S5	

# LAN Connector

LED COLOR

A2(+) A1(-)::GREEN  
A2(+) A3(-):ORANGE

B1(+) B2(-):YELLOW



- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width, 12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat, except RJ-45 moat.

**RJ11 signal must leave the other signal or power plane 100mil.**

DOC\_TIP,DOC\_RING,TIP,RING:  
W/S : 10/100 @ Surface layers  
10/20 @ Inner layers

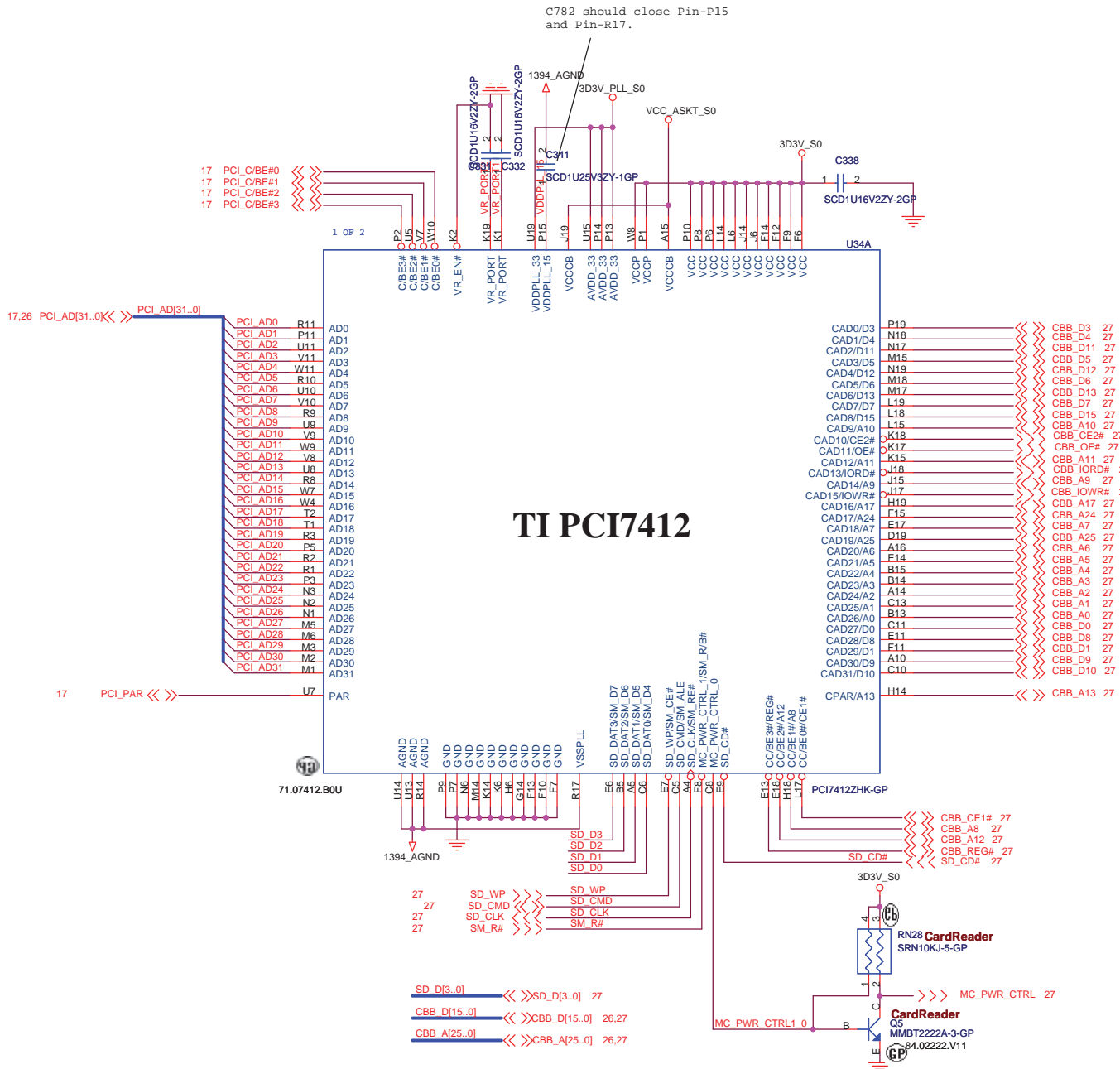
10/100 LAN Transformer	RJ45 PIN
TD+ --> TX+	RJ45-1
TD- --> TX-	RJ45-2
RD+ --> RX+	RJ45-3
RD- --> RX-	RJ45-6

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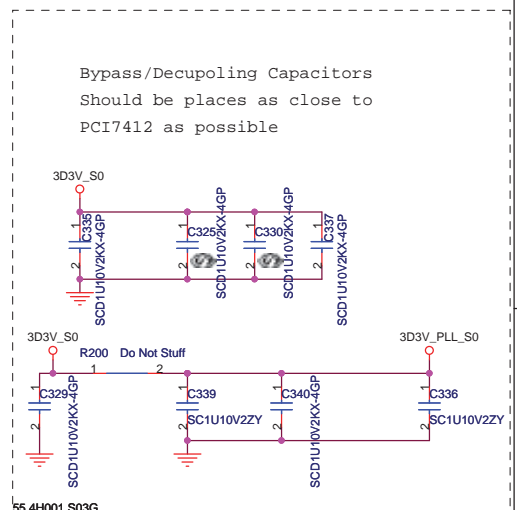
**緯創資通 Wistron Corporation**  
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Title <b>LAN Connector</b>		
Size A3	Document Number <b>Biwa</b>	Rev <b>-1</b>
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# TI PCI7412

\* All 1394 signals must be routed on top side only  
 \* Differential pairs of each ports should have equal trace length  
 \* Stubs must be keep as short as possible



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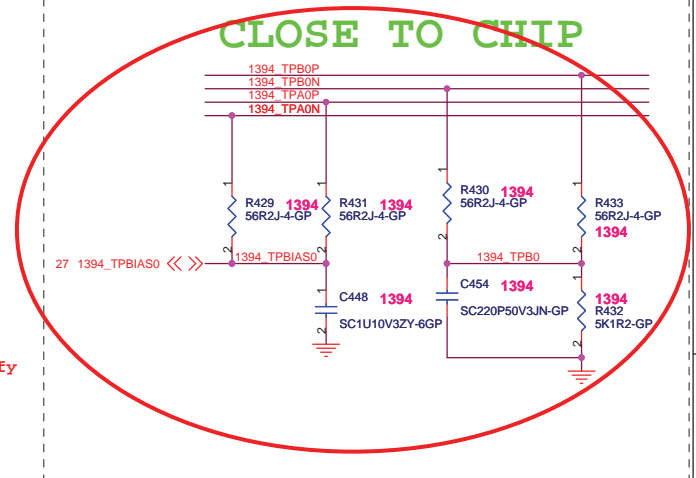
**緯創資通 Wistron Corporation**  
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Title: **TI PCI7412 (1 of 2)**

Size: Document Number Rev SA

Date: Thursday, March 01, 2007 Sheet 26 of 42

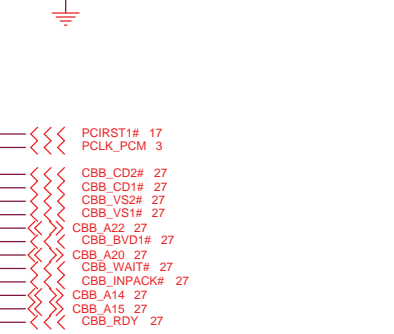
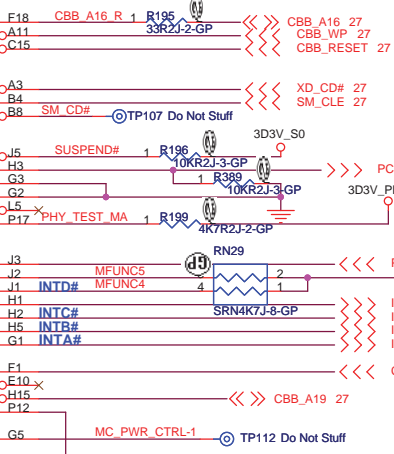
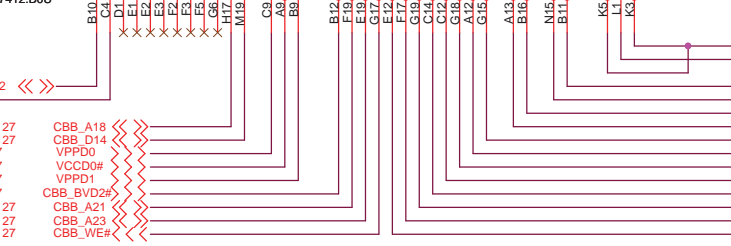
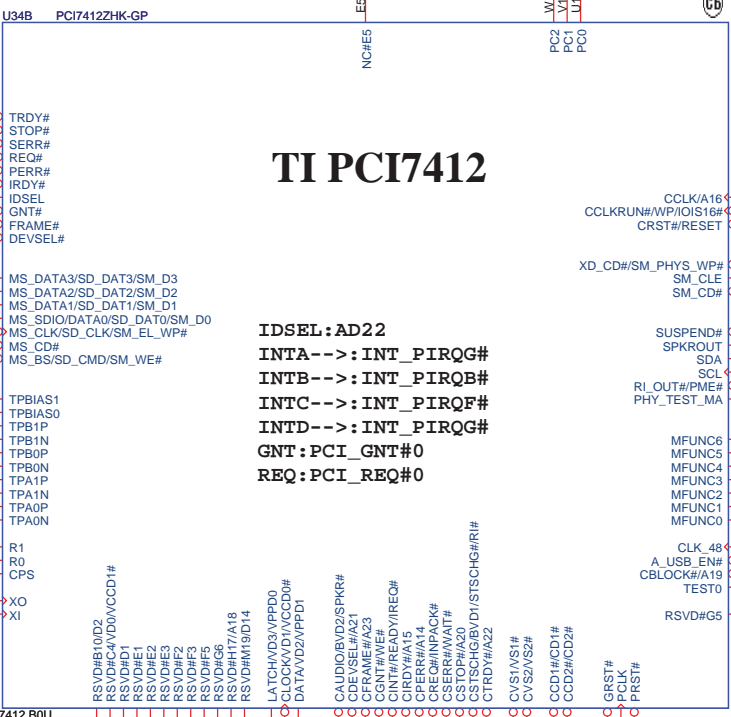
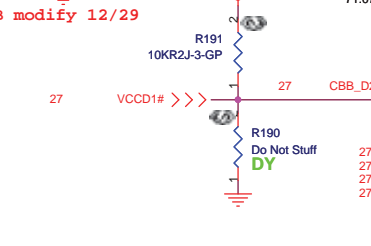
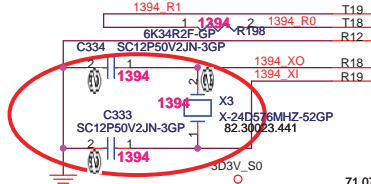
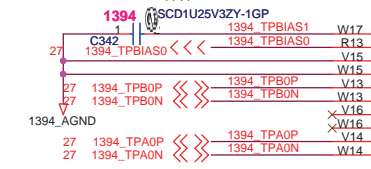
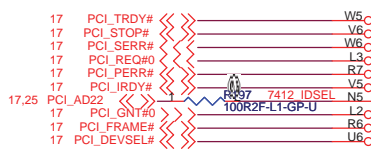
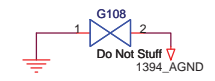
CLOSE TO CHIP



# TI PCI7412

**IDSEL:AD22**  
**INTA-->:INT\_PIRQG#**  
**INTB-->:INT\_PIRQB#**  
**INTC-->:INT\_PIRQF#**  
**INTD-->:INT\_PIRQG#**  
**GNT:PCI\_GNT#0**  
**REQ:PCI\_REQ#0**

INTA# CARBUS 1 (INT\_PIRQG#)  
 INTB# 1394 (INT\_PIRQB#)  
 INTC# Flash Media (INT\_PIRQF#)  
 INTD# SD Host (INT\_PIRQG#) share  
 MFUNC4: use bit 19-16 Register define.

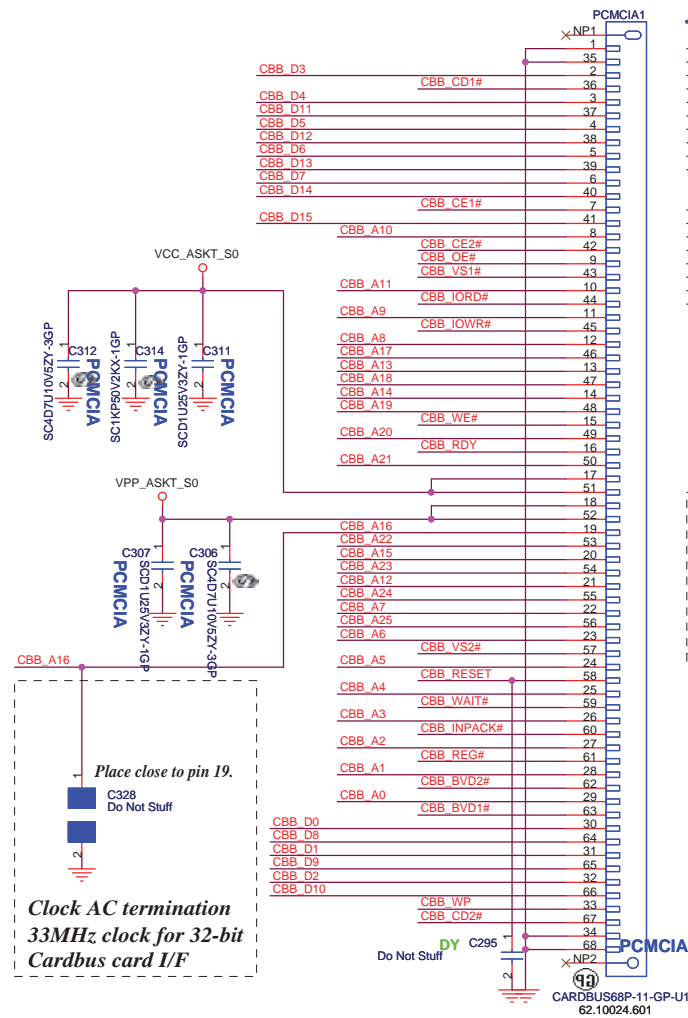


55.4H001.S03G

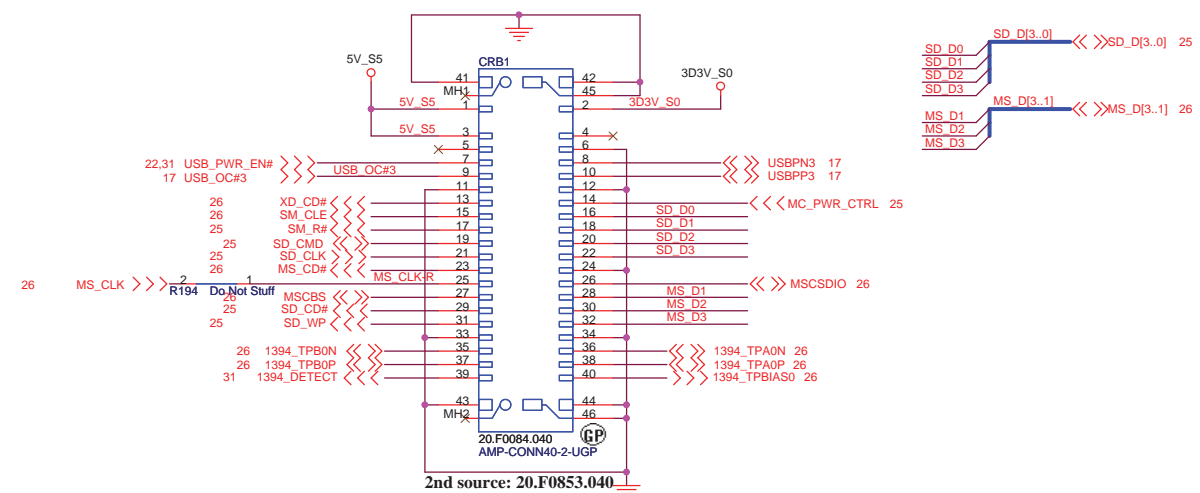
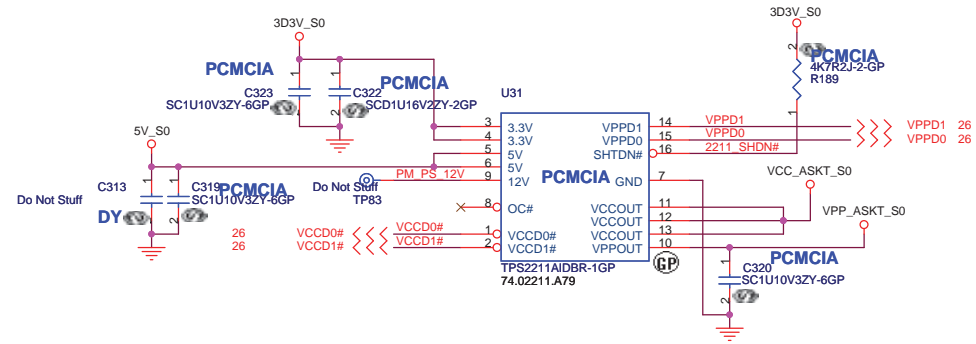
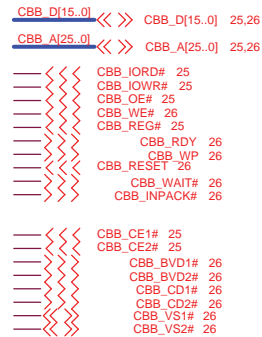
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 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title		TI PCI7412 (2 of 2)	
Size	Document Number	Rev	
		SB	
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# PCMCIA Socket



## Cardbus I/F



XD  
MS / MS PRO  
SD / SD IO / MMC

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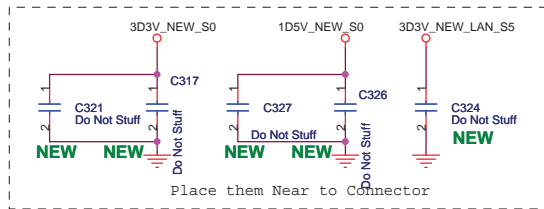
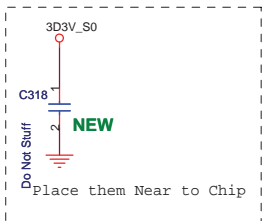
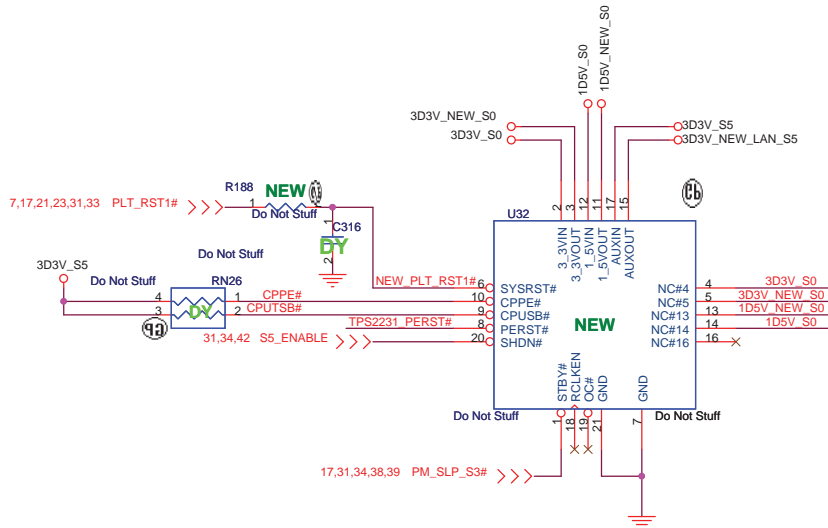
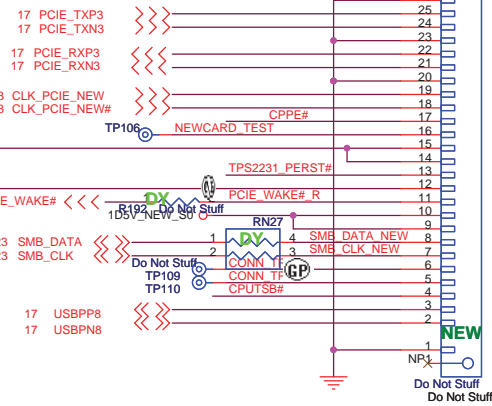
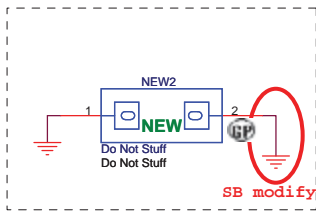
Title: **PCMCIA / CARD READER BD**

Size: Document Number: **Biwa** Rev: SA

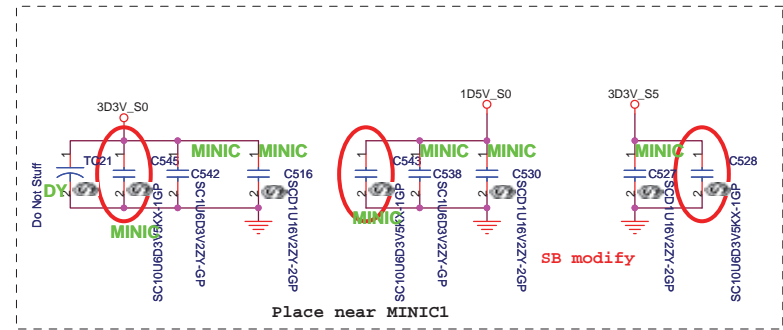
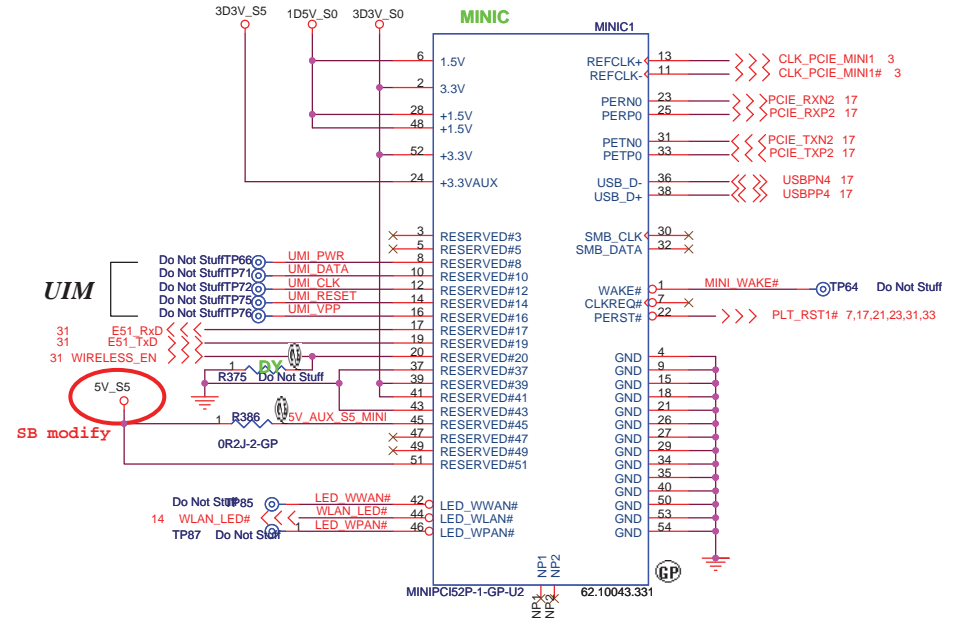
Date: Thursday, March 01, 2007 Sheet 27 of 42

# NEWCARD Connector

Reserve the symbol for bottom side connector



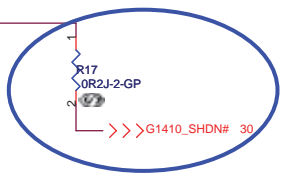
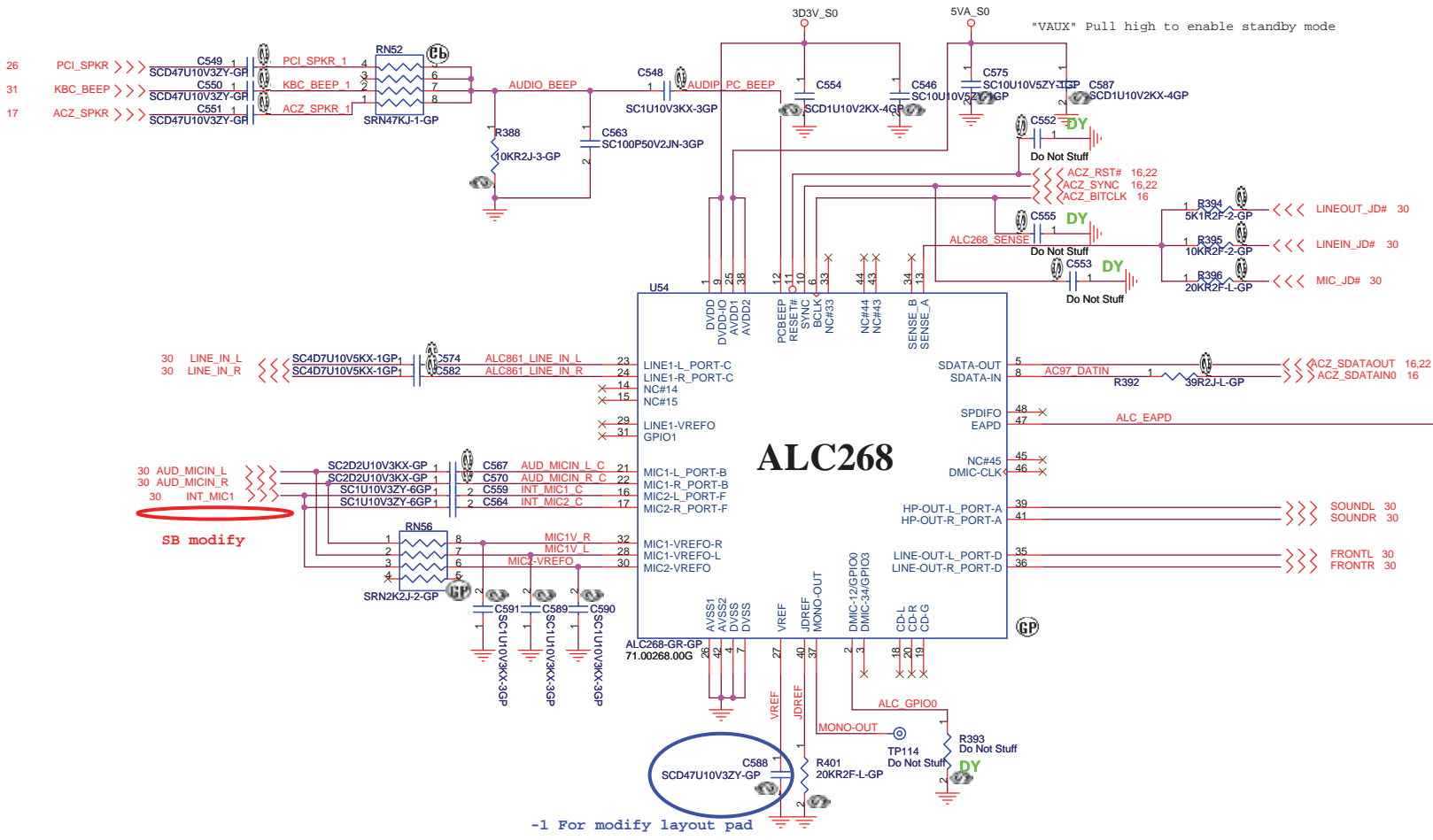
# Mini Card Connector



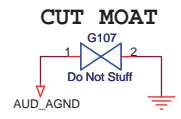
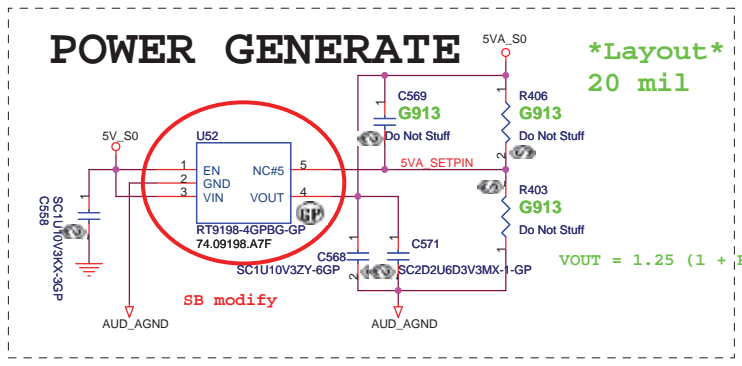
55.4H001.S03G

<b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsein 221, Taiwan, R.O.C.	
<b>MINI CARD / NEW CARD</b>	
<b>Biwa</b>	
Title	Rev
Size	Document Number
Date: Thursday, March 01, 2007	Sheet 28 of 42





-1 For modify for POPO noise

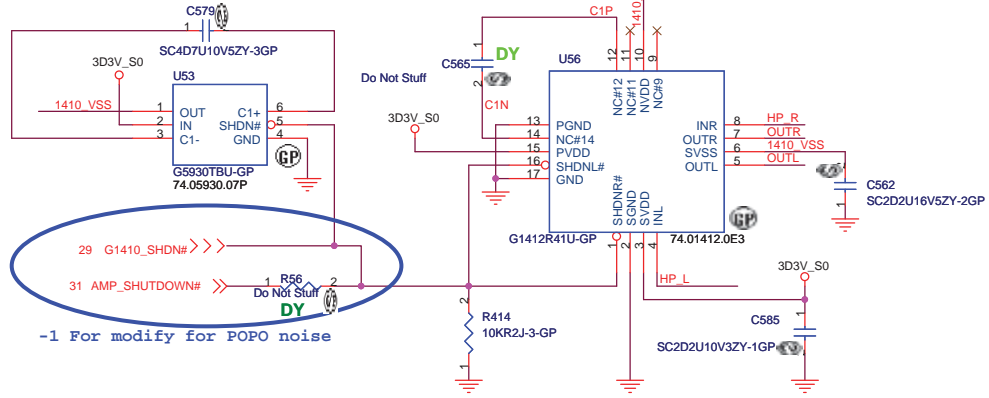
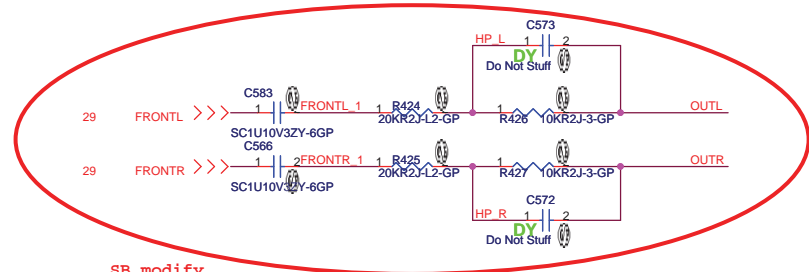
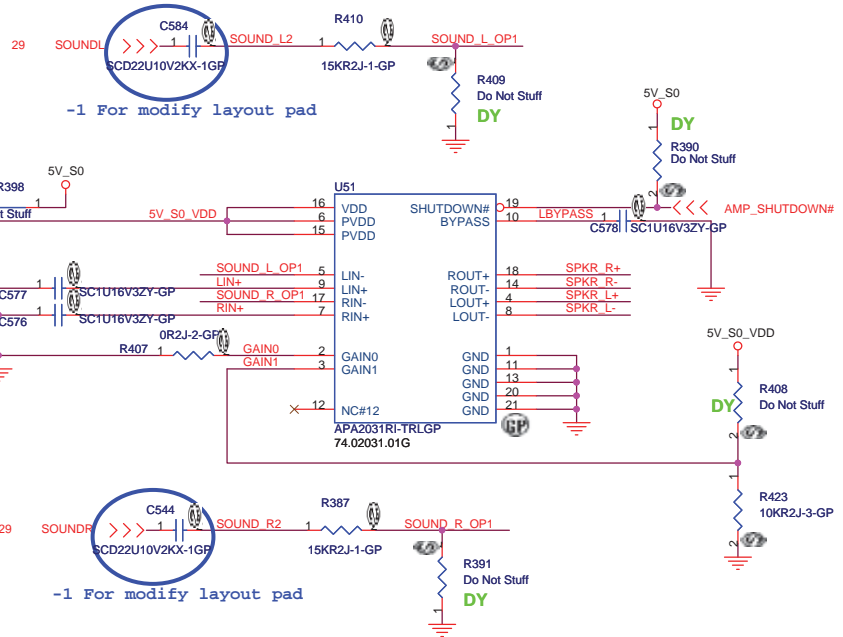


<http://hobi-elektronika.net>

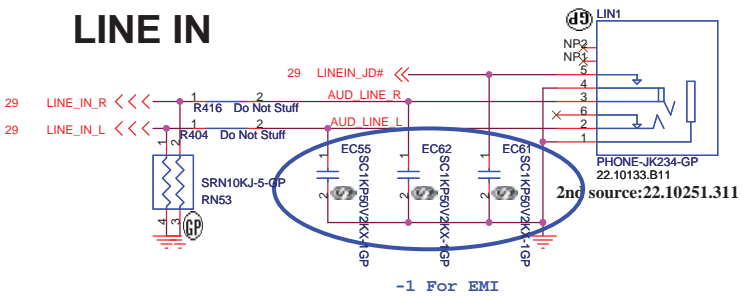
55.4H001.S03G	
<b>緯創資通 Wistron Corporation</b>	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <b>AZALIA CODEC - ALC268</b>	
Size	Document Number <b>Biwa</b>
Date: Thursday, March 01, 2007	Sheet 29 of 42
	Rev <b>-1</b>

# AUDIO OP AMPLIFIER

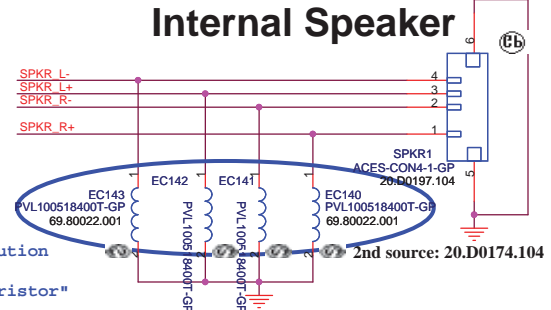
I/P signal level need +5V level



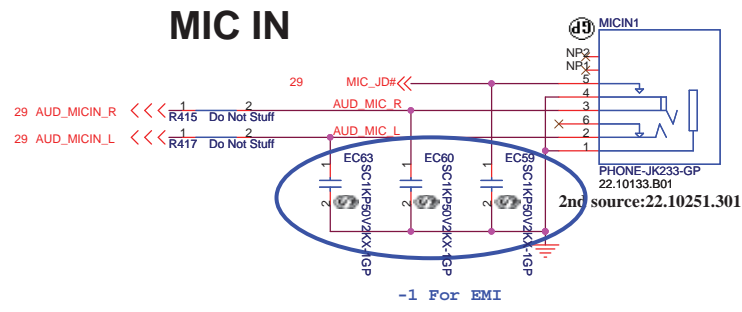
## LINE IN



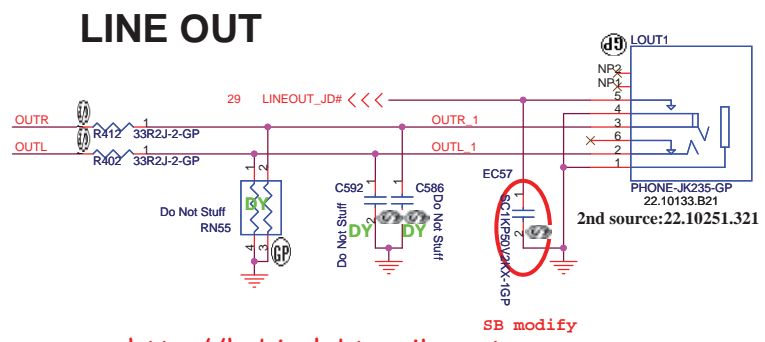
## Internal Speaker



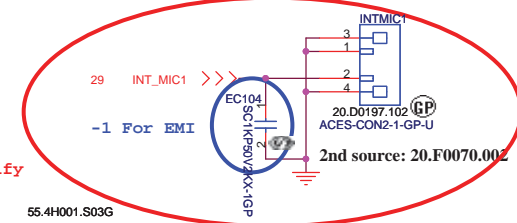
## MIC IN



## LINE OUT



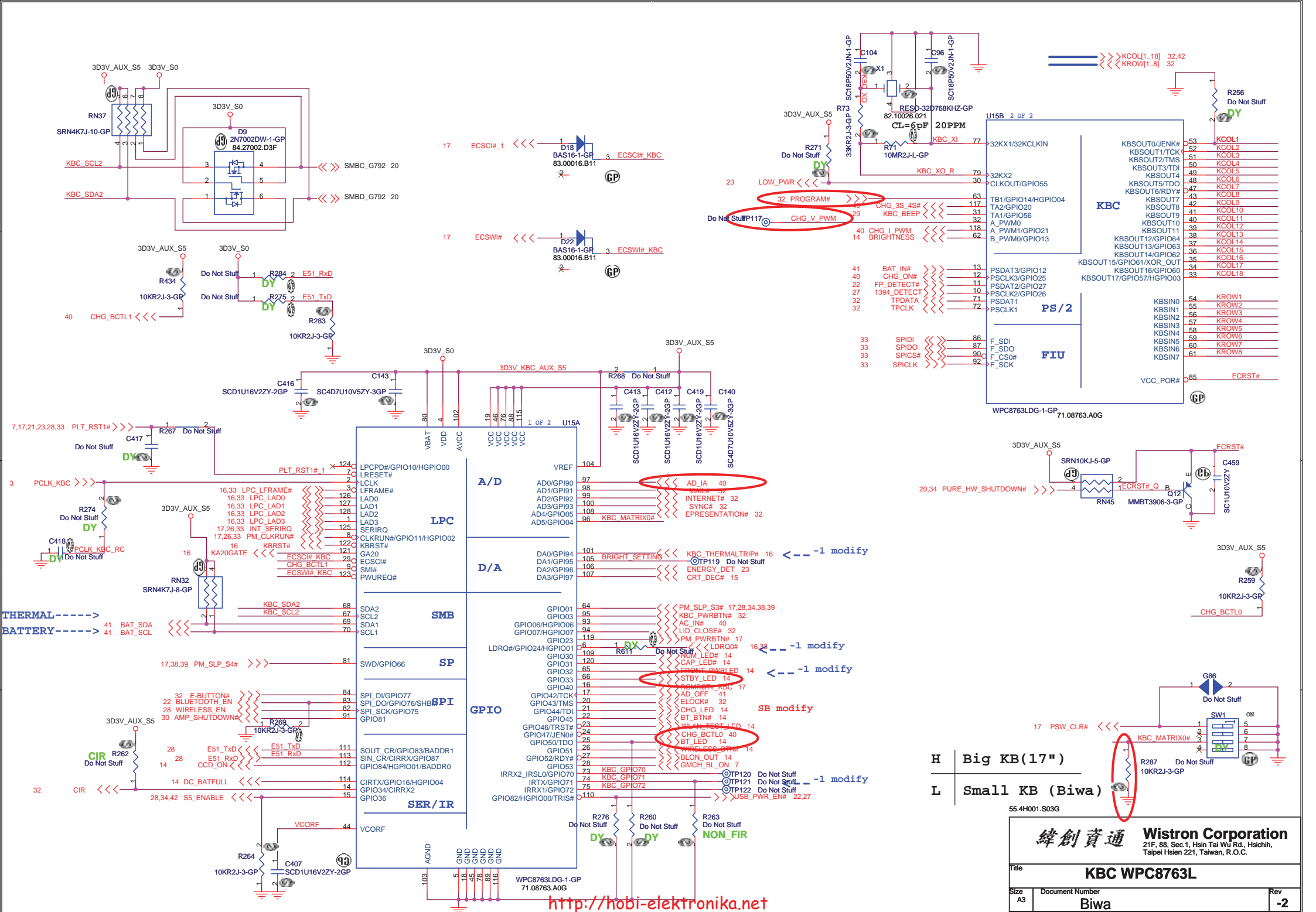
## Internal Microphone



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**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title		<b>AUDIO AMP AND JACK</b>	
Size	Document Number	Rev	
A3		-2	
Date:	Thursday, March 01, 2007	Sheet	30 of 42



<http://hobi-elektronika.net>

- H | Big KB (17")
- L | Small KB (Biwa)

55.4H001.S03G

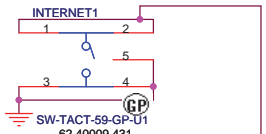
**緯創資通** **Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title: **KBC WPC8763L**

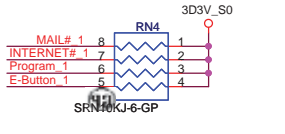
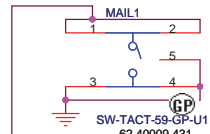
Size: A3 | Document Number: **Biwa** | Rev: **-2**

Date: Thursday, March 01, 2007 | Sheet: 31 of 42

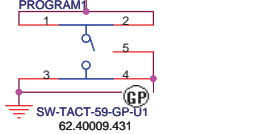
### Internet Button



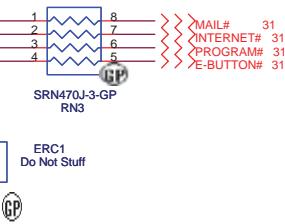
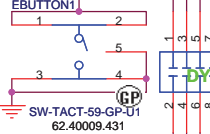
### Mail Button



### Program Button

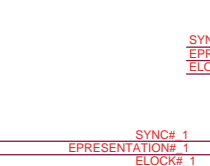
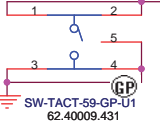


### E-Button

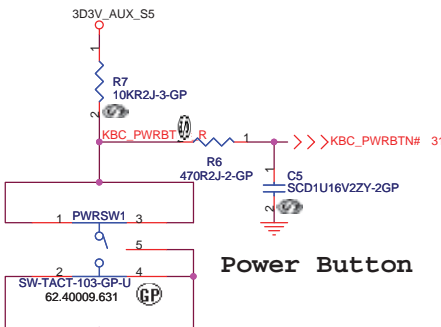
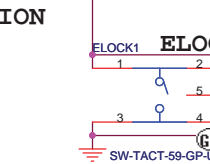
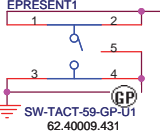


2nd source: 62.40009.561

### SYNC

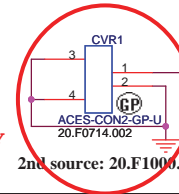


### EPRESENTATION



### Power Button

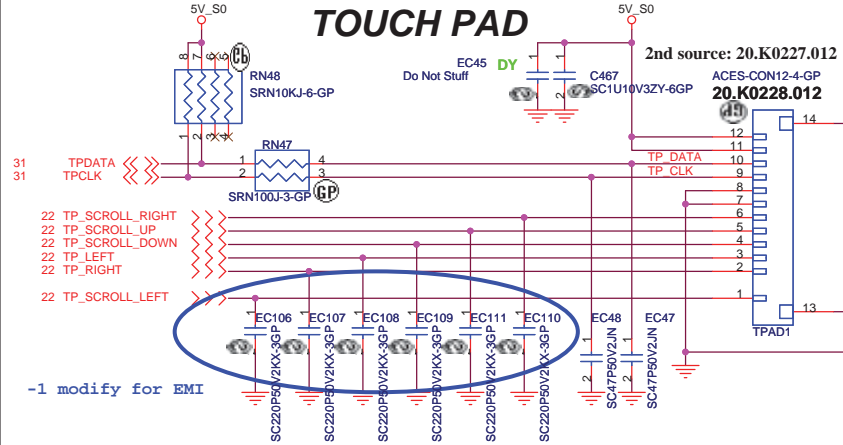
### Cover Up Switch



SB modify

2nd source: 20.F1000.002

### TOUCH PAD



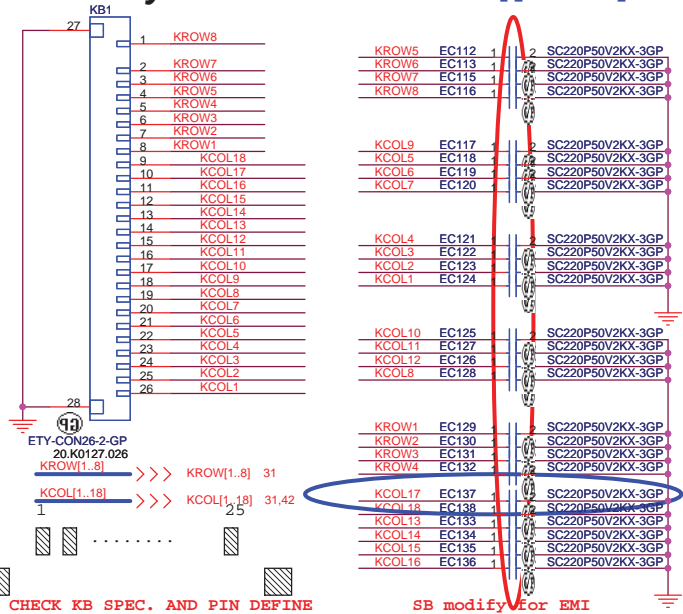
2nd source: 20.K0227.012

20.K0228.012

-1 modify for EMI

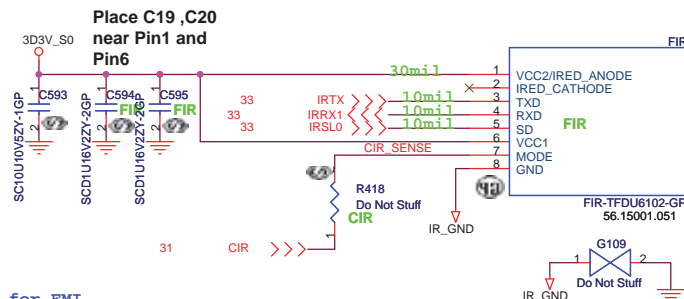
### Internal KeyBoard CONN

EMI Bypass cap.



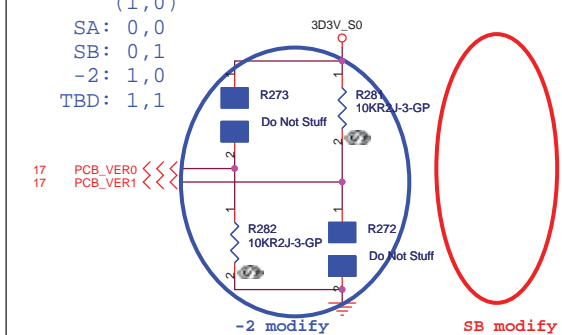
### VISHAY FIR Module

Layout Guide:  
 (1) FIR\_3D3V : 30 mils,  
 (2) C583, C581 close to U32



1 modify for EMI

PlanarID  
 (1,0)  
 SA: 0,0  
 SB: 0,1  
 -2: 1,0  
 TBD: 1,1



-2 modify

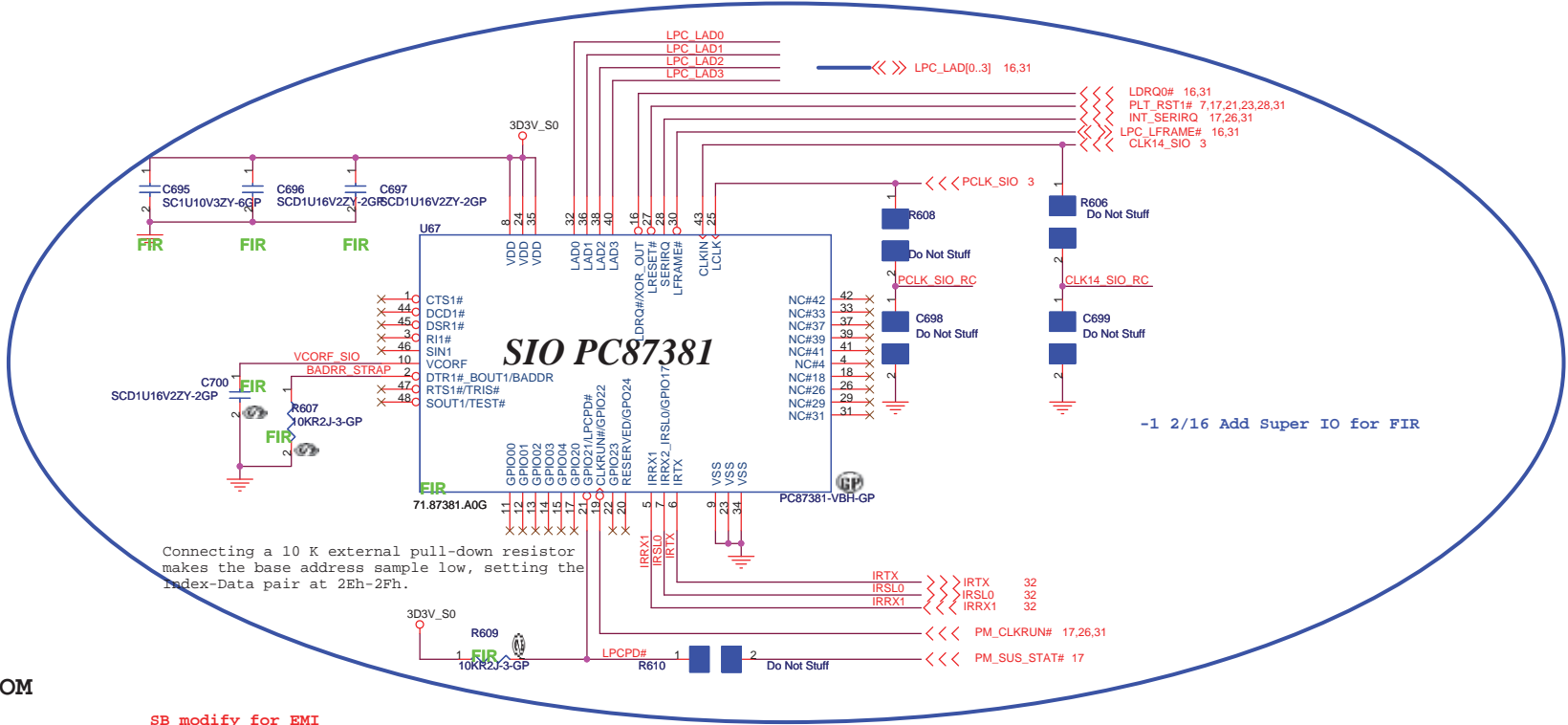
SB modify

55.4H001.S03G

緯創資通 Wistron Corporation  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

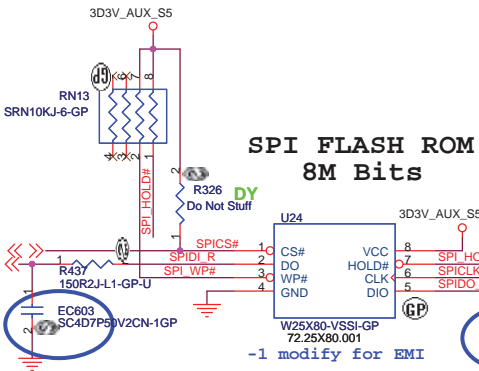
Title	BUTTONS / KB / TOUCHPAD / FIR		
Size	Document Number	Biwa	Rev -2
Date	Thursday, March 01, 2007	Sheet 32	of 42

<http://hobi-elektronika.net>



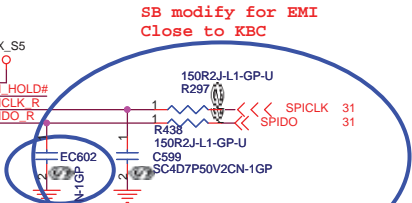
-1 2/16 Add Super IO for FIR

Connecting a 10 K external pull-down resistor makes the base address sample low, setting the Index-Data pair at 2Eh-2Fh.



**SPI FLASH ROM  
8M Bits**

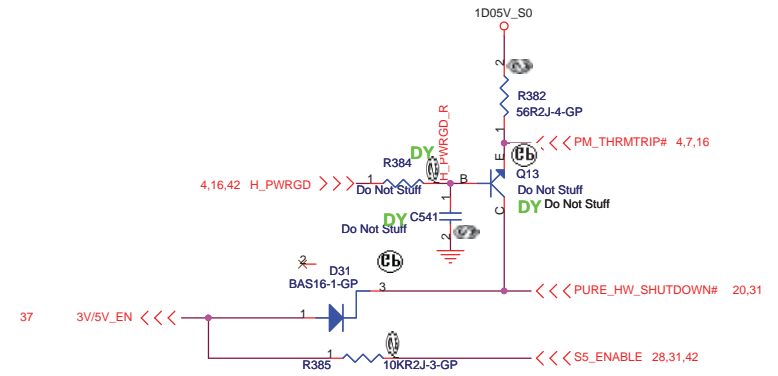
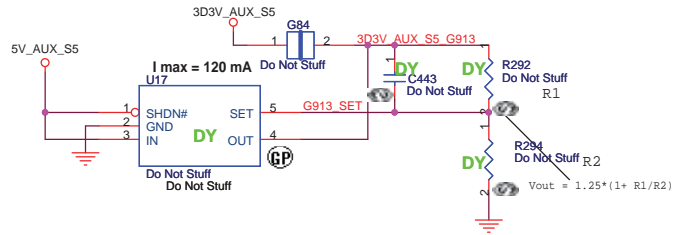
-1 modify for EMI



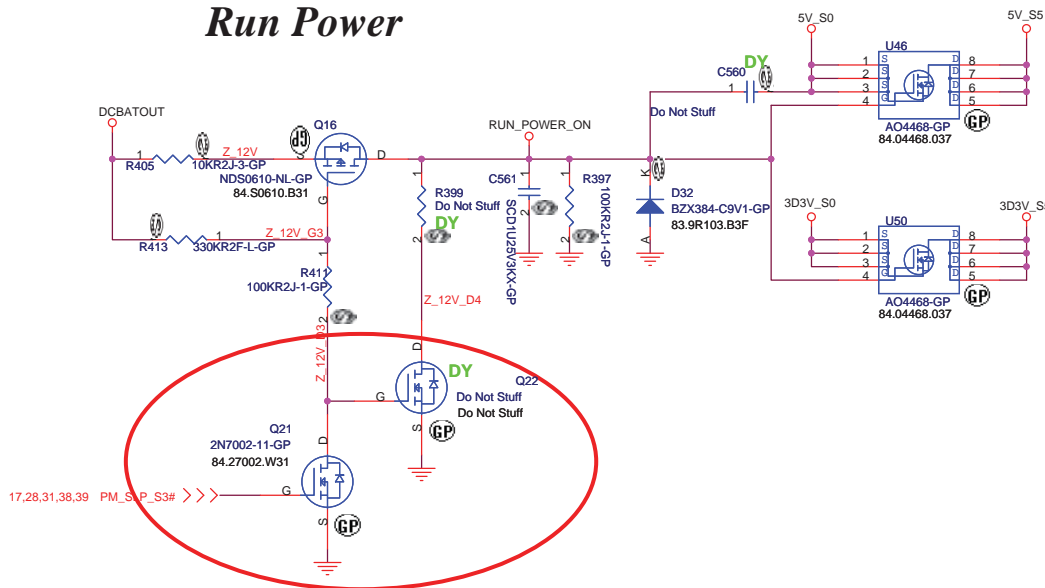
EMI RC circuit Close to output Pin R first then C to GND

SB modify for EMI  
Close to KBC

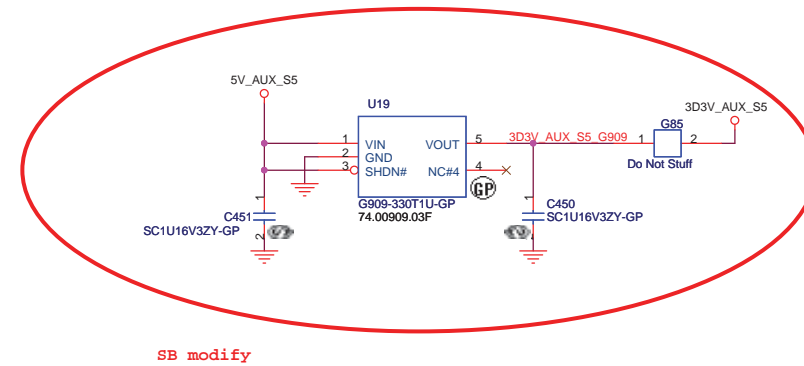
## Aux Power 3D3V\_AUX\_S5



## Run Power

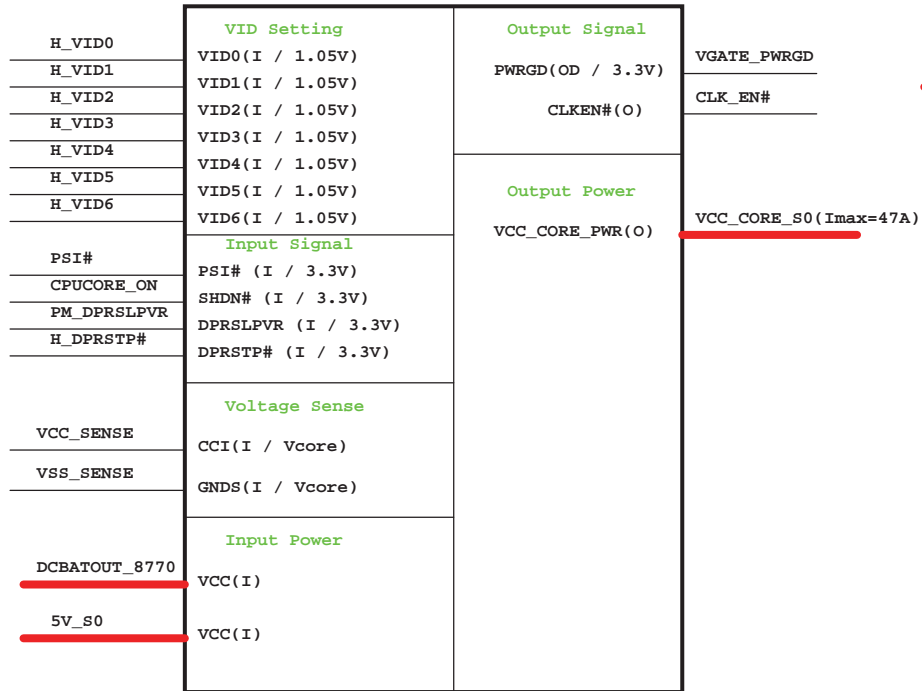


## Aux Power 3D3V\_AUX\_S5

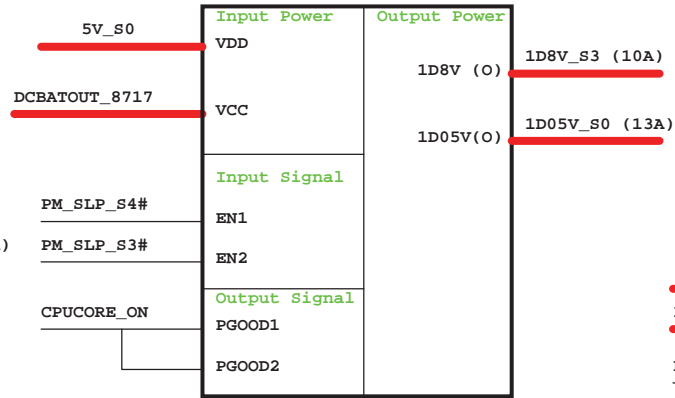




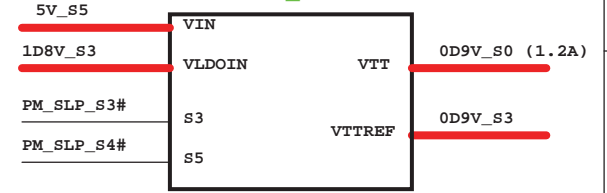
**CPU\_CORE**  
**MAXIM MAX8770**



**MAX8717**  
**1D8V/1D05V**

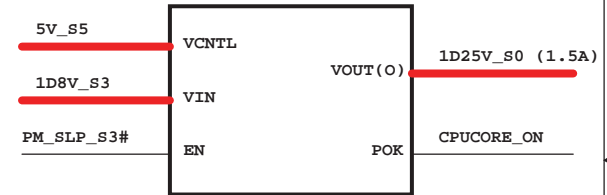


**0D9V\_S0**



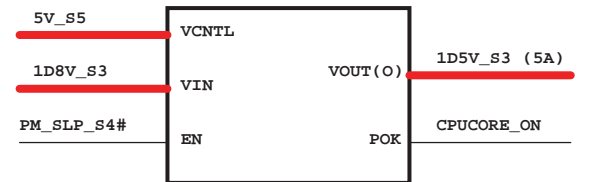
**TPS51100**

**1D25V\_S0**



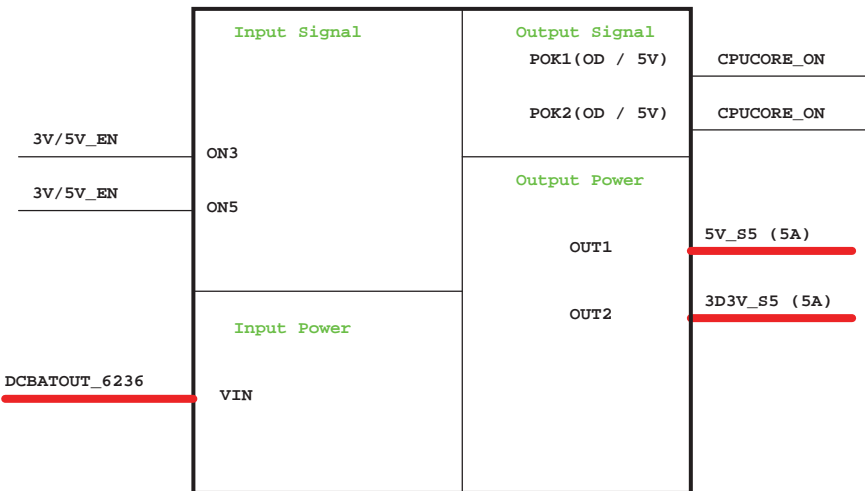
**APL5915**

**1D5V\_S3**

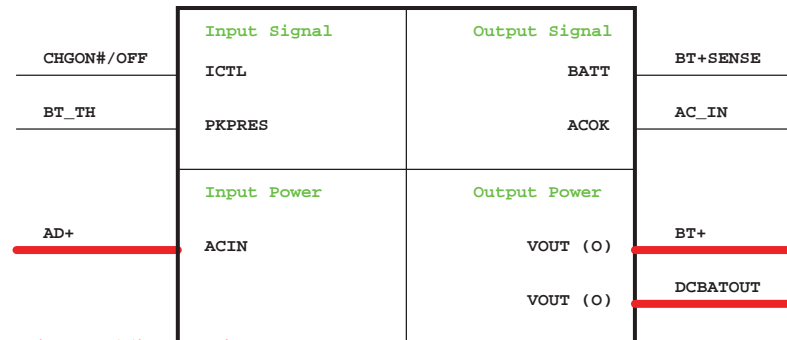


**APL5912**

**ISL6236**  
**5V/3D3V**



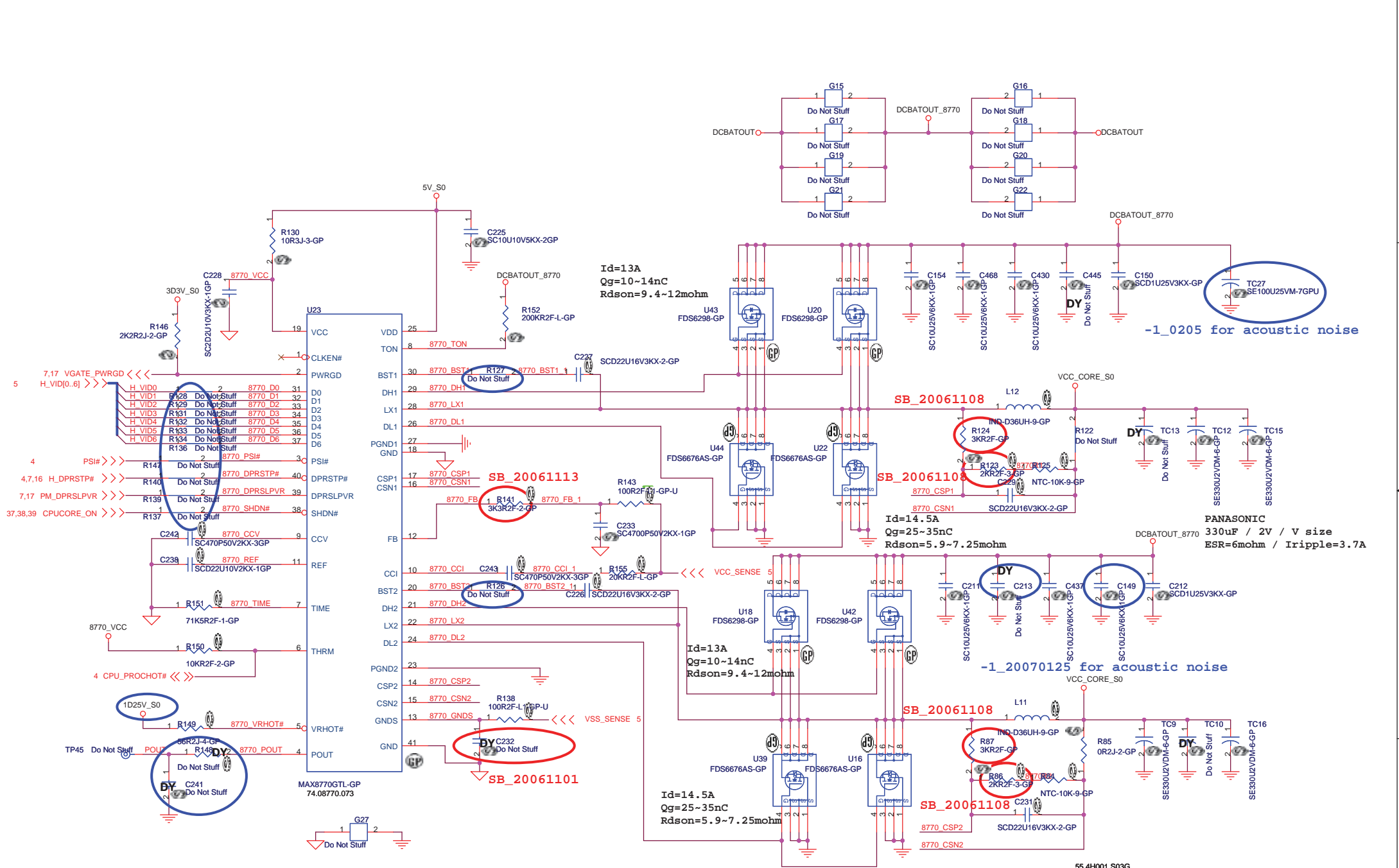
**Charger ISL6255**



<http://hobi-elektronika.net>

55.4H001.S03G

<b>緯創資通 Wistron Corporation</b>	
<small>21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</small>	
<b>Power Block Diagram</b>	
Size A3	Document Number <b>Biwa</b> Rev SA
Date: Thursday, March 01, 2007	Sheet 35 of 42



-1\_0205 for acoustic noise

-1\_20070125 for acoustic noise

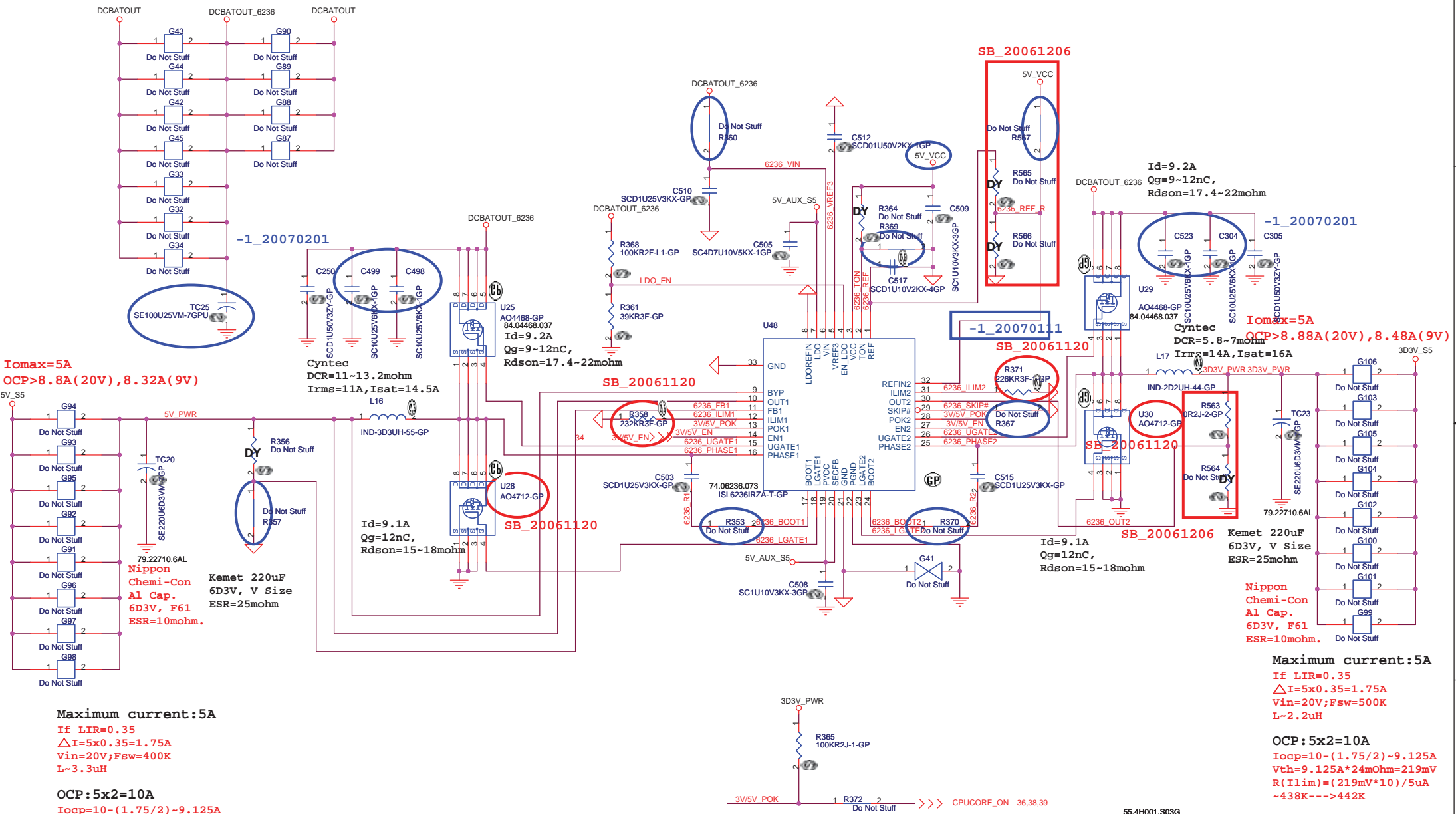
55.4H001.S03G

**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
 Taipei Hsien 221, Taiwan, R.O.C.

Title: **VCC CORE**

Size A3 Document Number: **Biwa** Rev: **-1**

Date: Thursday, March 01, 2007 Sheet 36 of 42



**I<sub>omax</sub>=5A**  
**OCP>8.8A (20V), 8.32A (9V)**

5V\_S5  
 G94 Do Not Stuff  
 G93 Do Not Stuff  
 G95 Do Not Stuff  
 G92 Do Not Stuff  
 G91 Do Not Stuff  
 G96 Do Not Stuff  
 G97 Do Not Stuff  
 G98 Do Not Stuff  
 G99 Do Not Stuff  
 G100 Do Not Stuff  
 G101 Do Not Stuff  
 G102 Do Not Stuff  
 G103 Do Not Stuff  
 G104 Do Not Stuff  
 G105 Do Not Stuff  
 G106 Do Not Stuff

**Maximum current:5A**  
 If LIR=0.35  
 $\Delta I = 5 \times 0.35 = 1.75A$   
 $V_{in} = 20V; F_{sw} = 400K$   
 $L > 3.3\mu H$

**OCP: 5x2=10A**  
 $I_{ocp} = 10 - (1.75/2) = 9.125A$   
 $V_{th} = 9.125A * 24m\Omega = 219mV$   
 $R(I_{lim}) = (219mV * 10) / 5uA$   
 $\approx 438K \rightarrow 442K$

**-1\_20070201**  
 TC25 SE100U25VM-7GPU  
 C250 SCD1U50V3ZY-GP  
 C499 SC10U25V6KX-1GP  
 C498 SC10U25V6KX-1GP  
 U25 AO4468-GP 84.04468.037  
**I<sub>d</sub>=9.2A**  
**Q<sub>g</sub>=9~12nC,**  
**R<sub>dson</sub>=17.4~22mohm**

**Cyntec**  
 DCR=11~13.2mohm  
 I<sub>rms</sub>=11A, I<sub>sat</sub>=14.5A  
 L16 IND-3D3UH-55-GP  
**I<sub>d</sub>=9.1A**  
**Q<sub>g</sub>=12nC,**  
**R<sub>dson</sub>=15~18mohm**

**SB\_20061120**  
 R358 232KR3F-GP  
 R359 3V/5V\_POK  
 R360 6236 UGATE1  
 R361 6236 PHASE1  
 U28 AO4712-GP  
**SB\_20061120**

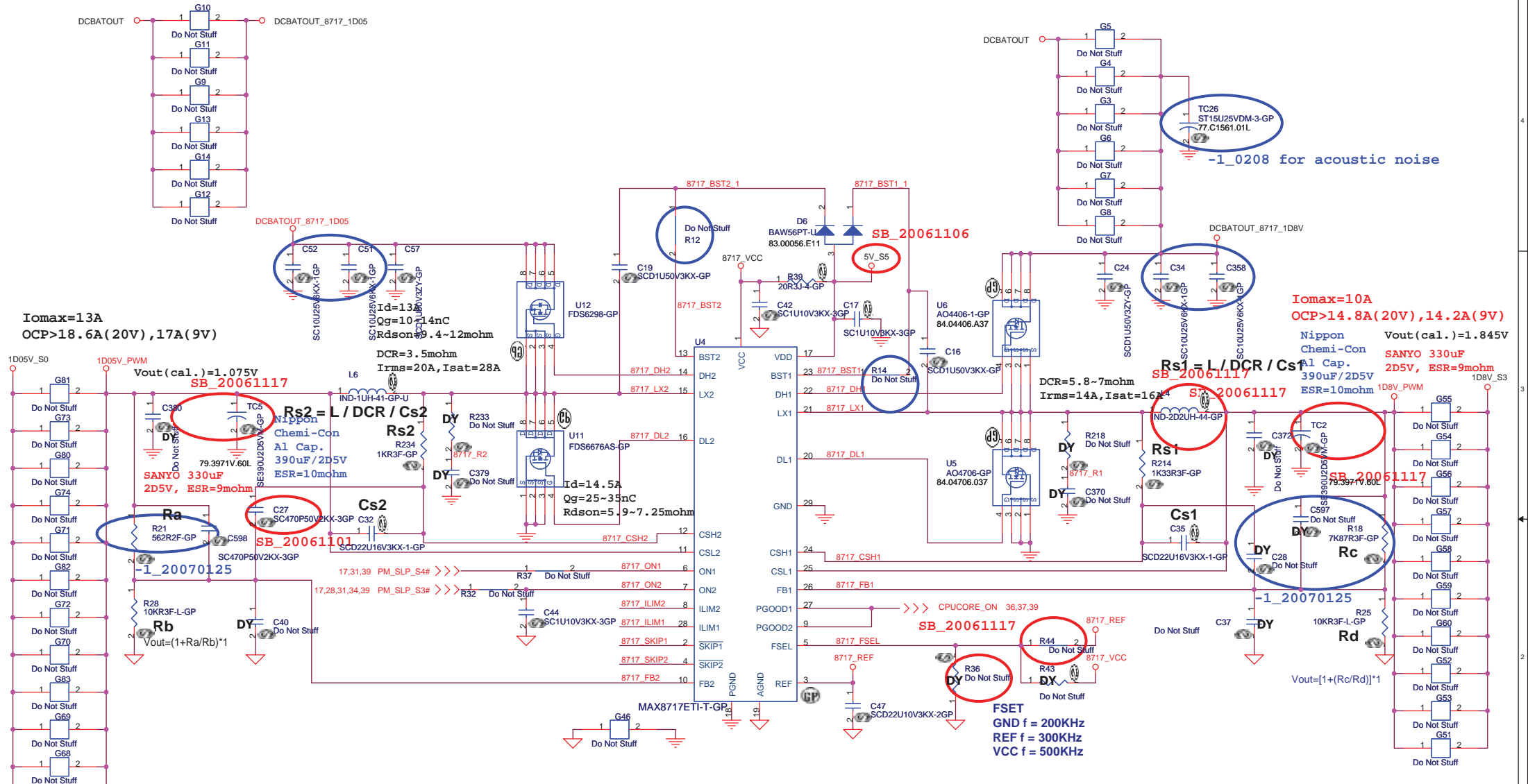
**SB\_20061206**  
 R565 Do Not Stuff  
 R566 Do Not Stuff  
 R567 Do Not Stuff  
 R568 Do Not Stuff  
 R569 Do Not Stuff  
 R570 Do Not Stuff  
 R571 Do Not Stuff  
 R572 Do Not Stuff  
 R573 Do Not Stuff  
 R574 Do Not Stuff  
 R575 Do Not Stuff  
 R576 Do Not Stuff  
 R577 Do Not Stuff  
 R578 Do Not Stuff  
 R579 Do Not Stuff  
 R580 Do Not Stuff  
 R581 Do Not Stuff  
 R582 Do Not Stuff  
 R583 Do Not Stuff  
 R584 Do Not Stuff  
 R585 Do Not Stuff  
 R586 Do Not Stuff  
 R587 Do Not Stuff  
 R588 Do Not Stuff  
 R589 Do Not Stuff  
 R590 Do Not Stuff

**-1\_20070111**  
 R371 226KR3F-GP  
 R372 Do Not Stuff  
 R373 Do Not Stuff  
 R374 Do Not Stuff  
 R375 Do Not Stuff  
 R376 Do Not Stuff  
 R377 Do Not Stuff  
 R378 Do Not Stuff  
 R379 Do Not Stuff  
 R380 Do Not Stuff  
 R381 Do Not Stuff  
 R382 Do Not Stuff  
 R383 Do Not Stuff  
 R384 Do Not Stuff  
 R385 Do Not Stuff  
 R386 Do Not Stuff  
 R387 Do Not Stuff  
 R388 Do Not Stuff  
 R389 Do Not Stuff  
 R390 Do Not Stuff

**SB\_20061120**  
 R335 232KR3F-GP  
 R336 3V/5V\_POK  
 R337 6236 UGATE1  
 R338 6236 PHASE2  
 U29 AO4468-GP 84.04468.037  
**I<sub>omax</sub>=5A**  
**OCP>8.88A (20V), 8.48A (9V)**  
 DCR=5.8~7mohm  
 L17 I<sub>rms</sub>=14A, I<sub>sat</sub>=16A  
 IND-2D2UH-44-GP  
 R563 DR2J-2-GP  
 R564 Do Not Stuff  
 R565 Do Not Stuff  
 R566 Do Not Stuff  
 R567 Do Not Stuff  
 R568 Do Not Stuff  
 R569 Do Not Stuff  
 R570 Do Not Stuff  
 R571 Do Not Stuff  
 R572 Do Not Stuff  
 R573 Do Not Stuff  
 R574 Do Not Stuff  
 R575 Do Not Stuff  
 R576 Do Not Stuff  
 R577 Do Not Stuff  
 R578 Do Not Stuff  
 R579 Do Not Stuff  
 R580 Do Not Stuff  
 R581 Do Not Stuff  
 R582 Do Not Stuff  
 R583 Do Not Stuff  
 R584 Do Not Stuff  
 R585 Do Not Stuff  
 R586 Do Not Stuff  
 R587 Do Not Stuff  
 R588 Do Not Stuff  
 R589 Do Not Stuff  
 R590 Do Not Stuff

**SB\_20061206**  
 R563 220uF 6D3V, V Size  
 ESR=25mohm  
 Kemet 220uF 6D3V, V Size ESR=25mohm  
 Nippon Chemi-Con Al Cap. 6D3V, F61 ESR=10mohm.  
**Maximum current:5A**  
 If LIR=0.35  
 $\Delta I = 5 \times 0.35 = 1.75A$   
 $V_{in} = 20V; F_{sw} = 500K$   
 $L > 2.2\mu H$

**OCP: 5x2=10A**  
 $I_{ocp} = 10 - (1.75/2) = 9.125A$   
 $V_{th} = 9.125A * 24m\Omega = 219mV$   
 $R(I_{lim}) = (219mV * 10) / 5uA$   
 $\approx 438K \rightarrow 442K$

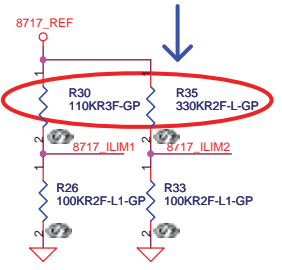


**I<sub>omax</sub>=13A**  
**OCP>18.6A (20V), 17A (9V)**

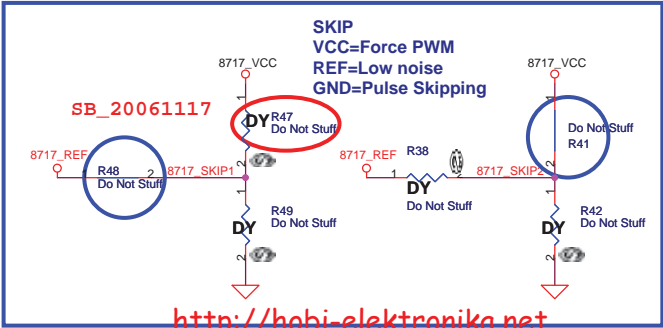
**I<sub>omax</sub>=10A**  
**OCP>14.8A (20V), 14.2A (9V)**  
**Nippon Chemi-Con**  
**SANYO 330uF**  
**Al Cap. 2D5V, ESR=9mohm**  
**V<sub>out</sub> (cal.)=1.845V**  
**1D8V\_PWM**  
**ESR=1.0mohm**

V<sub>out</sub> (cal.)=1.075V  
**S<sub>B\_20061117</sub>**  
R<sub>s2</sub> = L / DCR / C<sub>s2</sub>  
R<sub>s1</sub> = L / DCR / C<sub>s1</sub>  
V<sub>out</sub> = (1+R<sub>a</sub>/R<sub>b</sub>)\*1  
V<sub>out</sub> = (1+(R<sub>c</sub>/R<sub>d</sub>))\*1  
R<sub>a</sub>: 562R2F-GP  
R<sub>b</sub>: 10KR3F-L-GP  
R<sub>c</sub>: 7K87R3F-GP  
R<sub>d</sub>: 10KR3F-L-GP  
DCR=3.5mohm  
I<sub>rms</sub>=20A, I<sub>sat</sub>=28A  
Id=13A  
Qg=10~14nC  
R<sub>dson</sub>=9.4~12mohm  
Id=14.5A  
Qg=25~35nC  
R<sub>dson</sub>=5.9~7.25mohm  
DCR=5.8~7mohm  
I<sub>rms</sub>=14A, I<sub>sat</sub>=16A  
FSET GND f = 200KHz  
REF f = 300KHz  
VCC f = 500KHz  
SKIP VCC=Force PWM  
REF=Low noise  
GND=Pulse Skipping  
Adjust the current limit threshold from R30, R35  
VILIM = 0.5V~2.0V  
Output Current = ILIM / 10 / LDCR - di/2

**S<sub>B\_20061120</sub>**



VILIM = 0.5V~2.0V  
Output Current = ILIM / 10 / LDCR - di/2



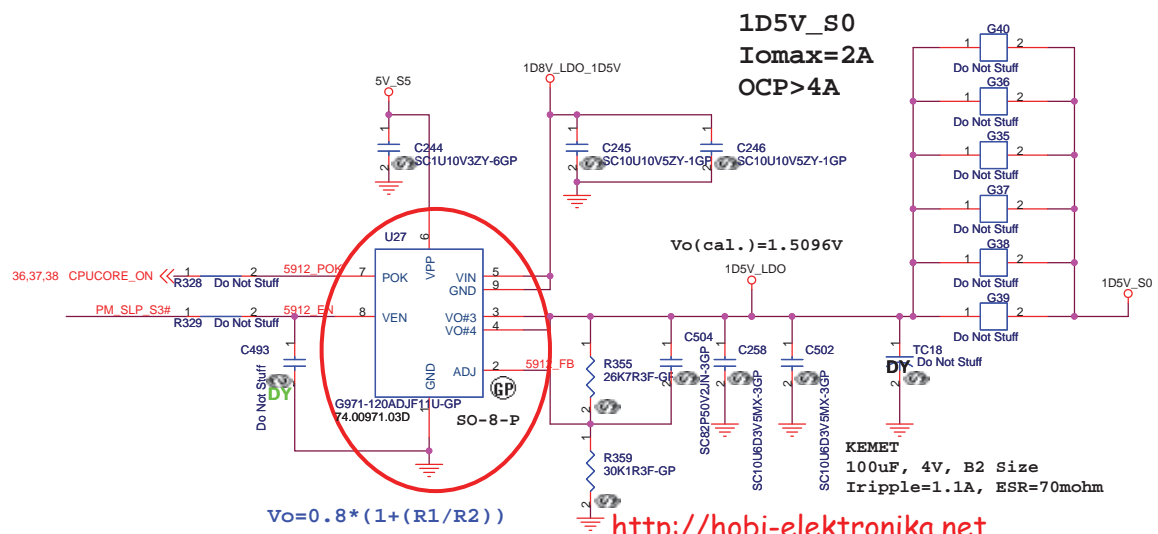
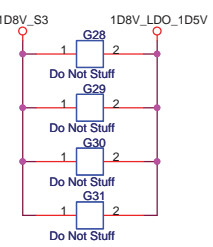
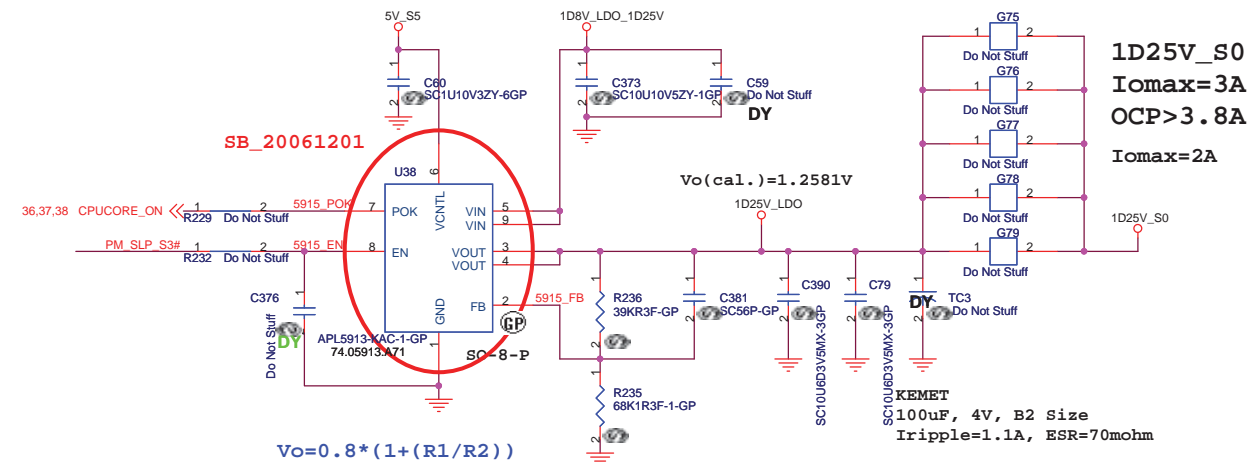
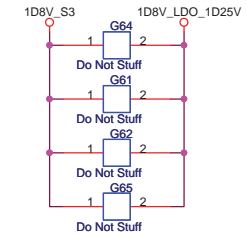
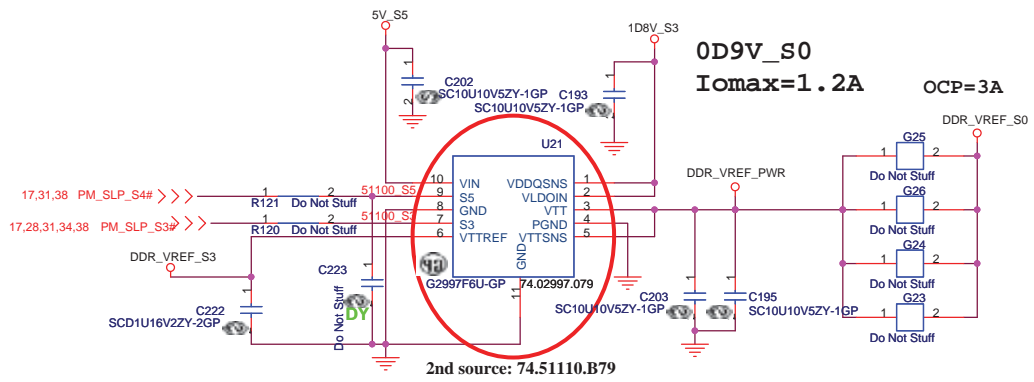
<http://hobi-elektronika.net>

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**緯創資通**  
**Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title <b>MAX8717_1D8V_1D05V</b>	
Size A3	Document Number <b>Biwa</b>
Date Thursday, March 01, 2007	Rev <b>-2</b>

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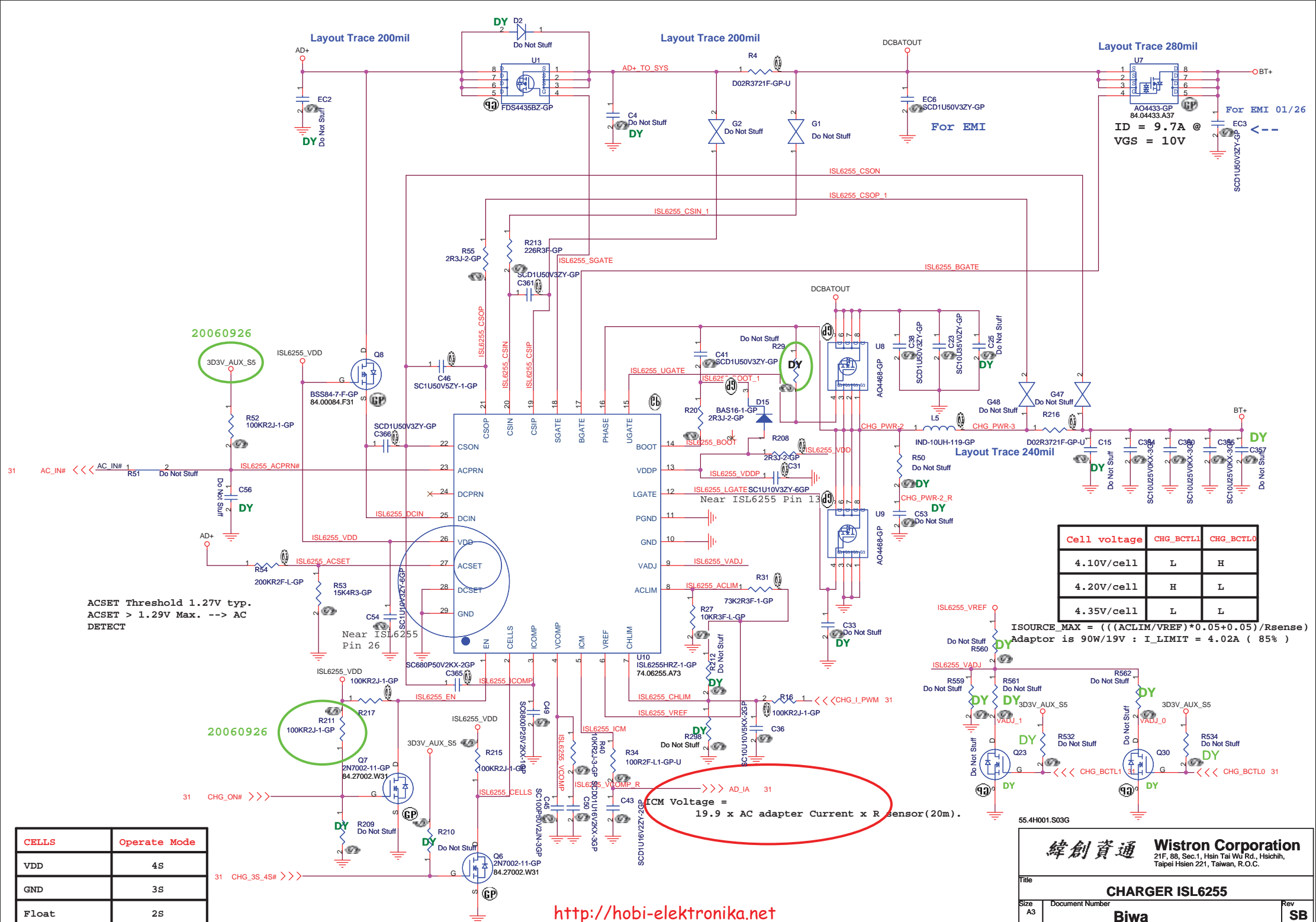
**緯創資通 Wistron Corporation**  
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **1D25V/1D5V/0D9V**

Size: A3    Document Number: **Biwa**    Rev: **SB**

Date: Thursday, March 01, 2007    Sheet 39 of 42





Layout Trace 200mil

Layout Trace 200mil

Layout Trace 280mil

Layout Trace 240mil

20060926

20060926

ACSET Threshold 1.27V typ.  
ACSET > 1.29V Max. --- AC  
DETECT

ICM Voltage =  
19.9 x AC adapter Current x R sensor (20m).

Cell voltage	CHG_BCTL1	CHG_BCTL0
4.10V/cell	L	H
4.20V/cell	H	L
4.35V/cell	L	L

ISOURCE\_MAX = ((ACLIM/VREF)\*0.05+0.05)/Rsense  
Adaptor is 90W/19V : I\_LIMIT = 4.02A ( 85% )

CELLS	Operate Mode
VDD	4S
GND	3S
Float	2S

<http://hobi-elektronika.net>

55.4H001.S03G

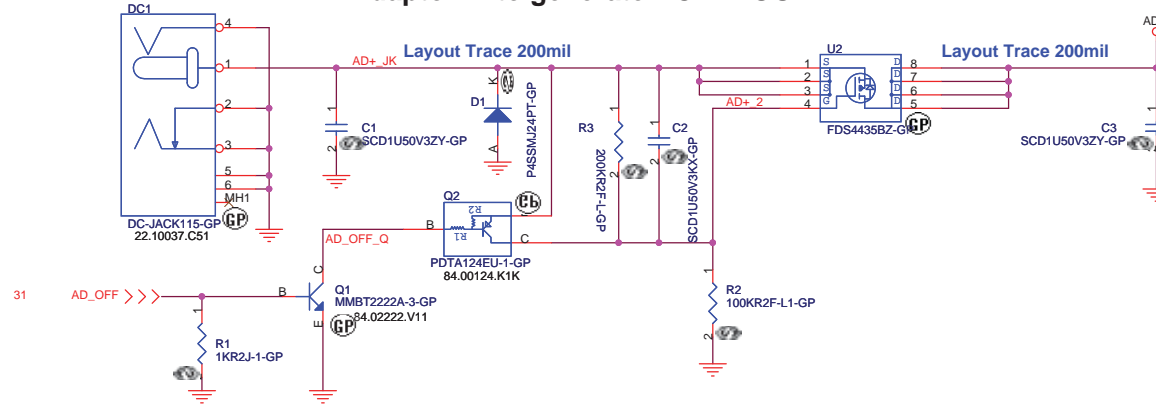
**緯創資通** **Wistron Corporation**  
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
Taipei Hsien 221, Taiwan, R.O.C.

Title: **CHARGER ISL6255**

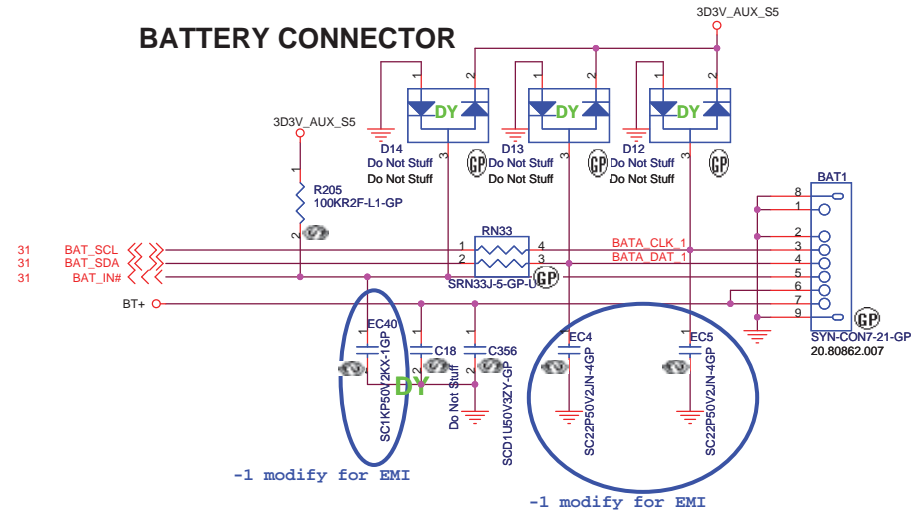
Size A3	Document Number	Rev
	<b>Biwa</b>	<b>SB</b>

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### Adaptor in to generate DCBATOUT



### BATTERY CONNECTOR



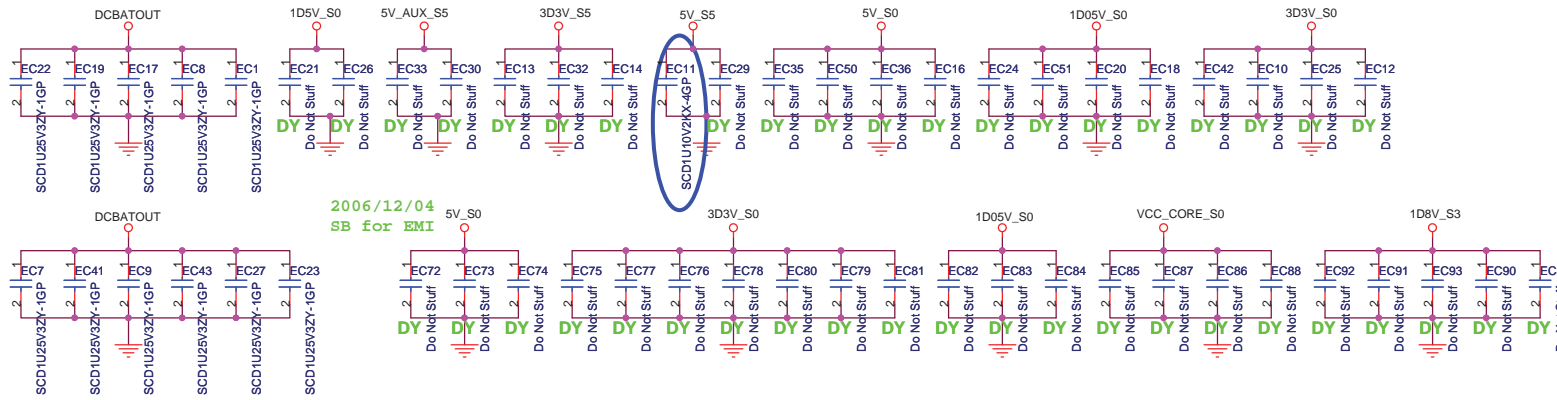
<http://hobi-elektronika.net>

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,  
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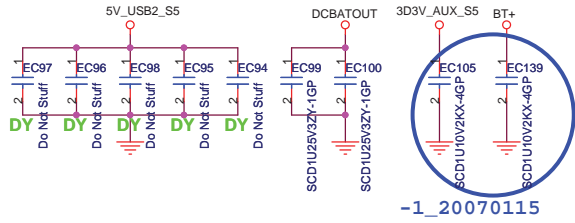
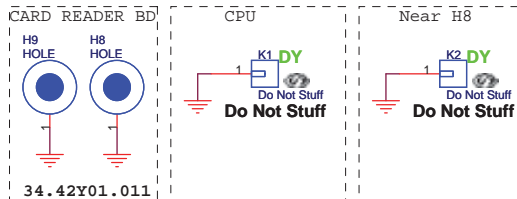
Title <b>AD/BATT CONN</b>		
Size A3	Document Number <b>Biwa</b>	Rev <b>-1</b>
Date: Thursday, March 01, 2007	Sheet 41 of 42	

# EMI Capacitor

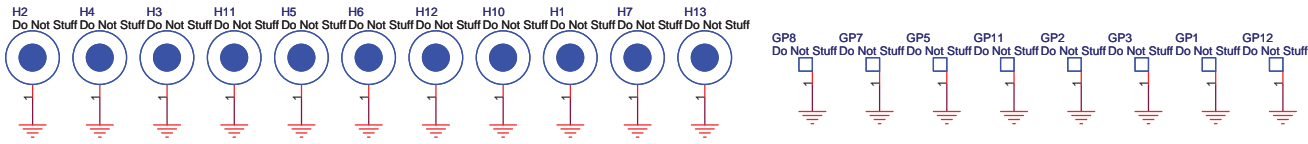
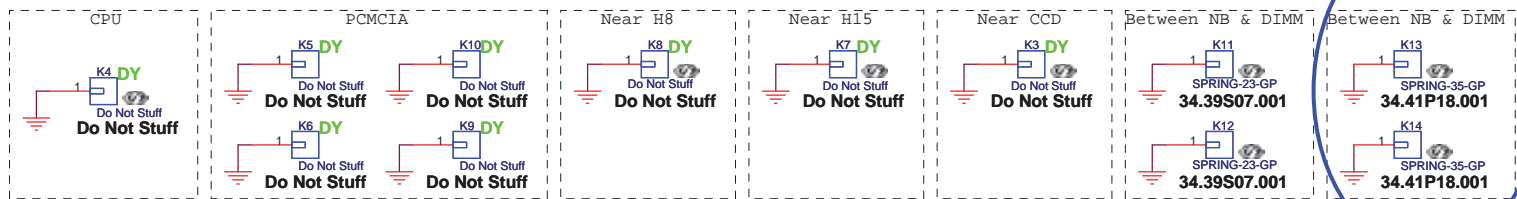
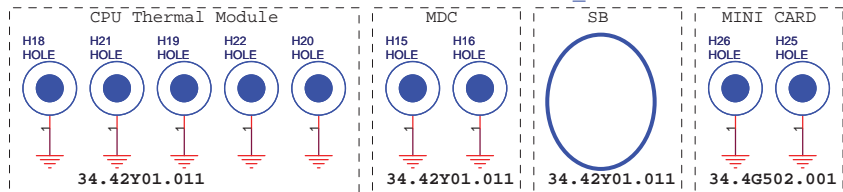


2006/12/04  
SB for EMI

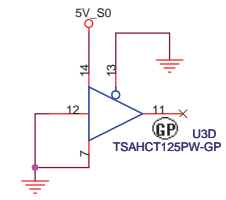
TOP



BOTTOM



# Unused gate



# KBC JTAG Test Pad

- 31.32 KCOL1 <<< KCOL1 TP88 Do Not Stuff
- 31.32 KCOL2 <<< KCOL2 TP91 Do Not Stuff
- 31.32 KCOL3 <<< KCOL3 TP92 Do Not Stuff
- 31.32 KCOL4 <<< KCOL4 TP90 Do Not Stuff
- 31.32 KCOL6 <<< KCOL6 TP89 Do Not Stuff
- 31.32 KCOL7 <<< KCOL7 TP93 Do Not Stuff

# DFX Test Point

- 3D3V\_AUX\_S5 TP97 Do Not Stuff
- 3D3V\_S5 TP102 Do Not Stuff
- 5V\_S5 TP100 Do Not Stuff
- 4,16,34 H\_PWRGD TP31 Do Not Stuff
- 28,31,34 S5\_ENABLE TP86 Do Not Stuff
- 4,6 H\_CPUREST# TP39 Do Not Stuff

Test Point放在Dimm Door打開可量測處

55.4H001.S03G

		<b>Wistron Corporation</b> 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title: <b>EMI/Spring/Boss</b>		
Size: Document Number	Rev: <b>-1</b>	
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